ENQUIRY DOCUMENT - TENDER

(Document No : C098-TENDER_DOC-C098-000-81-41-CD-T-8105)

इंजीनियर्स इंडिया लिमिटेड
(भारत सरकार का उपक्रम)
ENGINEERS INDIA LIMITED
(A Govt. of India Undertaking)

हर एक काम देश के नाम

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ENGINEERS INDIA LIMITED

(A GOVT. OF INDIA UNDERTAKING)

(BIDDING DOCUMENT NO.: JP/C098-000-CD-T-8105/1004)
(DOMESTIC COMPETITIVE BIDDING)

BIDDING DOCUMENT

FOR

BALANCE WORKS FOR CONSTRUCTION OF BOUNDARY WALL AROUND THE SHRI RAM MANDIR COMPLEX IN AYODHYA

Prepared & Issued by:

इंजीनियर्स इंडिया लिमिटेड
(भारत सरकार का उपक्रम)

ENGINEERS INDIA LIMITED
(A Govt. of India Undertaking)

MASTER INDEX

NAME OF WORK : BALANCE WORKS FOR CONSTRUCTION OF BOUNDARY WALL AROUND THE SHRI RAM MANDIR COMPLEX IN AYODHYA

BIDDING DOCUMENT NO. : JP/C098-000-CD-T-8105/1004

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इंजीनियर्स इंडिया लिमिटेड (भारत सरकार का उपक्रम) ENGINEERS INDIA LIMITED (A Govt. of India Undertaking)

DOMESTIC NOTICE FOR INVITATION FOR BID(IFB)
FOR
BALANCE WORKS FOR CONSTRUCTION OF BOUNDARY WALL AROUND THE SHRI RAM MANDIR COMPLEX IN AYODHYA
BIDDING DOCUMENT No.: JP/C098-000-CD-T-8105/1004
(DOMESTIC COMPETITIVE BIDDING)

1.0 INTRODUCTION

Engineers India Ltd. (EIL), a Government of India, Public Sector Undertaking is a premier consultancy organization having registered office at 1, Bhikaiji Cama Place, R.K. Puram, New Delhi – 110066.

EIL has been appointed as the Executing Agency by the client for the construction of the boundary wall around the Shri Ram Mandir Complex.

The boundary wall work is presently under progress and this tender is being floated for execution of the balance works associated with the construction of the boundary wall, including allied and related works as specified in the tender documents.

For this purpose, EIL invites e-bids (Through CPP Portal https://eprocure.gov.in/eprocure/app) for the above work under single stage Three-Part System (Part-I: Earnest Money Deposit (EMD)/ Bid Security, Part-II: Techno-commercial / Un-Priced Bid & Part-III: Price Bid) from competent agencies with sound technical and financial capabilities meeting the Bidder's Qualification Criteria (BQC) as stated under para 4.0 below.

2.0 BRIEF SCOPE OF WORK

The overall scope of work in general shall include construction & execution of Civil & Structural works including Piling, Sub-structure & Super-structure works for RCC Boundary wall, Watch Towers and any other associated works at Shri Ram Janmabhoomi Complex Ayodhya as per the broad & detailed scope of work, scope of Material Supply, Schedule of Rates, tender specifications, drawings, codes, standards, good engineering practice and directions of Engineer- in- Charge etc. all complete.

For other details, refer Bid Document.

3.0 TIME SCHEDULE:

4 months from the date of issue of Letter for Acceptance (LOA)

4.0 BIDDER'S QUALIFICATION CRITERIA:

Bidder shall fulfil the following qualification criteria in order to qualify for the subject work:

4.1 EXPERIENCE CRITERIA (TECHNICAL)

Bidder shall fulfil the qualification criteria as mentioned in clause 4.1.1 below:

4.1.1. Value of completed contract of similar work during the preceding 07 (seven) years to be reckoned from last day of the month previous to the month in which the enquiry was issued, should be as under.

4.1.1.1 Three similar completed works each costing not less than **Rs. 3.00 crore**, or
4.1.1.2 Two similar completed works each costing not less than **Rs. 4.00 crore**, or
4.1.1.3 One similar completed work costing not less than **Rs. 5.00 crore.**

"Similar work (s)" as mentioned shall mean successful execution of Civil-Structural work(s) including RCC work & Structural steel work."

4.1.2. GENERAL PROVISION W.R.T. EXPERIENCE CRITERIA (TECHNICAL)

4.1.2.1. **Bidder's past experience as Consortium/ JV:**

Bidder's past experience as a leader or member of a Consortium/JV shall be considered acceptable, provided his scope in that Consortium/JV meets the requirement stipulated in the subject BQC under evaluation.

In case, the PTR (Past track record) of Consortium/JV experience submitted by the Bidder meets the similar work without indicating the division of scope of work in terms of specific activities and associated value of work between the Consortium/JV members, but only the division of scope in terms of percentage share is indicated, in such case the completed value shall be arrived at after considering percentage share of each member, for the purpose of BQC evaluation.

4.1.2.2. **Experience from Own Projects:**

Experience of only the Bidding entity shall be considered. A job executed by a Bidder for its own plant/projects shall not be considered as experience for the purpose of meeting the Qualification Criteria of the bidding document.

However, Jobs executed for Subsidiary/ Fellow subsidiary / Holding company shall be considered as experience for the purpose of meeting BQC, subject to submission of additional document towards "tax paid invoice(s) duly certified by Statutory Auditor of the Bidder or consolidated statement issued by Statutory Auditor of the Bidder towards payments of statutory tax" in support of the job executed for Subsidiary/ Fellow subsidiary / Holding company.

In case referred Project falls under "No Tax Area" (like SEZ), Bidder can submit certificate from their Statutory Auditor to this effect in place of Tax paid invoice.

Chartered Accounted (CA) (in place of Statutory Auditor) is acceptable where audited accounts are not mandatory as per law for latest financial year. Also, CA shall not be an employee/ Director and not having any interest in the Bidder's company/Firm.

4.1.2.3. In case, two separate Bidders submit reference of same work (wherein one was Main Contractor and the other was Sub-Contractor) for meeting Bidder Qualification Criteria, both Bidders' experience shall be considered for qualification subject to Bidder's meeting other qualification requirements.

4.1.2.4. In case a Bidder submits PTR having job awarded for multiple Parts in single Work Order having separate completion schedule for each Part, and the Bidder wants to get qualified based on the completion of One or more Parts (irrespective of whether all Parts under the same work order are completed or not), which meets the subject BQC value-wise and with respect to Similar Work, the same may be considered subject to the completion certificate with executed value of that/those Part(s) from the Owner/End User/PMC for that/those Part(s).

However, where multiple-Parts work is awarded under different Work Order(s) having different Work Order reference number(s) with the same Enquiry Document No., cumulative value of such completed Work Orders meeting definition of Similar Work, as submitted, shall be considered for the purpose of BQC Evaluation.

4.1.2.5. **METHODOLOGY FOR EVALUATION OF EPC (ENGINEERING, PROCUREMENT & CONSTRUCTION) /LSTK (LUMP SUM TURNKEY) WORK EXPERIENCE IN ITEM RATE TENDERS**:

a)For experience based on EPC/LSTK works: In case bidder has executed EPC/LSTK/ multidisciplinary works which includes the Qualifying work(s) as per the definition of "Similar work", then the value of such qualifying work(s) out of the total value of EPC/LSTK/multidisciplinary works shall be considered for the purpose of evaluation.

b) **Documentation to be submitted by bidder in case of experience based on EPCL/LSTK works**: In the event the qualifying requirement of similar works cannot be ascertained from the work order /completion certificate submitted by bidder, Copy of relevant pages of Contract or Copy of relevant pages of final bill certified by Owner/Consultant or letter from their Owner/Consultant specifying the executed value(s) of similar work can be submitted for qualification to establish the value of similar work.

However if the above document could not establish the value of similar work, Billing Schedule/ Billing Break–up approved by Owner/Consultant can also be considered for establishing the value of similar work.

4.1.2.6. In case the Bidder has executed composite work which includes the qualifying work(s) as per the above definition of ''similar work'', then the value of such qualifying works(s) out of the total value of Composite Work shall be considered for the purpose of qualification.

4.1.2.7. The annual inflation in the value of contract executed by the Bidder under the past experience shall not be considered.

4.1.2.8. The executed Contract Price as per the Completion Certificate shall be considered for meeting value based Experience Criteria of BQC.

However, if the completion certificate also indicates details of taxes & duties, then these values of taxes and duties shall be excluded for evaluation.

4.1.2.9. All the documents submitted by the bidder, as above shall be submitted duly authenticated as per the authentication requirements of Bidding Document.

4.1.2.10. Bidder to note that the originals of the documents submitted in support of BQC shall be verified after award of work. Hence, bidder should submit the documents having their original in their possession.

4.1.2.11. EIL reserves the right to complete the evaluation based on the details furnished without seeking any additional information.

4.2 FINANCIAL CRITERIA :

4.2.1 Annual Turnover:

The Average Annual Financial Turnover of the Bidder during the last three financial years shall be at least **INR 2,99,62,000/- (Indian Rupees Two Crore Ninety Nine Lakhs Sixty Two Thousand Only)**. Annual Turnover shall be verified from the audited financial statement of the company.

Average Turnover shall be determined by summing up the annual turnover of each financial year and dividing the sum by three. In the event a bidder does not have turnover in any one or two of the years of the submitted financial years, the turnover for that/those years shall be taken as Nil and the average turnover will be calculated by considering the denominator as 3 years – to determine the conformity to the turnover criteria.

4.2.2 Net-Worth:

The Net worth of the bidder as per the latest Audited Financial Statement shall be **positive.**

Indian Central Public Sector Undertakings / Enterprises shall be exempted from the requirement of Net Worth.

4.2.3 Working Capital (WC):

The Working Capital of the Bidder as per the latest Audited Financial Statement shall be minimum **INR 99,87,000/- (Indian Rupees Ninety Nine Lakhs Eighty Seven Thousand Only).** In case bidder is unable to meet the WC requirement as above, the bidder can supplement the WC with a fund based line of credit from any Scheduled Bank in India or a commercial bank having Net Worth more than equivalent INR 100 Crore. In such a case, bidder shall furnish a declaration from the bank (dated any date between the tender floatation and bid due date) for availability of unutilized fund based line of credit for the shortfall in WC of above mentioned value, in the format enclosed as **Annexure-A** to IFB, along with the bid.

The letter shall provide the status of Fund based Line of Credit as on any date between the date of Enquiry and Bid Due Date. In case of non-submission of required letter from bank in the Bid, The bidder shall not be given another opportunity to submit the letter even if techno-commercial clarifications are being sought from the Bidders and this may become a cause of disqualification.

Currency for the amount of line of credit from the bank shall be in the currency as per the IFB/BDS.

[Example: If the WC required is Rs. 50 Crore and the Bidder has WC of Rs. 30 Crore as per the Audited Financial Statement, Bidder needs to submit a LOC for the balance Rs. 20 Crore.

Further, if the Working Capital required is Rs. 50 Crore and the Bidder has WC of (-) Rs. 10 Crore as per the Audited Financial Statement, Bidder needs to submit LOC for Rs. 60 Crore to meet the BQC requirement].After opening of bids, in case the bidder is not meeting the required working capital amount even from the line of credit certificate submitted along with the bid, no further opportunity shall be given to bidder to modify or replace the certificate by any subsequent certificate from the same bank or any other bank.

However, if the bank certificate submitted in the bid is carrying certain inaccuracies in the language of the certificate as per the format enclosed in the tender, bidder shall be asked to clarify or make corrections in the language of the bank letter. In case of such clarifications/corrections, the same shall be submitted as an amendment to the line of credit from the bank submitted in the bid. In no case alterations in the amount of line of Credit as already submitted in the bid shall be allowed.

If any bidder is not meeting the working capital requirement as per its audited Financial Statement and also has not submitted the required line of credit certificate from bank in the bid, the bidder shall be rejected and no opportunity to submit the certificate shall be provided to bidder.

Bidder shall be required to upload the copy of line of credit certificate along with the bid on the e-tendering portal itself, duly signed by a digital signature. The bidders shall not be required to submit the original of the line of credit certificate to EIL separately.

Line of Credit certificate issued by the bank and submitted in the bid shall be verified from the issuing bank's branch.

The declaration letter for the shortfall of working capital shall be from a single bank only. Letter from multiple banks will not be acceptable. However, banking syndicate shall be allowed wherein a group of banks can jointly underwrite and jointly lend money to the bidder. In case of Banking syndicate also, declaration letter for meeting working capital shall be from a single bank only, on behalf of banking syndicate.
In case the bidder submits letters from multiple banks, the highest working capital amongst all the bank shall only be considered for BQC evaluation.

4.2.4 The financial statements (as per clause No. 4.3.2.1) shall be reviewed in respect of financial criteria stated herein above. However, in case any matter is referred in the notes to accounts and schedules referred in balance sheet and profit & loss account then, only quantified qualified/ adverse/ disclaimer opinion in the statutory auditor's reports, if any, having impact on financial criteria shall be considered for evaluation.

4.2.5 CALCULATION OF TURNOVER, NET WORTH AND WORKING CAPITAL

i The definition of Turnover shall be as follows:

Turnover shall be calculated excluding GST & other Incomes.

ii The networth shall be calculated as per following: -

The networth means paid up share capital, Share application money pending allotment* and reserves# less accumulated losses and deferred expenditure to the extent not written off. Networth shall be calculated using the following formula:

Reserves to be considered for the purpose of net worth shall be all reserves created out of the profits and securities premium account but shall not include reserves created out of revaluation of assets, write back of depreciation and amalgamation.

*Share application money pending allotment will be considered only in respect of share to be allotted.

Description		Values <in Currency>

Paid up share capital (A)	:	XXXXX
Add: Share application money pending allotment (B)	:	XXXXX
Add: Reserves (as defined above) (C)	:	XXXXX
Less: Accumulated Losses (D)	:	XXXXX
Less: Deferred Revenue Expenditure to the extent not written off (E)	:	XXXXX
Net Worth (A+B+C-D-E)	:	**XXXXX**

iii Working Capital calculation: Working Capital shall be Current Assets minus Current Liabilities.

Where Current asset means asset when it satisfies any of the following criteria:—

(a) it is expected to be realised in, or is intended for sale or consumption in, the company's normal operating cycle*;

(b) it is held primarily for the purpose of being traded;

(c) it is expected to be realised within twelve months after the reporting date; or

(d) it is cash or cash equivalent unless it is restricted from being exchanged or used to settle a liability for at least twelve months after the reporting date.

Where Current Liabilities means liabilities when it satisfies any of the following criteria:—

(a) it is expected to be settled in the company's normal operating cycle*;

(b) it is held primarily for the purpose of being traded;

(c) it is due to be settled within twelve months after the reporting date; or

(d) the company does not have an unconditional right to defer settlement of the liability for at least twelve months after the reporting date. Terms of a liability that could, at the option of the counterparty, result in its settlement by the issue of equity instruments do not affect its classification.

*An operating cycle is the time between the acquisition of assets for processing and their realization in cash or cash equivalents. Where the normal operating cycle cannot be identified, it is assumed to have a duration of twelve months.

Bidders (Other than companies such as Partnership/Proprietorship firms) are required to submit Annexure-C to IFB with the following details duly certified from their Auditor/Chartered accountant.

S.no. **(1)**	Particulars **(2)**	Total Value as per Balance Sheet (INR) **(3)**	Amount **(out of column no. 3) Receivable/ Due within 12 months from balance sheet date** or as per above definition of current assets and current liabilities **(4)**
A	Current Assets as per Balance sheet		……
B	Assets (**Excluding Fixed Assets**) **which are not specifically disclosed as current assets** in the Balance sheet.		
	a. Loans and Advances	……	……
	b. Investments (Including Fixed Deposits)	……	……
	c. Other asset **(Excluding Fixed Assets)** which are not classified as current assets	……	……
		Total Current Assets	**…… (X)**
C	Current Liabilities as per Balance sheet		……
D	Liabilities **which are not specifically disclosed as current liabilities** in the Balance sheet.		
	a. Bank Overdraft / Bank CC limit etc.*		……
	b. Secured Loans	……	……
	c. Unsecured Loans	……	……
	d. Provisions	……	……
	e. Other Liabilities which are not classified as current Liabilities.	……	……
		Total Current Liabilities	**…… (Y)**
	Working Capital **(X-Y)**		……

*Bank Overdraft/ Bank CC limit shall be treated as current liabilities only and accordingly same shall be filled in column 4 only.

4.3. DOCUMENTS TO BE SUBMITTED BY BIDDER IN SUPPORT OF BQC:

4.3.1 DOCUMENTS TO BE SUBMITTED BY BIDDER IN SUPPORT OF EXPERIENCE CRITERIA (TECHNICAL)

4.3.1.1 The bidder shall, in his own interest, furnish complete documentary evidence to establish that the bidder meets the Qualification criteria as given above.

4.3.1.2 Bidder shall complete and submit the **Experience Record Performa** (along with supporting documents mentioned) provided in the Bidding Document to establish that the bidder meets the Bidder Qualification Criteria. Projects/ works filled in Experience Record Performa shall only be evaluated. Documents etc. of other projects/ jobs mentioned elsewhere other than this experience record Performa shall not be considered and evaluated.

4.3.1.3 In support of meeting the requirements of above-mentioned clauses, Bidder shall furnish following

4.3.1.3.1 Copy of work order or purchase order or letter of intent or contract agreement issued by Owner/PMC to the Bidder indicating Owner/PMC, Contractor, Job or project name, date of award, and scope of work.

4.3.1.3.2 Copy of completion certificate issued by Owner/PMC to the Bidder indicating completion of work, completion date, actual executed value.

4.3.1.3.3 A job completed by a Bidder as Sub-Contractor shall be considered for the purpose of meeting the experience criteria of BQC, provided the appointment of Sub Contractor was authorized and subject to submission of following documents in support of meeting the "Bidder's Qualification Criteria":

(a) Documentary evidence/ Certificate by End-user/Owner/PMC, with regards to approval of bidder/ engaging Bidder/ execution by the Bidder as a Sub Contractor to the Main Contractor.

(b) Work order and Completion Certificates indicating the value of works and the date of completion issued by Main Contractor

4.3.1.3.4 If work order/ completion certificate does not indicate all the requirements of qualification criteria then Bidder should either submit a certificate to this effect from the Owner/PMC or final Running account (RA) Bill (certified/ verified by Owner/PMC) indicating work done and executed value. As built construction drawings certified by Owner/PMC may be considered to evaluate work done by the Bidder.

Note: For requirement of approval of sub-contractor, clause no. 4.3.1.3.3 shall be applicable.

4.3.2 **DOCUMENTS TO BE SUBMITTED BY BIDDER IN SUPPORT OF FINANCIAL CRITERIA**

4.3.2.1 Bidder shall submit any of the following:

Copy of Complete Audited Financial Statement (which includes 'Balance Sheet' and 'Profit & Loss Account' along with all schedules, Notes referred therein and the Auditor's report), in support of meeting the financial criteria as mentioned above.

OR

A letter from the Statutory Auditor/ Chartered Accountant (CA) (*) (in the format enclosed as Annexure – B1 to IFB).

OR

A letter from the bidder duly certified by Statutory Auditor/ CA (*) (in the format enclosed as Annexure – B2 to IFB).

(*) Letter from CA (not being an employee/Director and not having any interest in the bidder's company) in place of Statutory Auditor is acceptable where audited accounts are not mandatory as per law at the time of preparation of financial statement for a particular financial year.

The above financial details, as per **Annexure-B1** to IFB or **Annexure-B2** to IFB, shall be submitted **without any reservation/qualification remarks**. In case of any qualification remarks, Complete Audited Financial Statement, as above, shall also be submitted with the bid.

4.3.2.2 Bidder to evidence meeting of financial criteria shall submit complete audited financial statements as above for the preceding three financial years, in line with one of the following: -

a) In case the last financial year's closing date was within 9 months prior to bid due date and Complete Audited Financial Statement (which includes 'Balance Sheet' and 'Profit & Loss Account' along with all schedules, Notes referred therein and the Auditor's report) of last financial year are not available, Bidder has the option to submit the financial details of the three previous years immediately prior to the last financial year.

b) Otherwise, it is compulsory to submit the financial details of the immediate preceding three financial years.

For example, In case, bid due date is up to 31st December and Financial details of immediate preceding financial year (year ending 31st March of the same year) are not available, the financial details of the three previous years immediately prior to the last financial year may be submitted.

4.3.2.3 In case bidder is a Parent/ Holding Company, where only consolidated Audited Financial Statement are prepared and audited which includes the financial details of their wholly owned subsidiaries, etc., consolidated audited Financial Statement shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the bidder certifying that standalone Financial Statements of bidder (without the financial data of subsidiaries, etc.) is not separately prepared and audited as per the law of land prevailing in bidder's country.

Further, in case bidder is a subsidiary company and separate Financial Statement of the bidder is not prepared & audited, but only a consolidated audited Financial Statement of their Parent / Holding Company is available, consolidated audited Financial Statement shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the parent company certifying that separate Financial Statement of bidder is not prepared and audited as per the law of land prevailing in bidder's country.

4.3.2.4 For meeting the Financial criteria, bidders shall be required to submit the Audited Annual Reports/ Financial Statements of the company as per the provision of bidding document, audited and issued till the final bid due date. Bidder shall be evaluated based on the Financial Statements of the company submitted in the bid.

Any shortfall information / document on Audited Annual Reports/ Financial Statements of the Company, audited and issued on or before the bid due date can be asked through CQ, but bidder shall not be allowed to submit the Financial Statements of the Company audited & issued post final bid due date & time. Accordingly, Financial Statements of the Company audited and issued post final bid due date & time shall not be considered for evaluation.

4.3.2.5 The Institute of Chartered Accountant of India at its 379th council meeting dated 17-18th December, 2018 made generation of Unique Document Identification Number (UDIN) mandatory for every signature of full time practicing chartered accountant in phased manner for the following service:

a) All certificates with effect from 1st February, 2019.

b) GST and Income Tax Audit with effect from 1st April, 2019.

c) All audit and Assurance Functions with effect from 1st July, 2019.

In view of the above, bidder shall ensure that any certificate/ reports issued/ attested by a practicing chartered accountant in India and submitted in the bid shall mandatorily include the UDIN number. Certificate/ reports issued/ attested without UDIN number of practicing chartered accountant in India shall not be considered for evaluation.

This requirement of including UDIN shall not be applicable for certificate/ reports issued/ attested by a chartered accountant practicing in foreign country.

4.4 AUTHENTICATION & VERIFICATION OF DOCUMENTS

4.4.1 It is bidder's prime responsibility to submit genuine and authentic documents. No amount of checking or verification by the buyer shall absolve bidder from his responsibility.

Under the EIL suspension / banning rules (available on EIL portal *www.engineersindia.com*), the punishment for such an action is clearly mentioned. Moreover, other actions against the bidder like encashment of EMD or PBG depending upon the stage of discovery of the fraud / false documentation may be taken up by EIL. Moreover, the bidder's organization is responsible for any and all actions of their employees and any claims seeking to pin point the blame on some employee of bidder and attempting to absolve the bidder's organization will not be entertained.

The bidder must also note that the EIL reserves the right to proceed based on acceptable offer (who have submitted authenticated documents in line with the Clause No. 4.4.2 below) and reject outright the other bids which have some shortcomings including non-submission of authenticated documents. The bidder shall therefore submit the authenticated documents along with the offer itself and in case of rejection of his bid shall not have any right to seek another opportunity for submission of authenticated documents.

4.4.2 **Bidder shall furnish an undertaking in the format as per ANNEXURE-I to IFB towards the authenticity of submitted BQC Documents, duly signed by the authorized signatory of Bidder holding Power of Attorney for signing of Bid**.

Proprietorship/Partnership firms shall submit the undertaking as per ANNEXURE-I to IFB, duly signed by the Proprietor/any two Partners.

4.4.3 Bidders shall be required to upload the digitally signed authenticated copies of documents for meeting BQC (including the documents against MSE if any) on the e-tendering portal only. In addition to authentication, verification of the documents submitted towards meeting the BQC by the techno-commercially acceptable bidders shall be done. Documents shall be verified from the document issuing authority.

This may be carried out by EIL through e-mail / letter or visit. Bidder shall provide complete assistance towards the same. It shall be responsibility of the bidder to assist EIL in carrying out this exercise. Accordingly, bidder shall ensure that bidder shall submit those executed works

meeting the qualification criteria for which they can arrange such verification from their respective clients.

Payment to the Bidder shall be released only on completion of verification. Failure of cross verification shall entitle EIL/Client to reject the bid or terminate the PO / Contract, if issued.

In case the BQC documents have already been verified by EIL for any other enquiry/ tender, the same may also be considered verified on the strength of previous verification and accepted by EIL. However, in such a case, bidder shall indicate in their bid that PTR documents submitted in this bid has already been already verified by EIL from Bidder's Client in tender no. _____ for the project _____.

In case bidder's supporting documents are not in English language and, bidder also submits duly certified translated documents, verification from document issuing authority shall be carried out only for the original documents.

5.0 THE SALIENT FEATURES OF THE BIDDING DOCUMENT:

a)	Bid Security / Earnest Money Deposit	:	**INR 19,97,500/-** Bid Security to be submitted in favour of "Engineers India Limited" in line with provisions of Clause 19.0 of Instructions to Bidders (ITB). **In case the bidder fails to submit the Bid Security (if submitted through BG/DD/FDR/Insurance Surety Bond) in original physical form within the final bid due date & time, his bid shall be rejected, irrespective of their status/ ranking in tender and notwithstanding the fact that a copy of the same is uploaded by the bidder.**
b)	Bidding Document available on Web-site	:	From **9th May 2026 to 1200 Hrs (IST) on 19th May 2026**
c)	Last Date and time of submission of Bids	:	**Up to 1200 Hrs (IST) on 19th May 2026**
d)	Pre-bid meeting*	:	**Through Online as per link below on 13th May 2026 at 14:00 Hrs (IST)** **https://teams.microsoft.com/meet/48524607378793?p=7AxCAwzvJ1vnea50Fz** **Join the meeting now** Meeting ID: 485 246 073 787 93 Passcode: Uq7td9hQ
e)	Last date for pre-bid queries	:	**Up to 12th May 2026**
f)	Opening of Techno-commercial (Unpriced) Bids*	:	1400 Hrs (IST) on **20th May 2026**
g)	Cost of Bidding Document (Non-Refundable)	:	Not applicable
h)	Opening of Priced Bids	:	The date & time to be intimated later
i)	Site Location for Site	:	Refer Instructions to Bidders

	Visit		
j)	Place of Submission of EMD	:	Dak Receipt Section, Engineers India Limited Sector-16 (On N.H.-8) Tower-2 (Ground Floor), Gurugram -122 001, Haryana (India) Tel No. +91-124- 2891360/1364/1362 **Kind. Attn.: Mr Jaydip Purkayastha – GM (SCM)**

* If dates identified as (*) above happen to be a declared holiday/closed day in EIL Gurugram, then activity shall be conducted on next working day.

5.1. The detailed IFB along with Complete bidding document can be viewed/ downloaded from the website: https://eprocure.gov.in/eprocure/app till the Bid Due Date & Time. However, Information about the location of the Bidding Document shall also be available on and EIL website https://tenders.eil.co.in. e-Bids are required to be submitted through Government of India's Central Public Procurement portal https://eprocure.gov.in/eprocure/app only, on or before the Bid-Submission Date & Time. In order to perform e-procurement activities, the bidders are required to enroll/ register themselves at https://eprocure.gov.in/eprocure/app. No enrollment/registration fee would be charged from the bidders for the same.

5.2. Bidding Document along with IFB, time extension (if any), amendments etc. to the IFB/bidding document shall be uploaded on https://eprocure.gov.in/eprocure/app portal only. Bidders should regularly visit the website to keep themselves updated.

5.3. No Manual Bids/Offers shall be permitted. The offers submitted through the designated e-tendering system shall only be considered for evaluation & ordering. Bids submitted in physical form or sent in any other form such as through E-Mail /CD/DVD/Pen Drive etc. shall not be accepted. Physical / Fax / e-mail Bids (other than the documents specifically required to be submitted in hard form) shall not be accepted.

5.4. Bidders to please refer to the Annexure – I to Instructions to Bidders of Bidding Document regarding e-tendering guidelines.

6 AWARD METHODOLOGY:

The contract shall be awarded to the qualified and techno-commercially acceptable bidder who is Lowest (L-1) in price subject to PPP-MII order 2017(preference to Make in India).

7 REVERSE AUCTION

Not Applicable

8 GENERAL

8.1 In case Contract awarded for a previous tendered work has to be terminated on account of Contractor and a separate enquiry / tender has been refloated to get the remaining/ complete work executed, such defaulting Contractor will not be considered for the refloated enquiry / tender.

8.2 Failure to meet the above Qualifying Criteria at Clauses 4.0 above will render the bid to be summarily rejected

8.3 Bidder should not be in Suspension/ Banning/ Debarment List of EIL.

8.4 Bidder shall submit confirmation in the bid that they are not on suspension/banning list or black listed or debarred by EIL/ Client on due date of submission of bid. If a Bidder is on suspension/banning/debarment list of EIL/Client on due date of submission of bids/during the process of evaluation of bids, the offer of such bidder shall not be considered for bid opening/evaluation/award.

8.5 Bidder to inform the status of being suspension/banning list or black listed by any other Central Government Department/ Central public sector on due date of submission of bid. In case, this information is not provided, the bid shall be rejected.

8.6 Unincorporated Joint Venture bids/Consortium Bids/Bids from Wholly Owned Subsidiary relying on Parent company's experience shall not be accepted.

8.7 Bidder shall not be under liquidation, court receivership or similar proceedings.

8.8 Bidders shall furnish all qualification details along with relevant supporting documents in the first

instance itself as EIL may finalise the qualification based on details submitted without asking for any additional details. In view of this, bidder, in their own interest, must submit experience details for as many Jobs as possible that, in his opinion, meet the Bidder Qualification Criteria (BQC).

8.9 Bidders are required to submit all such past experience(s) (PTR) meeting the BQC along with relevant supporting documents in the first instance itself, alongwith the bid. Accordingly, only such past experience(s) shall be considered for qualification, details of which are provided as per the specified format by the bidder (or documents such as work-order / completion certificate etc.) of which are enclosed with the bid by the bidder and subsequently no additional past experience (PTR) shall be sought from the bidder.

In case, a Bidder does not meet the BQC based on experience documents submitted by Bidder in support of meeting the BQC, bid shall be rejected. However, in case CQs / TQs are issued to the Bidder, Bidders may be allowed to submit additional documents for any of the work out of the past experience(s) (PTR) list already submitted along with the bid, to support their meeting the BQC.

No additional past experience(s) (PTR) shall be considered from the bidders, since this would amount to substantive change in the bid.

8.10 EIL reserve the right to evaluate the Bids using in-house information. Further, if the Bidder cites any reference of a job executed for Owner / some other Owner through EIL and the Bidder is not able to furnish documentary evidence, Owner/EIL may consider the internal records of Owner or EIL (as the case may be).

8.11 Any direct email communication from Bidder's Owner / PMC (from their domain server) [of whom Bidder has submitted the past experience] to EIL shall be acceptable for establishing work experience. The same shall be considered as an authentic document.

8.12 Only Class-I local suppliers and Class-II local suppliers as defined in the policy for Public Procurement (Preference to Make in India) (PPP-MII) order, 2017, attached as Annexure-IV to ITB are eligible to quote.

8.13 Bidder shall submit the Integrity Pact (as per Form-K of Bidding Forms) duly filled in, signed & stamped by the authorized signatory of the bidder on all pages. In case of non-submission of Integrity Pact in the bid, an opportunity shall be given in the CQ to submit the IP, provided bidder has declared integrity pact submission confirmation in Checklist (Form-F of Bidding Forms) in the original bid. The bidder in addition to submitting Integrity Pact shall also be required to specifically confirm that "Bidder is not involved in any case of transgression in terms of Integrity Pact" by submitting signed & stamped copy of "Undertaking w.r.t. Section-V of Integrity Pact" attached with Form-K of Bidding Form. Non-submission of the IP & Undertaking shall lead to rejection of the offer.

8.14 Bidder shall refer the Annexure "Tender Clause on Procurement from Bidders from a Country(ies) sharing land border with India". Accordingly, Bidders shall submit a certificate of compliance in the enclosed Form - I A / Form - I B / Form-II, as applicable in Annexure-V of ITB, otherwise offer of the bidder shall be rejected.

8.15 Bidder shall refer the Annexure "Domestically (Indian) Manufactured Iron & Steel Products in Government Procurement (DMI&SP)". Accordingly, Bidders shall submit applicable Forms enclosed in Annexure-VI of ITB, otherwise offer of the bidder shall be rejected.

8.16 All documents to be submitted by the bidder for meeting the Bidder Qualification Criteria shall be furnished in a folder titled as "Documentation against Bidder Qualification Criteria (Technical & Commercial)" with proper index.

8.17 All amendments, clarifications, corrigendum on time extension etc. will be uploaded on website http://eprocure.gov.in/eprocure/app only. Bidders should regularly visit the website to keep themselves updated. No extension in the bid due date / time shall be considered on account of delay in receipt of any document by mail.

8.18 EIL shall not be responsible for any expenses incurred by bidders in connection with the preparation & delivery of their bids, site visit and other expenses incurred during bidding process

8.19 EIL reserves the right to reject any or all Bids without assigning any reason, whatsoever.

8.20 Based on documents submitted by Bidder(s) in the unpriced bid if a suspicion of cartel formation is observed, bid(s) will not be considered for evaluation/placement of order. Such bidder will also be debarred from bidding in future and EMD shall be forfeited.

8.21 For detailed specifications, terms and conditions and other details, refer to the Bidding Document.

8.22 **Physical / Fax / e-mail Bids (other than the documents specifically required to be submitted in hard form)** shall not be accepted.

8.23 Please acknowledge receipt of Bidding Document and immediately confirm your participation in the subject bidding as per proforma (ACKNOWLEDGEMENT CUM CONSENT LETTER) enclosed in the Bidding Document.

8.24 EIL reserves the right to carry out capacity & capability assessment of the bidder using in-house information and past performance.

8.25 Clarification, if any, can be obtained from GM (SCM), Engineers India Limited, R&D Complex, Sector-16 (On N.H.-8),Tower-1 (1st Floor), Gurugram-122 001,Haryana (India), Tel No. +91-124-289 1360/1362/1287/1361 e-mail id: jaydip@eil.co.in /vibhor.saxena@eil.co.in/neeraj@eil.co.in/ bhupendra@eil.co.in

8.26 **Engineers India Ltd including its officers and representatives, shall under no circumstances solicit or request any payment, monetary consideration from bidders other than those specifically stipulated in the published tender/enquiry document and its amendments (if any).**

Bidders are cautioned that, should they receive any phone calls, messages, emails, or personal approaches requesting payments other than specified in tender document, such communications are fraudulent and do not originate from Engineers India Ltd.

Engineers India Ltd. shall not be responsible for any financial loss, penalty, or damage caused due to actions taken by Bidders/ contractors on the basis of such communications.

GENERAL MANAGER (SCM)
ENGINEERS INDIA LIMITED, GURUGRAM

Annexure-I to IFB

SELF-CERTIFICATION FOR ALL BQC DOCUMENTS (INCLUDING MSE DOCUMENTS]

RFQ/Bidding Document No.:
Item/Work:

I, _____ S/o/D/o of _____, working as _____ *{authorised signatory of Bidder holding Power of Attorney for signing of Bid or proprietor / any two partners in case of Proprietorship / Partnership firms (indicate, as applicable)}* of the Company/ Firm _____ having its registered office at _____ certify that all the details including documents pertaining to Bidder Qualification Criteria signed by undersigned vide our offer reference _____ against your Enquiry document _____, are true, authentic, genuine and exact copy of its original.

It is certified that none of the documents are false/forged or fabricated. All the documents has been submitted with full knowledge of (i) the provisions of the Indian laws in respect of offences including, but not limited to those pertaining to criminal breach of trust, cheating and fraud (ii) provisions of bidding conditions and iii) Suspension / Banning rules of Owner/ EIL, which entitle the Owner/EIL to initiate action in the event of such declaration turning out to be a misrepresentation or false representation.

It is further certified that, if any documents are required to be submitted by our company/ Firm subsequent to submission of bid, shall also be submitted under my knowledge and shall be true, authentic, genuine, exact copy of its original and shall not be false/forged or fabricated.

I hereby acknowledge that the Owner/EIL possesses the right to verify the BQC Documents from the relevant document issuing authority or end user. The result of this verification, as stated above, shall be binding upon our Company/Firm, without any opportunity for dissent or contestation.

I also accept that in case, at a later date, any of the document submitted in our bid referred above is found to be false/forged or fabricated, I, shall be held responsible for the same and EIL/Owner has every right to take action against me and my company, as deemed fit as per law of land and provisions of the Bidding Documents and EIL/Owner's right to put our company on Suspension / Banning list for future business with EIL/Owner.

Specimen Signature of authorized signatory of Bid

Signature
Name & Designation (*proprietor in case of Proprietorship /any two partners in case of Partnership firms (indicate, as applicable)*)

Annexure-A to IFB

(To be declared by the Bank on their Letter Head)

DECLARATION FOR AVAILABILITY OF UNUTILIZED LINE OF CREDIT

Ref:_____ Date: _____

We _____<Insert Name of Bank>, a Bank, having its registered office at _____<Insert full address of the Bank with Country Name> and Branch at _____ <Insert full of Branch address with Country Name, in case different from registered office >, hereby confirm that the Company M/s _____<Insert Company Name in favour of whom Declaration being issued>, having its registered office at _____<Insert full address of Company with Country Name> and their working Office address at _____ <Insert full working office address with Country Name, in case different from registered office >, is having Bank account with our Bank.

The credit limits of the Company as on _____ **<Insert any Date between the date of Enquiry and Bid Due Date>**are as follows:

Fund Based Line of Credit (towards Working Capital like CC Limit)	**Amount in (Currency_____)**
Sanctioned Line of Credit	
Utilized Line of Credit	
Balance Line of Credit	

The Bank further hereby declare [Bank to specify as applicable]:

(a) that we are a Scheduled Bank in India; OR

(b) that we are a Commercial Bank having Net Worth more than **INR 1000 Million** (or equivalent USD) as per our latest audited financial statements.

Yours Faithfully,

Signature
Name:
Designation:
E-mail ID:
Mobile number:
Tel (with STD Code):

Seal:

Annexure-B1 (Letter from Statutory Auditor/CA)

(To be printed on Letter Head of Statutory Auditor/CA)

FINANCIAL DETAILS

We, _____, a CA firm having our registered office address _____ and certificate number _____ certify that we are statutory auditor of the Company M/s _____, having its registered office at _____.

OR

We, _____, a CA firm having our registered office address _____ and certificate number _____ certify that statutory audit is not mandatory for the M/s _____, having its registered office at _____ as per prevailing law and we are practicing Chartered Accountant, not being an employee / Director and not having any interest in the company.

Financial details of the above-mentioned Company, as per latest available audited balance sheet are as follows: Statutory Auditor/Chartered Accountant to select either of the following options and strike off the other.

a. In case bidder is a parent company, i.e., having its subsidiaries: Auditor to select either of the following options and strike off the other.
   i. Financial details are of parent company without the financial data of subsidiaries
   ii. Financial details are of parent company including the financial data of subsidiaries. It is certified that separate annual report of bidder, without the financial data of subsidiaries, is not prepared and audited.

   OR

b. In case bidder is a subsidiary company: Auditor to select either of the following options and strike off the other.
   i. Financial details are of subsidiary company
   ii. Financial details are of parent company including the financial data of subsidiaries. It is certified that separate annual report of bidder, i.e., subsidiary, is not prepared and audited.

   OR

c. In case bidder does not have any subsidiary or parent company, financial details are of the company itself.

S.No.	Description	Year	Value Currency (_____)
1.	Turnover	Latest financial year (_____)	
		Preceding 1st year (_____)	

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		Preceding 2nd year (_____)	
2.	Net Worth	Latest financial year (_____)	(*)
3.	Working Capital	Latest financial year (_____)	

(*) – Indicate Positive or Negative (Value is not Mandatory)

Note:

1. In case the financial year closing date is within 9 months of bid due date and audited annual report of immediately preceding financial year is not available, bidder has the option to submit the financial details of the three previous years immediately prior to the last financial year. Otherwise, it is compulsory to submit the financial details of the immediate three preceding financial years.

   Example, In case, audited annual report of immediate preceding financial year (year ending 31st March) is not available and where bid closing date is up to 31ST December, the financial details of the three previous years immediately prior to the last financial year may be submitted. However, in case the bid closing date is after 31st December, it is compulsory to submit the financial details of the immediate three preceding financial years only.

2. In case of a bidder (a Parent Company) only consolidated Audited Financial Statements are prepared and audited which includes the financial details of their wholly owned subsidiaries, etc., consolidated audited Balance Sheet and Profit & Loss Account shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the bidder certifying that separate Financial Statements of bidder (without the financial data of subsidiaries, etc.) is not prepared and audited.

3. Further, in case a bidder is a subsidiary company and separate Financial Statements of the bidder is not prepared & audited, but only a consolidated audited Financial Statements of the Parent Company is available, consolidated audited Balance Sheet and Profit & Loss Account shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the parent company certifying that separate Financial Statements of bidder are not prepared and audited.

4. **Net Worth calculation:** Net Worth means paid up share capital, Share Application Money pending allotment* and reserves# less accumulated losses and deferred expenditure to the extent not written off. Net Worth has been calculated using the following formula, as per provisions of the enquiry document:

   # Reserves to be considered for the purpose of Net Worth shall be all reserves created out of the profits and securities premium account but shall not include reserves created out of revaluation of assets, write back of depreciation and amalgamation.

   *Share Application Money pending allotment will be considered only in respect of share to be allotted.

Paid up share capital	XXXXX
Add: Share Application Money pending allotment	XXXXX
Add: Reserves (As defined Above)	XXXXX
Less: Accumulated Losses	XXXXX
Less: Deferred Revenue Expenditure to the extent not written off	XXXXX
Net Worth	**XXXXX**

5. **Working Capital calculation:** Working Capital shall be Current Assets minus Current Liabilities,

Where Current asset means asset when it satisfies any of the following criteria:—

(a) it is expected to be realised in, or is intended for sale or consumption in, the company's normal operating cycle*;

(b) it is held primarily for the purpose of being traded;

(c) it is expected to be realised within twelve months after the reporting date; or

(d) it is cash or cash equivalent unless it is restricted from being exchanged or used to settle a liability for at least twelve months after the reporting date.

Where Current Liabilities means liabilities when it satisfies any of the following criteria:—

(a) it is expected to be settled in the company's normal operating cycle*;

(b) it is held primarily for the purpose of being traded;

(c) it is due to be settled within twelve months after the reporting date; or

(d) the company does not have an unconditional right to defer settlement of the liability for at least twelve months after the reporting date. Terms of a liability that could, at the option of the counterparty, result in its settlement by the issue of equity instruments do not affect its classification.

*An operating cycle is the time between the acquisition of assets for processing and their realization in cash or cash equivalents. Where the normal operating cycle cannot be identified, it is assumed to have a duration of twelve months.

Bidders (Other than companies such as Partnership/Proprietorship firms) are required to submit the following details from their Statutory Auditor/Chartered accountant.

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S.no. **(1)**	Particulars **(2)**	Total Value as per Balance Sheet (INR) **(3)**	Amount **(out of column no. 3) Receivable/ Due within 12 months from balance sheet date** or as per above definition of current assets and current liabilities **(4)**
A	Current Assets as per Balance sheet		.....
B	Assets (**Excluding Fixed Assets**) **which are not specifically disclosed as current assets** in the Balance sheet.		
	a. Loans and Advances	.....	.....
	b. Investments (Including Fixed Deposits)	.....	.....
	c. Other asset **(Excluding Fixed Assets)** which are not classified as current assets	.....	.....
		Total Current Assets	**..... (X)**
C	Current Liabilities as per Balance sheet		.....
D	Liabilities **which are not specifically disclosed as current liabilities** in the Balance sheet.		
	a. Bank Overdraft / Bank CC limit etc.*		.....
	b. Secured Loans	.....	.....
	c. Unsecured Loans	.....	.....
	d. Provisions	.....	.....
	e. Other Liabilities which are not classified as current Liabilities.	.....	.....
		Total Current Liabilities	**..... (Y)**
	Working Capital **(X-Y)**		.....

*Bank Overdraft/ Bank CC limit shall be treated as current liabilities only and accordingly same shall be filled in column 4 only.

6. **Turnover:** Turnover shall be calculated excluding GST & other Incomes.

7. In view of above definition of Net Worth i.e. exclusion of certain reserves which shall not form part of Net Worth, EIL reserve the right to seek the clarifications from bidder duly signed by their statutory auditor regarding the origin/creation of various reserves shown in the Balance Sheet

8. Net Worth, Working Capital and Turnover has been calculated using the abovementioned formulae and after giving effect to the Impact of quantified qualified / adverse / disclaimer Auditor's opinion (if any) given in the Statutory Auditor's Report of the Bidder.

Signature with date
Name:
Designation:
UDIN [Applicable for CA in India]
Seal

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Annexure-B2 (Certification by Statutory Auditor/Chartered Accountant)

(To be printed on Letter Head of Company)

FINANCIAL DETAILS

We, M/s _____, having our registered office at _____ certify that M/s _____ is a CA firm having their registered office address _____ having certificate number _____ are our statutory auditor.

OR

We, M/s _____, having our registered office at _____ certify that statutory audit is not mandatory for the company as per prevailing law and M/s _____ , a CA firm having their registered office address _____ having certificate number _____are practicing Chartered Accountant, not being an employee/Director and not having any interest in our company.

Financial details of our Company, as per latest available audited balance sheet are as follows: Company to select either of the following options and strike off the other.

a. In case bidder is a parent company, i.e., having its wholly owned subsidiaries: Company to select either of the following options and strike off the other:
   i. Financial details are of parent company without the financial data of subsidiaries
   ii. Financial details are of parent company including the financial data of subsidiaries. It is certified that separate annual report of bidder, without the financial data of subsidiaries, is not prepared and audited.

OR

b. In case bidder is a subsidiary company: Auditor to select either of the following options and strike off the other.
   i. Financial details are of subsidiary company
   ii. Financial details are of parent company including the financial data of subsidiaries. It is certified that separate annual report of bidder, i.e., subsidiary, is not prepared and audited.

OR

c. In case bidder does not have any subsidiary or parent company, Financial details are of the company itself.

S.No.	Description	Year	Value Currency (_____)
1.	Turnover	Latest financial year (_____)	
		Preceding 1st year (_____)	
		Preceding 2nd year (_____)	
2.	Net Worth	Latest financial year (_____)	(*)
3.	Working Capital	Latest financial year (_____)	

(*) – Indicate Positive or Negative (Value is not Mandatory)

Note:

1. In case the last financial year closing date is within 9 months of bid due date and audited annual report of immediate preceding financial year is not available, bidder has the option to submit the financial details of the three previous years immediately prior to the last financial year. Otherwise, it is compulsory to submit the financial details of the immediate three preceding financial years.

   Example, In case, audited annual report of immediate preceding financial year (year ending 31st March) is not available and where bid closing date is up to 31ST December, the financial details of the three previous years immediately prior to the last financial year may be submitted. However, in case the bid closing date is after 31st December, it is compulsory to submit the financial details of the immediate three preceding financial years only.

2. In case of a bidder (a Parent Company) only consolidated Audited Financial Statements are prepared and audited which includes the financial details of their wholly owned subsidiaries, etc., consolidated audited Balance Sheet and Profit & Loss Account shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the bidder certifying that separate Financial Statements of bidder (without the financial data of subsidiaries, etc.) is not prepared and audited.

3. Further, in case a bidder is a subsidiary company and separate Financial Statements of the bidder is not prepared & audited, but only a consolidated audited Financial Statements of the Parent Company is available, consolidated audited Balance Sheet and Profit & Loss Account shall be considered for establishing the financial criteria subject to statutory auditor/ CEO/ CFO of the parent company certifying that separate Financial Statements of bidder are not prepared and audited.

4. **Net Worth calculation:** Net Worth means paid up share capital, Share Application Money pending allotment* and reserves# less accumulated losses and deferred expenditure to the extent not written off. Net Worth has been calculated using the following formula, as per provisions of the enquiry document:

   # Reserves to be considered for the purpose of Net Worth shall be all reserves created out of the profits and securities premium account but shall not include reserves created out of revaluation of assets, write back of depreciation and amalgamation.

   *Share Application Money pending allotment will be considered only in respect of share to be allotted.

Paid up share capital	XXXXX
Add: Share Application Money pending allotment	XXXXX
Add: Reserves (As defined Above)	XXXXX
Less: Accumulated Losses	XXXXX
Less: Deferred Revenue Expenditure to the extent not written off	XXXXX
Net Worth	**XXXXX**

5. **Working Capital calculation:** Working Capital shall be Current Assets minus Current Liabilities.

   Where Current asset means asset when it satisfies any of the following criteria:—

   (a) it is expected to be realised in, or is intended for sale or consumption in, the company's normal operating cycle*;

   (b) it is held primarily for the purpose of being traded;

   (c) it is expected to be realised within twelve months after the reporting date; or

   (d) it is cash or cash equivalent unless it is restricted from being exchanged or used to settle a liability for at least twelve months after the reporting date.

Where Current Liabilities means liabilities when it satisfies any of the following criteria:—

(a) it is expected to be settled in the company's normal operating cycle*;

(b) it is held primarily for the purpose of being traded;

(c) it is due to be settled within twelve months after the reporting date; or

(d) the company does not have an unconditional right to defer settlement of the liability for at least twelve months after the reporting date. Terms of a liability that could, at the option of the counterparty, result in its settlement by the issue of equity instruments do not affect its classification.

*An operating cycle is the time between the acquisition of assets for processing and their realization in cash or cash equivalents. Where the normal operating cycle cannot be identified, it is assumed to have a duration of twelve months.

Bidders (Other than companies such as Partnership/Proprietorship firms) are required to submit the following details from their Statutory Auditor/Chartered accountant.

S.no. **(1)**	Particulars **(2)**	Total Value as per Balance Sheet (INR) **(3)**	Amount **(out of column no. 3) Receivable/ Due within 12 months from balance sheet date** or as per above definition of current assets and current liabilities **(4)**
A	Current Assets as per Balance sheet		.....
B	Assets (**Excluding Fixed Assets**) **which are not specifically disclosed as current assets** in the Balance sheet.		
	a. Loans and Advances	.....	.....
	b. Investments (Including Fixed Deposits)	.....	.....
	c. Other asset **(Excluding Fixed Assets)** which are not classified as current assets	.....	.....
		Total Current Assets	..... **(X)**
C	Current Liabilities as per Balance sheet		.....
D	Liabilities **which are not specifically disclosed as current liabilities** in the Balance sheet.		
	a. Bank Overdraft / Bank CC limit etc.*		.....
	b. Secured Loans	.....	.....
	c. Unsecured Loans	.....	.....
	d. Provisions	.....	.....
	e. Other Liabilities which are not classified as current Liabilities.	.....	.....
		Total Current Liabilities	..... **(Y)**
	Working Capital **(X-Y)**		.....

*Bank Overdraft/ Bank CC limit shall be treated as current liabilities only and accordingly same shall be filled in column 4 only.

6. **Turnover:** Turnover shall be calculated excluding GST & other Incomes.

7. In view of above definition of Net worth i.e. exclusion of certain reserves which shall not form part of Net worth, EIL reserve the right to seek the clarifications from bidder duly signed by their statutory auditor regarding the origin/creation of various reserves shown in the Balance Sheet.

8. Net Worth, Working Capital and Turnover has been calculated using the abovementioned formulae and after giving effect to the Impact of quantified qualified / adverse / disclaimer Auditor's opinion (if any) given in the Statutory Auditor's Report of the Bidder.

Signature with date

Sign and Stamp of Statutory auditor/ CA (on all pages)
Signature with date
Name & Designation:
UDIN [Applicable for CA in India]
Seal

Annexure-C to IFB

Bidders (Other than companies such as Partnership/Proprietorship firms) are required to submit the following details from their Auditor/Chartered accountant.

Name of Bidder:_____

S.no. **(1)**	Particulars **(2)**	Total Value as per Balance Sheet (INR) **(3)**	Amount **(out of column no. 3) Receivable/ Due within 12 months from balance sheet date** or as per above definition of current assets and current liabilities **(4)**
A	Current Assets as per Balance sheet		.....
B	Assets (**Excluding Fixed Assets**) **which are not specifically disclosed as current assets** in the Balance sheet.		
	a. Loans and Advances	.....	.....
	b. Investments (Including Fixed Deposits)	.....	.....
	c. Other asset **(Excluding Fixed Assets)** which are not classified as current assets	.....	.....
		Total Current Assets	**..... (X)**
C	Current Liabilities as per Balance sheet		.....
D	Liabilities **which are not specifically disclosed as current liabilities** in the Balance sheet.		
	a. Bank Overdraft / Bank CC limit etc.*		.....
	b. Secured Loans	.....	.....
	c. Unsecured Loans	.....	.....
	d. Provisions	.....	.....
	e. Other Liabilities which are not classified as current Liabilities.	.....	.....
		Total Current Liabilities	**..... (Y)**
	Working Capital **(X-Y)**		.....

*Bank Overdraft/ Bank CC limit shall be treated as current liabilities only and accordingly same shall be filled in column 4 only.

Signature with date
Name:
Designation:
UDIN [Applicable for CA in India]
E-mail ID:
Mobile number:
Tel (with STD Code):
Seal:

EXPERIENCE RECORD PRO-FORMA (ERP)

FORMAT FOR PAST EXPERIENCE OF BIDDER (For Clause No. 4.1 of IFB)

SL. NO.	WHETHER BIDDER/ SUB-CONTRACTOR IS QUOTING BASED ON THE JOBS EXECUTED FOR SUBSIDIARY/FELLOW SUBSIDIARY/HOLDING COMPANY YES/ NO	BIDDER'S PROVEN TRACK RECORD (PTR)						
		NAME OF THE PROJECT	CLIENT/OWNER	YEAR OF EXECUTION	DETAIL OF WORK ORDER/PO/ LOA/LOI.	COMPLETION CERTIFICATE. (MENTIONING REFERENCE NO. & ISSUE DATE)	DATE OF COMPLETION.	TOTAL COST OF PROJECT

PO: Purchase Order, LOA: Letter of Acceptance, LOI: Letter of Intent.

Notes:

1. This pro-forma shall be duly filled-in, stamped and signed by bidder and shall be submitted along with Bid.
2. Since the information requested in this pro-forma shall be utilized to assess the Bidder's capability to execute subject order, it would be in the interest of the Bidder to include only those references which are relevant to the works for meeting BQC.
3. The Bidder shall also ensure that all information asked for is furnished and the same is correct and complete in all respects. **Incorrect information furnished in this pro-forma shall render the bid/ order liable for rejection at any stage of evaluation/ work execution, at the risk and cost of the Bidder.**
4. Copy of listed documents shall be submitted along with the Bid as a documentary proof. Completion Certificate from Owner shall be furnished for the same PO/Work Order, which has been furnished by the bidder as PTR document.
5. Bidders need to submit all such past experience(s) (PTR) meeting the BQC along with relevant supporting documents in the first instance itself along with the bid. Only such past experience(s) shall be considered for qualification whose details are enclosed with bid. No subsequent additional past experience (PTR) shall be sought from the bidder for bidder qualification after submission of bid.
6. Whenever a contractor had worked as a sub-contractor to main contractor, their experience also can be considered. With regard to Sub-Contracted work order, in addition to documents as given in BQC, the bidder has to submit a Certificate/ approval letter from the End user / Owner / Consultant of the Owner stating that the Main Contractor has intimated them about the engagement of subcontracting or have been allowed/ permitted as a sub-contractor.

(STAMP & SIGNATURE OF BIDDER)

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PROFORMA FOR ACKNOWLEDGEMENT LETTER

E-MAIL: jaydip@eil.co.in / vibhor.saxena@eil.co.in / neeraj@eil.co.in/bhupendra@eil.co.in

(PLEASE E-MAIL TO EIL WITHIN THREE DAYS ON RECEIPT OF BIDDING DOCUMENT)

GM (SCM)
Tower I - First Floor
Engineers India Limited
Sector-16, Gurugram, Haryana

Kind Attention	**:**	**Mr. Jaydip Purkayastha**
Bidding Document No.	**:**	**JP/C098-000-CD-T-8105/1004**
Name of Work	**:**	**BALANCE WORKS FOR CONSTRUCTION OF BOUNDARY WALL AROUND THE SHRI RAM MANDIR COMPLEX IN AYODHYA**

Dear Sirs,

We acknowledge with thanks receipt of your above cited Bidding Document along with enclosures. We undertake that the contents of the above Bidding Document shall be kept confidential including all the drawings, specifications and documents and the said documents shall be used only for the purpose, for which they are intended.

Further, our response is as under:- (Bidders to put a tick √, as applicable).

1. We will submit the bid within due date. ☐
2. We regret to submit our offer/quote because of the following reasons: ☐
   a. _____
   b. _____

Thanking you,

Very truly yours,

Name of Bidder	**:**
Contact Person	**:**
Contact Person Mobile No	**:**
Bidder's Address	**:**
Bidder's Phone No.	**:**
Bidder's Fax No.	**:**
Bidder's E-mail	**:**

INSTRUCTIONS TO BIDDER

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A GENERAL

1.0 SCOPE OF BID

1.1 In connection with the Invitation for Bids, Engineers India Limited on behalf of Owner invites e-Bid(s), under single stage two bid system, for the entire scope covered under the Bidding Document (hereinafter for the purpose of these instructions collectively referred to as the "WORKS" as specified in Bid Data Sheet (BDS).

1.2 Throughout the Bidding Document:

(a) "EIL" means Engineers India Limited, a company incorporated under the Companies Act, 1956 having its registered office at 1, Bhikaiji Cama Place, R.K Puram, New Delhi-110066 (INDIA).

(b) "Client" / "Owner" means "Shri Ram Janmabhoomi Teerth Kshetra Trust" and shall include its successor and assigns. and shall include its successor and assigns.

(c) except where the context requires otherwise, words indicating the singular also include the plural and words indicating the plural also include the singular; and

(d) "day" means calendar day.

(e) "Effective date" means date of issuance of Fax of Acceptance/ Letter of Award of Work.

(f) The words "un-incorporated Joint Venture (JV)" and "Consortium "have the same meaning.

(g) "Instructions to Bidders" shall mean the documents describing the manner in which Bidder shall prepare and submit his bid.

(h) "Letter Inviting Bid" (LIB)/ "Invitation for Bid" (IFB) shall mean EIL's request to Bidder for a Bid/ Tender together with the Bidding Document.

(i) "Tender" or "Bid" shall mean Bidder's offer to perform the Work, in accordance with Bidding Document.

(j) "Tender Document" or "Bidding Document" shall mean the documents issued to the bidder including any subsequent addenda to enable bidder submit his Bid.

(k) "Bidder" or "Tenderer" shall mean the person or company who receives the Tender Document or Bidding Document and submits Tender or Bid to EIL.

(l) **"Contractor"** shall mean Individual, Agency, Firm or Company (whether incorporated or not) selected by the EIL for the performance of the Contract and shall include its legal representatives, successors and permitted assigns.

(m) For all purposes, bid due date shall be considered as bid due date specified in the tender, if there is no extension. However, in case of extension(s), bid due date shall be the final bid due date after all extensions.

(n) Throughout this Bidding Document, E-Tendering website means Government of India Central Public Procurement (CPP) Portal https://eprocure.gov.in/eprocure/app

2.0 CORRUPT AND FRAUDULENT PRACTICES

2.1 EIL requires that Bidders / contractor observe the highest standard of ethics during the award/ execution of Contract. "Fraudulent Practice" means a misrepresentation of facts in order to influence the award of a Contract to the detriment of the EIL, and includes collusive practice among bidders (prior to or after bid submission) designed to establish bid prices at artificial non-competitive levels and to deprive the EIL of the benefits of free and open competition.

2.2 The EIL will reject a proposal for award if it determines that the bidder recommended for award has engaged in fraudulent practices in competing for the Contract in question.

2.3 Bidder is required to furnish the complete and correct information/ documents required for evaluation of their bids. If the information/ documents forming basis of evaluation is found to be false/ forged, the same shall be considered adequate ground for rejection of bids and forfeiture of Bid Security.

2.4 In case, the information/ document furnished by the Bidder / Contractor forming basis of evaluation of his bid is found to be false/ forged after the award of the contract, EIL shall have full right to terminate the contract and get the remaining job executed at the risk & cost of such Bidder/ Contractor without any prejudice to other rights available to EIL under the contract such as forfeiture of CPBG/ Security Deposit, withholding of payment etc.

2.5 In case, this issue of submission of false documents comes to the notice after execution of work, EIL shall have full right to forfeit any amount due to the Bidder / Contractor along with forfeiture of CPBG/ Security Deposit furnished by the bidder/ contractor.

2.6 Further, such bidder / contractor shall be put on Suspension / Banning List of EIL / Owner debarring them from future business with EIL and /or Owner for a time period, as per the prevailing policy of Owner / EIL.

3.0 ELIGIBLE BIDDERS

3.1 A bidder may be a firm or a company, who, have been issued the Bidding Document on Limited Competitive Basis or a Bidder meeting the BQC criteria as per Invitation for Bids (IFB) on Open Competitive basis.

3.2 If a bidder is on suspension/banning/debarment list of EIL on due date of submission of bids/during the process of evaluation of the bids, the offer of such bidder shall not be considered for bid opening/ evaluation/award.

3.3 If a supplier / an agency is placed on suspension/ banning/ debarment list of EIL after issue of enquiry but before unpriced bid opening, their bid will not be opened. If a supplier / an agency is placed on suspension/ banning/ debarment after opening of unpriced bids but before opening of priced bids, further evaluation shall be stopped and the corresponding priced bid will not be opened.

3.4 In case of consortium, if any of member (s) of consortium is on suspension/banning/debarment list of EIL on due date of submission of bid/ during the process of evaluation of the bids, the offer of such a consortium shall not be considered for bid opening/evaluation/award. In case a joint venture/ consortium is debarred all partners will also stand debarred for the period specified in debarment order.

3.5 If a bidder is qualified based on engaging a sub-contractor/ sub-vendor who meets stipulated qualification criteria and such a sub-contractor is on suspension/banning/debarment list of EIL on due date of submission of bid / during the process of evaluation of the bids, the offer of such a bidder shall not be considered for bid opening/evaluation/Award.

3.6 If a supplier/ an agency is placed on suspension/ banning/ debarment list after opening of priced bids and such a supplier/ agency happens to be the lowest bidder, next lowest firm shall be considered as L-1. Bid security submitted by such debarred firms shall be returned to them.

3.7 Bidder should be not under Liquidation, Court receivership or similar proceedings. Bidder to submit self-declaration in this regard as per Bidding Form-J.

3.8 In case of limited competitive bidding, the bidding is open only to the bidders to whom Bidding Document has been issued.

3.9 If a bidder is from a country which shares a land border with India, then they will be eligible to bid if they are registered with the Competent Authority (Annexure-V to ITB), otherwise their offer shall not be considered for Opening/ evaluation/ award.

3.10 In case contract awarded for the tendered work have to be terminated due to Sub-Contractor's default and a separate tender have to be floated to get the remaining/ complete work executed, such defaulting Sub-Contractor will not be considered for tenders issued for the refloated works of same project.

3.11 Only Class-I & Class-II local suppliers, as defined in the policy for Public Procurement (Preference to Make in India) (PPP-MII) order, 2017 attached with Bidding Document, are eligible to quote and such bidders shall submit the required documents as specified in the said policy.

B CONTENTS OF BIDDING DOCUMENT

4.0 BIDDING DOCUMENT

4.1 The Bidding Document shall in general consist of the following and should be read in conjunction with any amendment issued in accordance with ITB 7.0.

- Letter Inviting Bid (LIB) / Invitation for Bids (IFB)
- Instructions to Bidders and its attachments.
- Bid Data Sheet (BDS)
- Bidding Forms / Proposal Forms
- General Conditions of Contract (GCC).
- Special Conditions of Contract (SCC) and its Annexure.
- Schedule of Rates (SOR)/ Schedule of Prices (SOP).
- Technical Specifications / Standards.
- Drawings, if any

4.2 Although all the details presented in this Bidding Document have been compiled with reasonable care, the bidder is expected to examine the Bidding Document, including all instructions, forms, terms, specifications and drawings in the Bidding Document and it includes all the documents as per Table of Contents. In case of any ambiguity or incompleteness, the bidder must bring it to the attention of EIL immediately and prior to submission of Bid.

4.3 Bidding document once issued in case of limited competitive bidding is non-transferable. However, in case of Open Competitive Bidding, since the Bidding Document is available for free downloading on the portal, any bidder may submit the Bid and the same shall be evaluated in line with the provisions of the Bidding Document.

5.0 CLARIFICATION OF BIDDING DOCUMENT, PRE-BID MEETING

5.1 The enquiry is issued on "***Zero Deviation Bidding***" basis wherein no post bid correspondence of any nature shall be entertained. Bidders in their own interest are advised to take part in the pre-bid meeting seriously by issuing their genuine queries and also by attending the pre-bid meeting by their competent personnel. This will help bidder not only to cut short the evaluation time leading to requirement of shorter bid validity but also enable the bidder to submit their best prices based on the clear techno-commercial scope.

5.2 Bidder shall submit their queries only through NIC CPP portal strictly on or before cut-off date mentioned in IFB/LIB/CPP portal after which, EIL shall reserve the right not to entertain any queries. **Queries sent through e-mails by any bidder shall not be given any cognizance.**

5.3 To facilitate the above, Bidder's authorized representative(s) shall attend the pre bid meeting on the prescribed day at the given venue or through online platform specified in IFB/ LIB. During the pre-bid meeting, all the technical and commercial issues shall be discussed and concluded to ensure that the bid received subsequent to pre bid meeting shall be without any deviations to terms and conditions. Hence, bidders shall treat the pre bid meeting as utmost important and depute competent & senior person capable of taking on the spot decision to sort out all the technical and commercial issues.

However, in case any bidder does not attend the pre bid meeting, it shall be understood that the bidder has a clear understanding of the scope, terms & conditions of the bidding document and does not have any comments/ deviations to the requirements of the bidding document.

5.4 Conclusion agreed in this meeting shall be uploaded as "Record Notes of Pre-bid Meeting /Reply to Pre-bid Queries" containing clarifications to the bidder's queries, on portals where bidding document issued. Any modification/ amendment or any clarification leading to modification to the commercial or technical part of the bidding document shall not be issued as a clarification but shall be issued through amendment/addendum only. This addendum / amendment shall be considered a part of the bidding document. However, Record Notes of Pre-bid Meeting/ Reply to Pre-bid Queries shall not be considered as part of enquirydocument.

5.5 The bidders may carry their qualification documents in case they desire them to be reviewed by EIL officials during the pre-bid meeting. The bidders would also be requested to ensure that the bid along with qualification documents is submitted well within bid due date and time.

5.6 Non participation in the pre-bid meeting shall not be rejection criteria.

5.7 Although the details presented in this Bidding document have been compiled with all reasonable care, it is the Bidder's responsibility to ensure that the information provided is adequate and clearly understood and it includes all documents as per the Index.

5.8 In order to ensure fruitful discussions during pre-bid meeting, the bidder is requested to submit any queries/clarification/information pertaining to Bidding document, as per the proforma enclosed as **Form-D** to ITB, only through NIC CPP portal strictly on or before cut-off date mentioned in IFB/LIB/CPP portal. **Queries sent through e-mails by any bidder shall not be given any cognizance**. These queries shall be replied during pre-bid meeting.

5.9 The bidders are required to participate in the pre-bid meeting after going through the entire bidding document. Bidder shall come with all technical and commercial points on which they need clarifications and also to ensure that they possess all the supporting documentation. In case of any doubt, they may discuss the same during the meeting to avoid any techno-commercial clarifications/ discussions post bid.

5.10 Based on the pre-bid discussions, no-deviation form/techno-commercial compliance shall be signed and submitted by the bidders as part of their offer. After pre-bid meeting, no deviation shall be accepted. Bidder in their own interest shall submit bids fully complying to bidding document requirements and EIL shall reserve the right to proceed with the available compliant bids for evaluation without raising any technical/ commercial queries.

5.11 Technical/ Commercial queries (TQ/CQ) shall not be issued once the bid have been opened. However, wherever CQ/ TQ are unavoidable, the same shall be raised and the cut-off date given for CQ/ TQ replies shall be adhered to. Offers shall be evaluated based on the information available upto cut-off date for CQ/ TQ replies. Bidder shall not submit any Price against TQ/ CQ raised unless specifically sought in writing.

6.0 SITE VISIT

6.1 Bidder is advised to visit and examine the site, its surroundings and familiarise himself with the existing facilities and environment, and collect all other information which he may require for preparing and submitting the bid and entering into the Contract. Claims and objections due to ignorance of existing conditions or inadequacy of information will not be considered after submission of the Bid and during implementation. All costs towards the same including the cost of visiting the Site shall be at the bidder's own expense.

6.2 Bidder and any of its personnel will be granted permission by EIL/Owner to enter upon its premises and lands/ Project Site for the purpose of such visit, but only upon the express condition that the bidder and its personnel will relieve and indemnify EIL/Owner and its personnel from and against all liability in respect thereof, and will be responsible for death or personal injury, loss of or damage to property, and any other loss, damage, costs, and expenses incurred as a result of the inspection.

6.3 Any loss to the property / life of the visitor during the said visit shall be the visitor's responsibility. Visitor shall keep EIL/ Owner indemnified from any legal consequences arising there from.

6.4 **Bidder shall refer BDS for schedule and contact details related to site visit.**

7.0 AMENDMENT OF BIDDING DOCUMENT

7.1 At any time prior to the deadline for submission of bids, EIL may, for any reason whether at his own initiative or in response to the clarification requested by the prospective bidder(s), issue amendment in the form of Amendment/ Addendum. Any amendment thus issued shall become part of Bidding Document and Bidder shall submit a copy of the Addendum duly signed and stamped in token of his acceptance.

7.2 Any addendum issued shall be part of the Bidding Documents and shall be uploaded on https://eprocure.gov.in/eprocure/app portal.

7.3 To give bidders reasonable time in which to take an addendum into account in preparing their bids, EIL may extend the deadline for the submission of bids, pursuant to Clause 22.3 of ITB.

7.4 EIL may also for any reason issue amendment subsequent to receiving the bids. Any amendment thus issued shall become part of Bidding Document. Bidder shall follow the instructions issued along with Amendment with regard to submission of impact on quoted price / revised price, if any.

8.0 CONFIDENTIALITY OF BIDDING DOCUMENT

8.1 The Bidding Document is and shall remain the exclusive property of EIL without any right to Bidder to use them for any purpose except for the purpose of Bidding.

8.2 On no account will any agency to whom Bidding Documents is issued, part with possession thereof or copy or take copies or tracings of any drawing, plan etc. It should be understood that the information therein is confidential, and that the Bidding Documents are therefore being issued to bidders in the strictest confidence.

9.0 ACKNOWLEDGEMENT & CONFIRMATION

9.1 Within 3 days of downloading of Bidding Document, bidder shall acknowledge and confirm his intention to bid or otherwise, for the tendered work on EIL website http://tenders.eil.co.inor as per proforma "Acknowledgement-Cum-Consent Letter" enclosed in Bidding Document.

C PREPARATION OF BIDS

10.0 COST OF BIDDING

10.1 Bidder shall bear all costs associated with the preparation and submission of its Bid, and EIL/ Owner shall not be responsible or liable for those costs, regardless of the conduct or outcome of the bidding process.

11.0 LANGUAGE OF BID

11.1 The Bid, as well as all correspondence and documents relating to the bid exchanged by the bidder and EIL, shall be in the English language. Supporting documents and printed literature that are part of the Bid may be in another language provided they are accompanied by an accurate translation of the relevant passages in the English language, in which case, for purposes of interpretation of the Bid, such translation shall govern.

11.2 In the event of submission of any document/ certificate by the bidder in a language other than English, the bidder shall get the same translated into English and submit the same after getting the translation duly certified, stamped and signed by local Chamber of Commerce or Indian Embassy or any translator in India recognized / authorized by Indian Embassy.

12.0 COMPLIANCE TO BID REQUIREMENT

12.1 ZERO DEVIATION:

i) Bidders to note that enquiry is issued on Zero deviation basis. Bids are to be submitted on Zero deviation basis and in strict compliance with the terms & conditions, scope, specifications and other stipulations contained in the enquiry without any deviations.

ii) Accordingly, Bidder must submit format for "Compliance to Bid requirement" as per **Form-C**, duly filled in along with Unpriced part of Bid.

iii) Any condition specifically mentioned in the tender documents elsewhere that non-compliance of the clause shall lead to rejection of the bid.

iv) In case Bidder stipulates deviations, EIL have the right to reject such bid at its absolute discretion without giving any opportunity for such Bidder to make good such deficiency.

13.0 DOCUMENTS COMPRISING THE BID

13.1 Bidders should submit their bid through Govt. of India's Central Public Procurement Portal (CPPP) https://eprocure.gov.in/eprocure/app only. Bidder shall follow the guidelines as given in Annexure-I to ITB of the Bidding Document for submission of their bid in CPP Portal https://eprocure.gov.in/eprocure/app.

13.2 The e-Bid should be prepared by the Bidder and shall be submitted on the aforesaid website in three parts duly e-signed as per the following details:

i) PART – I: Earnest Money Deposit (EMD)/ Bid Security

ii) PART – II: Techno-Commercial / Unpriced Bid

iii) PART - III: Price Bid

13.3 PART- I (EARNEST MONEY DEPOSIT / BID SECURITY)

Scanned Copy of Bid Security (or exemption certificate, wherever applicable) in accordance with Clause 19.0 of ITB.

Note: The above shall be uploaded in "Fee folder" in e-tendering portal

13.4 **PART- II (TECHNO-COMMERCIAL/ UNPRICED BID)**

This part shall contain scanned copies of Technical and Unpriced Commercial bid, which shall comprise the following:

(a) Bid forwarding letter;

(b) Master Index and Amendment/ addendum (if any), duly signed and stamped by the bidder in token of having read all parts of the Bidding Document and having accepted and considered the same in preparing and submitting the Bid;

(c) Scanned Copy of Power of Attorney in favour of person (s) digitally signing the bid that such person (s) is/are authorised to sign the bid on behalf of the bidder and any consequence resulting due to such signing shall be binding on the bidder. For proprietorship agency, it should be clearly specified in the Bidder's letter head that it is a proprietary firm and the Bidder is the sole owner. For partnership firm, power of attorney by all other partners in the name of the person who will sign their offer.

Note:- All documents/files of the bid shall be signed and uploaded by using the digital signature issued in the name of the person having valid Power of Attorney at the time of bid submission.

In case of bids submitted by a JV, if permitted in BDS, shall include a copy of the Joint Venture Agreement entered into by all members;

(d) Integrity Pact duly filled in, signed & stamped on each page as per Form-K of Bidding Forms along with an undertaking confirming that bidder is not involved in any case of transgression in terms of Integrity Pact, in accordance with Clause 14 of ITB.

(e) Bid Form (Bidding Form-A) & Information about bidder (Bidding Form-B) in accordance with relevant forms provided in Bidding Forms;

(f) Compliance to Bid requirement (Bidding Form-C) as per relevant form provided in Bidding Forms;

(g) Commercial Questionaire (Bidding Form-E)

(h) Checklist for submission of bid (Bidding Form-F)

(i) Bank Mandate Form (Bidding Form-G) with cancelled cheque duly signed and stamped with the Banker's certification as per relevant form provided in Proposal Forms;

(j) Details of P.F. and ESI Registration as per Form-H (1) of Proposal Forms.
In case Bidders establishment is not registered with PF & ESI Authorities, the Bidder shall furnish an undertaking, as per Form-H(2) of Proposal Forms, that in the event of their establishment falls under the purview of PF & ESI Act during the execution of Contract then the Bidder shall get their establishment registered under PF & ESI and they shall also be solely responsable to fulfil the obligation of PF & ESI at no extra cost to EIL/Owner.

(k) Self Declaration as per Bidding Form-J.

(l) Bidder's Undertaking regarding "Procurement from a Bidder from a Country sharing Land Border with India" policy (Form-I A / Form-I B / Form-II, as applicable in Annexure-V of ITB)

(m) Bidder's Undertaking regarding "PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII) ORDER, 2017" policy i.e. FORM 2 only enclosed in Annexure-IV of ITB).

(n) Documents as per requirement specified w.r.t DMI&SP policy in clause 33.0 of ITB.

(o) Signed and stamped copy of Preamble to SOR & Pre-filled SOR (FORM SP-0).

(p) As a token of confirmation that prices are quoted in the requisite format strictly complying to the requirement, **unpriced copy** of Schedule of Rates (SOR) **(FORM SP-1 & SP-3)**, as uploaded in the price bid, with prices being replaced by word "quoted", shall be uploaded along with the un-priced bid.

(q) Completely filled, signed and stamped copy of 'Statement for details of GST' (**FORM SP-2**) shall be submitted along with the un-priced part.

(r) Copies of documents defining constitution or legal status, place of registration and principal place of business of the Company.

Organization details

- In case of a proprietorship firm, the name and address of proprietor, and certified copy of Bank Account Details and self-declaration on letter head certifying himself.
- In case bidder is a partnership firm, certified copy of the partnership deed.
- In case of company (whether private or public), certified copy of the `Certificate of Incorporation' together with certified copy of Memorandum/Articles of Association.

(s) Signed and stamped copy of Annexure-IV (KEY CONSTRUCTION MANPOWER TO BE DEPLOYED) to SCC & Annexure-VII (KEY CONSTRUCTION EQUIPMENTS TO BE MOBILIZED) to SCC.

(t) Documents required as per IFB/NIT.

(u) Deleted.

(v) Any other information required in the Bidding Documents or considered relevant by the bidder.

(w) In addition to above, in case the bidder is a Micro or Small Enterprise (MSE), then they shall submit Udyam Registration certificate. The Udyam Registration certificate shall be verified from GoI Udyam registration portal. Also, if the MSE is owned by SC/ST Entrepreneurs or MSE Owned by Women, the bidder shall furnish appropriate documentary evidence in this regard

Note: The above shall be uploaded in "PREQUAL/ TECHNICAL" folder in e-tendering portal

13.5 PART-III (PRICED BID)

(a) Schedule of Prices/ Schedule of Rates with prices filled in (including rebate, ifany). The rates are to be filled in accordrance with instructions provided in preamble to Schedule of prices, in e-tendering portal, without making any changes in the format/names of the file/worksheet.

(b) Stipulation, Deviation to terms and conditions, presumptions, overwriting etc. shall not be stipulated in Price part of bid. In case of & conditions stipulated in Price bids are in deviation to terms & conditions of Enquiry, the bids of such bidders shall be summarily rejected and shall not be considered for further evaluation. Evaluation shall be carried out excluding such bidder(s).

(c) In case a bidder submits prices or any other figure (required to be quoted in Price bid) which affects the Price evaluation, in their un-priced part, such prices shall not be given any cognizance. In case the bid ofs uchbidder is techno-commercially acceptable, the prices as quoted by the bidder in the priced part shall be considered for evaluation and ordering.

(d) If after opening of Price part, it is observed that the bidder has not indicated the prices in the Price part, the bid of such bidder shall be considered as non-responsive and shall be rejected irrespective of the fact that the bidder had submitted the prices in the un-priced part and Price evaluation shall be carried out with the remaining techno-commercial aceptable bidders. The prices uploaded at the designated priced folder of the e-tendering website shall only be considered.

Part-III shall be uploaded in "FINANCE" folder in e-tendering portal.

14.0 *INTEGRITY PACT*

14.1 EIL has entered into a Memorandum of Understanding (MoU) with Transparency International India (TII) for implementation of Integrity Pact in EIL. Bidder shall submit, the scanned copy of the Integrity Pact (Form-K of Bidding Forms) duly signed and stamped in token of compliance in **Part-II (Unpriced Techno-Commercial Part)** of the Bid.

14.2 **Non-submission of Integrity Pact in the bid shall be a ground of disqualification. However, in case of non-submission of Integrity Pact alongwith the bid, an opportunity shall be given in the CQ to submit the IP, provided bidder has declared integrity pact submission confirmation in Checklist (Form-F) of Bidding Forms.**

14.3 The detail of Independent External Monitors (IEMs), appointed by EIL, in terms of Integrity Pact (IP) is **specified in the BDS**.

14.4 The Bidder in addition to submitting Integrity Pact shall also be required to specifically confirm that "Bidder is not involved in any case of transgression in terms of Integrity Pact" by submitting signed and stamped copy of "Undertaking w.r.t. section V of integrity pact"(as per Annexure-I of Form-K of Bidding Forms).

14.5 Integrity Pact shall be signed by the authorised signatory of the bidder. However, in case of Proprietorship firm IP may be signed by the Proprietor and in case of Partnership firm, IP shall be signed by all Partners of the firm.

In case of consortium bids (if permitted in BDS), Integrity Pact shall be submitted by all consortium members. Also, Affidavit shall be submitted by all the members of Consortium. Non-submission of Integrity Pact in the bid by any of the consortium member shall be a ground of disqualification. In case of non-submission of Integrity Pact in the bid by any of consortium member, no opportunity shall be given in the TQ/CQ to submit the IP, even though CQs/TQs are being issued to other bidders.

In case of sub-contracting, the principal contractor shall be solely responsible for adherence to the provision of the Integrity Pact. The Integrity Pact and Undertaking w.r.t. section V of integrity pact" shall be submitted by the Principal contractor only.

15.0 ALTERNATIVE BIDS

15.1 A bidder (i.e., the bidding entity) shall, on no account submit more than one bid either directly (as a single bidder or as a member of consortium) or indirectly (as a sub-contractor) failing which following actions shall be initiated:

i) All bids submitted by such bidder (say 'A') directly & indirectly, shall stand rejected and BID SECURITY, if any, in case of direct bid submitted by bidder 'A' shall be forfeited.

ii) If another bidder (say 'B') has proposed bidder 'A' as a sub-contractor then bidder 'B''s bid shall also be rejected. However, in case the bidder 'B' has also proposed an alternative sub-contractor who is other than the bidder 'A', then bidder 'B''s bid shall be evaluated with the proposed alternative sub-contractor only. Hence, every bidder shall ensure in his own interest that his proposed sub-contractor is not submitting alternative/ multiple bids.

Note: However, in case EIL has proposed a list of Sub-contractor/ sub-vendors in the enquiry document itself which shall be common for all the Bidders, the provisions at (ii) above shall not be applicable as long as only the Sub-contractor / sub-vendors are common in case of various bidders. It is further clarified that:

- A sub-Contractor can be common to more than one Bidder, provided the sub-Contractor themselves are neither a Bidder nor a consortium member.
- Where an Enquiry has multiple Parts, the above condition shall be applicable individually for each Part, as if it is a separate Enquiry.

16.0 BID PRICES AND DISCOUNTS

16.1 The prices must be quoted strictly in the format provided in the Bidding Document. Conditional discount, if offered, shall not be considered for evaluation.

16.2 Unless stated otherwise in the Bidding Document, the Contract shall be for the total works as described in Bidding Document, based on the Schedule of Rates/ Prices submitted by the bidder and accepted by EIL.

16.3 Bidder shall quote for all the items of Schedule of Rates/Prices after careful analysis of cost involved for the performance of the complete item considering all parts of the Bidding Document. In case any activity is not specifically covered in description of item under `Schedule of Rates/Prices' but is required to complete the work as per Scope of Work, Scope of Supply, Specifications, Standards,

Drawings, General Conditions of Contract, Special Conditions of Contract or any other part of Bidding Document, the rates/ prices quoted shall be deemed to be inclusive of cost incurred for such activity.

16.4 The quoted price for performance of the work & services pursuant to the Contract shall be deemed to be inclusive of all taxes duties levies and cess etc. except "Goods and Services Tax" (hereinafter called GST) (i.e. IGST or CGST and SGST/UTGST, applicable in case of interstate supply or intra state supply respectively and GST compensation cess if applicable) in line with provisions of Special Conditions of Contract.

It is for the bidder to assess and ascertain the rates of applicable Taxes & Duties for the tendered work. It is clearly understood that Owner / EIL will not have any additional liability towards payment of applicable Taxes & Duties as a result of Bidder's wrong assessment / interpretation of applicable taxes & duties. Any implication on account of wrong quotation of taxes and duties shall be to Bidder's account. However, the payment towards such taxes and duties shall be restricted to lower of taxes and duties quoted by the bidder or the documentary evidence provided by the bidder.

16.5 Percentage/Rates/ prices quoted by the bidder, shall remain firm, fixed and valid till the completion of the Works and will not be subject to variation on any account except as otherwise specifically provided in the Bidding Documents.

16.6 Discount, if any, must be indicated in the columna provided in Schedule of Rates/Prices only, provided in the Bidding Document.

16.7 All duties, taxes, and other levies payable shall be as per Special Conditions of Contract.

17.0 CURRENCIES OF BID AND PAYMENT

17.1 Unless otherwise specified in BDS, bidder shall submit Bid in Indian Rupees only and payment shall be made in Indian Rupees only.

18.0 PERIOD OF VALIDITY OF BIDS

18.1 Bids shall remain valid for the period **specified in the BDS** after the bid submission deadline date prescribed by EIL in accordance with Clause 22.0 of ITB. A bid with shorter validity shall be rejected by EIL as non responsive. Bidders shall not be entitled during the above period, without the consent of EIL in writing, to revoke or cancel their Bid or to vary the Bid given or any term thereof. In case of bidders revoking or cancelling their Bid or varying any terms in regard thereof without the consent of EIL in writing, EIL shall forfeit Bid security, submitted along with the bid and shall reject their bids. Such Bidder may also be put on Holiday list/ Negative List / Suspension / Banning List.

18.2 In exceptional circumstances, prior to the expiration of the bid validity period, EIL may request bidders to extend the period of validity of their bids. The request and the responses shall be made in writing. If a bid security is requested in accordance with Clause 19.1 of ITB, it shall also be extended for 2 (Two) months beyond the deadline of the extended validity period [for extension in required original bid validity by more than 15 days]. A bidder may refuse the request without forfeiting its bid security. A bidder granting the request shall not be permitted to modify its bid.

19.0 BID SECURITY / EARNEST MONEY DEPOSIT (EMD)

19.1 Bidder shall furnish as part of its bid, a Bid Security, in the amount and currency specified in the IFB/ in case of CPSUs/CPSEs, declaration from CPSUs/CPSEs in line with Clause 19.3 of ITB/ ~~in case of start-up, exemption document in line with 19.4~~. Bids submitted without Bid Security/Documentary

proof claiming EMD exemption or Bids Submitted with Bid Security for an amount less than the specified amount or Bid Security submitted in favour of beneficiary other than as specified in Enquiry Document or from other than the required bank shall be rejected outright and shall not be considered even for unpriced bid opening. Further, in case Bank Guarantee / DD / Fixed Deposit receipts (FDRs) submitted by the bidder is found to be fake, the bid will be rejected and a suitable action as per provision of Fraudulent Practice shall be initiated. **Format for Bid Security shall be as per Annexure-VII to ITB or Annexure-VIII to ITB.**

19.2 **EMD exemption is not applicable for MSE bidders.**

19.3 Indian CPSUs [state PSUs are not exempted] will be exempted from submitting Bid Security. CPSUs shall submit undertaking in their letter head to this effect that being CPSUs they are exempted from submitting Bid Security.

19.4 DELETED

19.5 EIL shall not pay any interest on Bid Security furnished. Further, in case Bid security submitted is found to be fake, bid of such bidder shall be rejected and may initiate action as deemed necessary as per EIL Policy.

19.6 The bid security shall be submitted through a demand draft / Banker's Cheque / bank guarantee / through Net Banking or Fixed Deposit receipts (FDRs) in favour of Engineers India Limited, in any of the following forms at the bidder's option:

a) Bidders (Indian or Foreign) shall submit unconditional Bank Guarantee or Fixed Deposit receipts (FDRs) through an "Indian Scheduled Public Sector or Scheduled Private Sector or Indian branch of Scheduled Foreign Banks as per RBI's List of Scheduled Commercial Banks (SCBs), strictly as per format (available in Annexure-VII to ITB or Annexure-VIII to ITB) provided in Bidding document;

b) DD payable at New Delhi

c) EIL Net Banking details mentioned in BDS. Bidder to upload scanned copy of the net banking transfer receipt.

19.7 **In case of bid security in the form of Bank Guarantee (BG) / Demand Draft (DD) / Fixed Deposit receipts (FDRs), bidders shall also be required to submit the original DD/BG/ Fixed Deposit receipts (FDRs) to EIL, in sealed envelope, before the due date and time for submission of Bid, mentioned in the LIB/IFB or any extension thereof as duly notified in writing by EIL, at the address mentioned in BDS. If the Bidder fails to submit Bid Security (BG/ DD / Fixed Deposit receipts (FDRs)) physically in original within the above cut-off date, his bid shall be rejected and not considered for further evaluation, irrespective of their status/ ranking in tender and notwithstanding the fact that a copy of Bid Security was earlier uploaded by the bidder on the e-tendering portal.**

19.8 The bid security shall be valid for Two (2) Months beyond the validity period of the bid, or beyond any period of extension if requested under Clause 18.2 of ITB.

19.9 EMD/ Bid securities of unsuccessful bidders will be returned upon placement of order/ award. Also, EMD of late bids/ where unpriced bids not opened / whose priced bids not opened, shall be returned after priced bid opening. In case of the successful Bidder, the same will be returned after the order/ contract is effective and Contract Performance Bank Guarantee / Fixed Deposit receipts (FDRs) / Security Deposit is submitted. However, in case EIL decides to cancel / annul the Enquiry / bidding

document at any stage during the bidding process but before the award of work/ items (as applicable), EMD of the bidders shall be returned at the earliest from the date of such decision.

19.10 The bid security shall be forfeited:

(a) If the bidder submits alternative bids in accordance with Clause 15.0 of ITB;

(b) If the bidder suo moto modifies his bid; or

(c) Withdraws his bid during the period of bid validity; or

(d) In case, during evaluation of bid, it is found that any forged/fake document has been furnished; or

(e) In the case of the a successful bidder, if the bidder fails or refuses:

(i) to sign the Contract in accordance with Clause 41.0 of ITB; and/or

(ii) to furnish a Contract performance Bank Guarantee in accordance with Clause 42.0 of ITB; and/or

(iii) to accept arithmetical corrections pursuant to Clause 35.0 of ITB.

In case, any of the above events happens, the bidder shall be given a notice of 7 days to take corrective action and in case corrective action is not taken, the bid security shall be encashed without any further notice

19.11 In case of a JV/Consortium bid (if permitted in BDS), the Bid Security shall be submitted by the Leader or any of the members of the Consortium on behalf of consortium and in the amount and currency **specified in the LIB.**

19.12 SFMS (STRUCTURED FINANCIAL MESSAGING SYSTEM)

Apart from hard copy submission of BGs, bank guarantee issued towards EMD/CPGB/ABG etc. it shall be preferred that same is also routed through SFMS (Structured Financial Messaging System) platform for Bank Guarantee issuance and Verification.

The information/message (as per SFMS platform) shall be sent by BG issuing bank branch to EIL's Banker for BG issued in favor of EIL as per details below:-

Name	Engineers India Limited
Address of EIL	1,Bhikaiji Coma Place,RK Puram New Delhi-1100
e-Mail address	billing@eil.co.in
PAN	AAACE5318C

Name of Bank	State Bank of India CAG Branch-II, 4th and 5th Floor Red fort Capital Parsvanath Towers Bhai Veer Singh Marg Gole Market, New Delhi-110001 Tel:011-23475562/5569 Fax:011-23475580
Branch Code	17313
Current Account Number	10813604212
IFSC Code	SBIN0017313
MICR Code	110002562
SWIFT Code (for USD)	SBININBB824

20.0 FORMAT AND SIGNING OF BID

20.1 The bidder shall submit e-bid as per the provisions given in this bidding document in Govt. of India's Central Public Procurement Portal (CPPP) https://eprocure.gov.in/eprocure/app as per the guidelines given in the bidding document.

20.2 The e-bid shall be digitally signed (e-signed) using the digital signature of a person duly authorised to sign on behalf of the bidder. The digital signature used for signing the bid shall be issued in the name of such authorised person and the certificate details, available from the e-signed documents, should indicate the details of the signatories. All documents/files of the bid shall be signed by using the digital signature issued in the name of the person having valid Power of Attorney (POA) at the time of bid submission. Any consequences resulting due to such signing (e-signing) shall be binding on the bidder. All documents as submitted in the e-Procurement Portal using digital signature at any time during the Bidding process shall be deemed considered signed by the authorized signatory only, irrespective of authorised signatory's signature on all pages or not.

20.3 Requirements for submitting the POA shall be as follows:

i) Company: Bidder shall submit a specific Power of Attorney for the tender in the name of authorized person.

Alternatively, in case Bid signatory has General Power of Attorney or has the power as per their Board resolution, the same shall be submitted duly certified by Notary Public or CEO/CFO/Company Secretary (CS)/Member of Board of Directors.

In case, Bid is signed by CEO/CFO/CS/any member of board of Directors, no separate POA is required, provided the documentary evidence of their being CEO/CFO/CS/any member of board of Directors is reflected in the MOA/AOA/Financial Statements, else submitted separately in the Bid.

ii) Partnership Firm: In such case,

- Bid can be signed by all the partners of the Firm and in such case no separate POA is required. OR
- Bid can be signed by any of the Partner(s) holding Power of Attorney as specified in the Partnership Deed, OR

- Bid can be signed by an authorized person and shall submit a specific POA for the tender duly signed by all the Partners.

  Bidder shall submit the copy of Partnership Deed.

iii) Limited Liability Partnership (LLP) Entity: Bid shall be signed by the person holding Power of Attorney as per the registered LLP Agreement for the Firm, OR, has the power as per their Board resolution, OR, a specific POA for the tender duly signed by all the LLP Partners.

Bidder shall submit (i) a copy of LLP Agreement, and (ii) a copy of Certificate of Incorporation.

iv) Proprietorship: Proprietor shall sign the Bid.

Bidder shall also submit a copy of (i) PAN card and (ii) Bank Mandate Form, duly certified by the Bidder's Banker.

v) For Indian Bidder, POA shall be on non-judicial stamp paper of minimum value of INR 100/- and duly Notarized by a Notary Public in India.

vi) Specific POA issued for the tender shall confirm that the authorized signatory has been authorized to do in the name and on behalf of the Company/Firm all or any of the acts, deeds or things necessary in connection with or incidental to the Bid submitted by the bidder for the subject Enquiry Document, including but not limited to the signing and submission of bid, participating in the meetings, responding to queries, submission of information / documents and generally to represent us in all the dealings with EIL/ Owner or any person, in connection with the works, without any prejudice, limitations and exceptions till the completion of the bidding process.

20.4 In case of a JV/Consortium bid (If permitted in the bidding document), the Bid shall be digitally signed (e-signed) using the digital signature of a authorized representative of the JV /Consortium, and so as to be legally binding on all the members as evidenced by a power of attorney signed by their legally authorized representatives.

D SUBMISSION AND OPENING OF BIDS

21.0 SEALING AND MARKING OF BIDS

21.1 **The bidder shall submit the, original Bid Security as per the requirement of Clause No. 19.0 of ITB at the address mentioned in BDS, in separate sealed envelopes, duly marking the** envelopes, as follows:

Part I -Bid Security & Originals
Name of Work:_____
Bidding Document No.:_____
Due date & Time of Submission: _____
From: [Name & Address of Bidder]: _____

21.2 The envelope shall bear the name and address of the bidder and bear a warning not to open before the time and date for bid opening. Bidder shall also mention the Bidding Document No. and Bidder's name on the back of DD.

21.3 If all envelopes are not sealed and marked as required, EIL will assume no responsibility for the misplacement or premature opening of the Part-I of bid.

21.4 Bidders shall submit bids (**Part-II & Part-III**) electronically.

22.0 DEADLINE FOR SUBMISSION OF BIDS

22.1 Bidders shall submit their bids electronically in the e-tendering portal, within the date and time **specified in the LIB/IFB**. Bidders submitting bids electronically shall follow the electronic bid submission procedures enclosed as **Annexure-I to this ITB.**

22.2 Bid Security in form of BG/DD in accordance with ITB 19.0, in original, must be received by EIL at the address mentioned in BDS and no later than the date and time for submission of Bids **specified in the LIB/IFB** or any extension thereof as duly notified in writing by EIL**.**

22.3 EIL may, in exceptional circumstances and at its discretion, on giving reasonable notice, extend the deadline for the submission of bids in which case all rights and obligations of the EIL and bidders, previously subject to the original deadline will thereafter be subject to deadline as extended. Bidders in their own interest are requested to register on e- tendering portal and upload their bid well in time.

22.4 Bidders should avoid the last hour rush to the website wherein bidder is likely to miss the deadline for bid submission. Due date extension request due to above reason may not be entertained.

23.0 *LATE BIDS/ BID SUBMISSION AT OTHER PLACE*

23.1 E-tendering system shall close immediately after the deadline for submission of bid or any extension thereof as duly notified in writing by EIL.

23.2 Any Bid being submitted in physical form (other than Part-I of Bid) shall not be considered for opening / evaluation / award and will be returned to such bidders.

23.3 In the event the Bid Security in original, in accordance with ITB 22.2, are not submitted within the deadline for submission of bids, the bids shall be declared late and shall not be considered for opening, notwithstanding the fact that the bid has been submitted in electronic form within the deadline. Bid security received in physical form in sealed envelope shall be returned to such bidder as it is, after the Unpriced Bid Opening of other eligible bidders.

24.0 WITHDRAWAL, SUBSTITUTION, AND MODIFICATION OF BIDS

24.1 The bidder may modify, re-submit or withdraw its e-bid after the bid submission, but, before the due date and time for submission of Bid following the electronic bid submission procedures**.**

24.2 No bid shall be withdrawn, substituted, or modified in the interval between the deadline for submission of bids and the expiration of the period of bid validity or any extension thereof. Withdrawal or modification of a bid during this interval shall result in the rejection of the bid and other action defined in the bidding document and under suspension/ banning policy of EIL/Owner.

25.0 BID OPENING

25.1 EIL shall verify the availability of requisite BID SECURITY in accordance with the provisions of bidding document, prior to opening of Part-II of e-Bid. Techno-commercial e-Bid of those bidders shall be considered for opening, who have already submitted the requisite Bid Security, in accordance with the provisions of bidding document.

25.2 Part-II of all bids received in the e-tendering portal for the cases specified in clause 23.3 of ITB shall not be opened.

25.3 Un-priced Bids shall be opened on the E-Tendering Portal. On the E-Tendering Portal, the participating Bidders can view the bid opening details online at their respective places. The Bid opened online shall be deemed considered as public opening and the Bidders representative shall not be called for attending the bid opening process. However, Bidder at their own will, may attend the opening at the EIL's office with an authorization letter/email. No separate formal communication will be sent for inviting the bidders for physically attending the bid opening.

25.4 The order of part wise opening of bids shall be as follows;

i. On scheduled date and time of UNPRICED bid opening,

a) Scanned copy of Bid Security along with original Bid Security (submitted in form of BG/DD) shall be opened first and verified whether Bid Security has been furnished as per bid requirement.

b) Upon meeting the requirement of Bid Security as per Clause 19.0 of ITB, Opening of documents of part –II, submitted in electronic form shall be processed on the e-Procurement module of the e-tendering portal.

c) If a bidder has not complied with Bid Security requirement b) above, such bidder's offer (Part-II) is not proceeded for further opening and rejected outright.

ii. Part-III of bid of only those bidders whose bids are determined to be technically and commercially acceptable by EIL shall be opened. Bidders selected for opening of their priced bids shall be informed about the date, time and place of price bid opening.

E EVALUATION AND COMPARISON OF BIDS

26.0 CLARIFICATION REQUEST FROM BIDDER

26.1 A bidder may seek clarification regarding the bidding document provisions, bidding process and / or rejection of his bid. EIL shall respond to such requests within a reasonable time. However, such information relating to the evaluation of bids and recommendation of contract award shall not be disclosed to any other persons not officially concerned with the bidding process.

26.2 Any attempt by a bidder to influence EIL/ Owner in the evaluation of the bids or Contract award decisions shall render their Bid liable for rejection.

26.3 Notwithstanding Clause 26.2 of ITB, from the time of bid opening to the time of Contract award, if a bidder wishes to contact EIL on any matter related to the bidding process, it shall be done so in writing only.

26.4 Right of Bidder to question rejection at Techno-commercial (Unpriced) Stage:

A tenderer shall have the right to be heard in case he feels that a proper procurement process is not being followed and/ or his Techno-commercial bid has been rejected wrongly. The tenderer is to be permitted to send his representation in writing. On receipt of representation it may be decided whether to withhold opening of the financial bids and bidder may be expeditiously replied. Certain decisions of the EIL in accordance with the provision of internal guidelines shall not be subject to review for reasons mentioned in 26.5 (iv) below.

26.5 Bidder's right to question rejection (at Award stage):

A tenderer shall have the right to be heard in case he feels that a proper procurement process is not being followed and/or his tender has been rejected wrongly. The tenderer is to be permitted to send his representation in writing to person details of which at sl. no. 5 of Bid Data Sheet (BDS). But, such representation has to be sent within 10 (ten) days from the date of LOA. The EIL should ensure a decision within 15 (fifteen) days of the receipt of the representation. Only a directly affected bidder can represent in this regard:

i. Only a bidder who has participated in the concerned procurement process i.e. prequalification, bidder registration or bidding, as the case may be, can make such representation
ii. In case pre-qualification bid has been evaluated before the bidding of Technical/ financial bids, an application for review in relation to the technical/ financial bid may be filed only by a bidder has qualified in pre-qualification bid;
iii. In case technical bid has been evaluated before the opening of the financial bid, an application for review in relation to the financial bid may be filed only by a bidder whose technical bid is found to be acceptable
iv. Following decisions of the EIL in accordance with the provision of internal guidelines shall not be subject to review
    a. Determination of the need for procurement;
    b. Selection of the mode of procurement or bidding system;
    c. Choice of selection procedure;
    d. Provisions limiting participation of bidders in the procurement process;
    e. The decision to enter into negotiations with the L1 bidder;
    f. Cancellation of the procurement process except where it is intended to subsequently re-tender the same requirements
    g. Issues related to ambiguity in contract terms may not be taken up after a contract has been signed, all such issues should be highlighted before consummation of the contract by the vendor/contractor; and
    h. Complaints against specifications except under the premise that they are either vague or too specific so as to limit competition may be permissible.

27.0 DEVIATIONS, RESERVATIONS, AND OMISSIONS

27.1 During the evaluation of bids, the following definitions apply:

(a) “Deviation” is a departure from the requirements specified in the Bidding Documents;

(b) “Reservation” is the setting of limiting conditions or withholding from complete acceptance of the requirements specified in the Bidding Documents; and

(c) “Omission” is the failure to submit part or all of the information or documentation required in the Bidding Documents.

28.0 DETERMINATION OF RESPONSIVENESS

28.1 EIL’s determination of a bid’s responsiveness is to be based on the contents of the bid itself, as defined in Clause 13.0 of ITB.

28.2 A substantially responsive bid is one that meets the requirements of the Bidding Documents without material deviation, reservation, or omission. A material deviation, reservation, or omission is one that,

(a) if accepted, would:

(i) affect in any substantial way the scope, quality, or performance of the Works specified in the Contract; or

(ii) limit in any substantial way, inconsistent with the Bidding Documents, EIL's rights or the bidder's obligations under the proposed Contract; or

(iii) would unfairly affect the competitive position of other bidders presenting substantially responsive bids.

28.3 No stipulation, deviation, terms & conditions, presumption, basis etc. shall be stipulated in the bid. Any conditions, if stipulated, shall be treated as null and void and shall render the bid liable for rejection.

29.0 CLARIFICATION OF BIDS

29.1 Bidders should ensure that the Bid submitted is substantially responsive Bid in the first instance itself. Evaluation may be completed based on the content of the Bid itself without seeking any subsequent additional information which may result in rejection of Bid. However, EIL may, at its discretion, request the bidder to submit the necessary information or documentation, within a reasonable period of time, to withdraw material deviation, reservation, or rectify omission in the bid related to documentation requirements. Requesting information or documentation on such account shall not be related to any aspect of the price of the Bid (forming part of price evaluation). EIL's request for clarification and the response shall be in writing.

29.2 No change, including any voluntary increase or decrease, in the prices or substance of the bid shall be sought, offered, or permitted. Bidder shall not be allowed to submit any price implication or revised price after submission of Bid unless the same is called for by EIL in writing.

29.3 Any clarification submitted by a bidder that is not in response to a request by EIL shall not be considered. Failure of the bidder to comply with the request may result in the rejection of its Bid.

29.4 If a bidder does not provide clarifications of its bid by the date and time set in EIL's request for clarification, its bid shall be evaluated with available information which may result in rejection of their bid.

29.5 UNSOLICITED POST TENDER MODIFICATIONS

Bidders are advised to quote strictly as per terms and conditions of the bidding document and not to stipulate any deviations/exceptions. Once quoted, the bidder shall not make any subsequent price changes, whether resulting or arising out of any technical / commercial clarifications sought on any deviations or exceptions mentioned in the bid. Similarly, no revision in quoted price shall be allowed should the deviations stipulated by him are not accepted by EIL and are required to be withdrawn by him in favour of stipulation of the bidding document.

Any unsolicited reduction/discount in price offered by a bidder within the bid validity by way of discount or revised prices, subsequent to the bid due date, shall not be taken into account for evaluation. However, such reduction in price shall be taken into account for ordering if such bidder happens to be recommended as per the originally quoted prices.

In the event of any unsolicited price increase sought by any bidder, subsequent to the bid due date, the bid of such a bidder shall be rejected, in case the bidder does not agree to withdraw the price increase. In case, price increase is sought by the L1 bidder after priced bid opening and the bidder does not agree to withdraw the price increase, the order shall not be placed with price increase and the **enquiry**

may be refloated. Wherever decision is taken to reject a bid, Bid Security, if submitted, by the Bidder, shall also be forfeited and the case shall then be referred for appropriate action as per procedure.

29.6 The scope of work has been defined in the bidding document. Only those bidders who take complete responsibility for the complete scope of work as contained in the bidding document shall be considered as acceptable.

30.0 EVALUATION OF TECHNO-COMMERCIAL BIDS

30.1 Prior to opening of price bids, EIL will determine whether each bid is accompanied with required Bid Security, Integrity pact, as applicable**;**

(i) Fulfils the technical, financial, experience and other requirements as specified in the Bidding Document;

(ii) Bid's responsiveness, in accordance with Clause 28.0 of ITB;

(iii) Any other relevant factor, if any that EIL deems necessary or prudent to be taken into consideration.

30.2 EIL reserves the right to use in-house information for assessment of capability of bidder and their performance on jobs completed/ in progress for evaluation purpose.

31.0 PREFERENCE TO MICRO OR SMALL ENTERPRISES

31.1 Benefits of Public Procurement Policy, 2012 for MSEs are not applicable for this tender.

31.2 EIL is committed to promotion and development of micro and small enterprises. Accordingly, bidders are also encouraged to promote the same by considering MSE suppliers/ Sub-contractor to the extent possible under the Orders/ Contracts awarded to them by EIL. All efforts shall be made by bidder to encourage procurement through MSEs (holding valid certificate) through their Sub-orders/ Sub-contract procurement. The successful bidder shall provide the following only for the purpose of reporting.

i) Monthly Reports for purchase of material/services/ sub-contracts (from MSE vendors) shall be submitted by bidder to .....(Name of CPSU).

ii) The report shall be signed by authorised person of Sub-contractor (Successful Bidder).

iii) Report shall be submitted in the following format.

Sl. N	Sub- Supp Subcontractor	Work order & date	Item Description	Amount In Rs)	Category MSE Gen/ ST/ Women	MSME Statu Micro/ Sr with code	Remarks

31.3 Government of India has implemented the Trade Receivables Discounting System (TReDS). TReDS is an institutional mechanism set up in order to facilitate the financing of trade receivables of MSMEs from corporate buyers through invoice financing by multiple financiers. EIL is already registered on the following TReDS Platform:

Name of the Company	Name of The Platform	Web Address	Address	Contact Person
A.TREDS Limited	Invoicemart	https://www.invoicemart.com/	11th Floor, Office No A-3, Ashar IT Park, Road No 16Z, Wagle Industrial Estate, Thane, Maharashtra, 400604	Mr. Ankur-8447308425
Receivables Exchange of India Limited	Trade Receivables Discounting System (TReDS)	http://www.rxil.in/	Trade Centre (Vatika Business Centre), First Floor (Unit No.2), Office No.14, BandraKurla Complex, Bandra (East), Mumbai – 400051. Maharashtra	Ms. Ruchi Agarwal 9560793437
Mynd Solutions Private Limited	M1xchange	https://www.m1xchange.com/	280, Udyog Vihar, phase-IV, Gurgaon, Haryana, 122001	Mr. Dipansu 9711008042

MSME bidders are requested to register on the TReDS platform.

32.0 PROCUREMENT FROM A BIDDER FROM A COUNTRY SHARING LAND BORDER WITH INDIA

Bidder shall refer the **Annexure-V of ITB** ["Tender Clause on Procurement from Bidders from a Country(ies) sharing land border with India"]. Accordingly, Bidders shall submit a certificate of compliance in the enclosed **Form - I A / Form - I B / Form-II as applicable in Annexure-V of ITB**, otherwise offer of the bidder shall be **REJECTED**.

33.0 POLICY FOR PROVIDING PREFERENCE TO DOMESTICALLY (INDIAN) MANUFACTURED IRON & STEEL PRODUCTS IN GOVERNMENT PROCUREMENT (DMI&SP)

33.1 In case Bidder's Quoted Price (Item wise basis) is more than INR 5 lakhs, Bidder should comply with the Domestically Manufactured Iron & Steel Policy (DMI&SP) for the Iron & Steel products involved in execution of the contract. Bidder shall submit affidavit of such Iron & Steel products as per the Format enclosed as Form-1 (Annexure-4 of Annexure-VI to ITB).

If Bidder's Quoted Price (Item wise basis) is lower than the threshold value of INR 5 Lakhs, Bidder shall submit a "Declaration of Non-Applicability of DMISP Policy" as per Annexure-3 of Annexure-VI to ITB. In case, at any stage before or after award, if Price of any of the quoted item is found more than INR 5 Lakhs, it shall be construed as the false/wrong declaration and Penal action shall be initiated against the Bidder as per provision of Bidding Document. If such a supplier/ agency happens to be the lowest bidder during price evaluation, the next lowest bidder shall be considered as L1.

For the purpose of this Policy, the threshold value INR 5 lakhs shall be considered on Item wise basis excluding GST & freight. In all cases where evaluation is on bottom line basis for each individual group, threshold value shall be considered on the basis of individual item of the respective group.

33.2 Domestic manufacturers of Iron and Steel products under Appendix-A and Appendix-B shall submit duly filled / certified Form-1 (Annexure-4 of Annexure-VI to ITB), at the time of bidding.

33.3 Bidders who are selling agents/authorized distributors/authorized dealers/authorized supply houses of the domestic manufacturers of iron & steel products, covered by Appendix-A, are eligible to bid

with self-certification on behalf of the domestic manufacturers under the policy, subject to the bidder furnishing an authorisation certificate issued by the domestic manufacturer at the time of delivery.

33.4 Bidder(s) to furnish affidavit as per Form-1 (Annexure-4 of Annexure-VI to ITB) at the time of delivery. Bidder to submit an undertaking to this effect as per Annexure-2 of Annexure-VI to ITB w.r.t compliance of this DMI&SP Policy. Compliance towards certification of Form-1 (Annexure-4 of Annexure-VI to ITB) shall be as stipulated at 33.2 and 33.3 above.

33.5 For products covered under Appendix B of the DMI&SP policy, the bidder shall furnish certification issued by the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) declaring that the capital goods to be used in iron & steel industry are domestically manufactured in terms of the domestic value addition prescribed.

33.6 If a bidder does not submit above affidavit or undertaking as per format, the offer of bidder shall be rejected.

33.7 In case of detection of mis-declaration by the bidder of the prescribed declaration, in the tender document, at any stage before or after award, the following actions shall be taken by the procuring company:

a. Rejection of bid and Forfeiture of EMD or Forfeiture of CPBG depending upon the stage of detection.

b. Banning of business dealings in line with the EIL extant policy.

33.8 A supplier debarred by any procuring entity for violation of this Order shall not be eligible for preference under this Order for procurement by any other procuring entity for the duration of the debarment. The debarment for such other procuring entities shall take effect prospectively from the date on which it comes to the notice of other procurement entities.

A declaration shall be submitted by the bidder in the bid for the above.

34.0 OPENING OF PRICE BID

34.1 Priced Bid (Part-III) of only those bidders whose bids is determined to be technically and commercially acceptable by EIL shall be opened. Bidders selected for opening of their priced bids shall be informed about the date, time and place of price bid opening. Priced Bids shall be opened on the E-Tendering Portal. Since, on e-tendering portal participating Bidders can view the Bid opening details online at their respective places, the Priced Bids opened online shall be deemed as public opening and the Bidders' representatives shall not be called for attending the bid opening process.

35.0 CORRECTION OF ARITHMETICAL ERRORS

35.1 EIL shall correct arithmetical errors on the following basis:

The prices quoted by bidders shall be checked for arithmetic correction, if any, based on percentage in figures and words filled by the bidder in the SOR/price schedule formats. If some discrepancies are found between the percentage in figures/words, the total amount shall be corrected as per the following procedure, which shall be binding upon the bidder:

a. Where bids are invited on + or – percentage over the EIL estimated contract price and there is a discrepancy in the percentage increase / decrease quoted in figures and in words, the percentage increase / decrease quoted in words shall prevail.

b. In case "+" or "-" not indicated against the % figure and also no amount is quoted, then the '+' shall be considered for the % figure.

c. In case the bidder left the % & amount as blank, then % increase/decrease shall be considered as NIL.

35.2 Bidders shall be requested to accept correction of arithmetical errors. Failure to accept the correction in accordance with Clause 35.1 of ITB, shall result in the rejection of the Bid and Bid Security shall be forfeited.

36.0 DELETED

37.0 EVALUATION AND COMPARISON OF PRICE BIDS

37.1 EIL shall compare the price bids based on the evaluation methodology and loading criteria, if any, provided in BDS to determine the lowest evaluated bid.

38.0 EIL'S RIGHT TO ACCEPT ANY BID, AND TO REJECT ANY OR ALL BIDS

38.1 EIL reserves the right to accept or reject any or all the bids at his discretion and may annul the Bidding process, without thereby incurring any liability to affected Bidder or Bidders or without any obligation to inform the affected Bidder or Bidders of the grounds or the reasons for EIL's action.

F AWARD OF CONTRACT

39.0 AWARD CRITERIA

39.1 Subject to Clause 38.1 of ITB, the EIL shall award the Contract to the bidder who has been determined to be the lowest evaluated bid as per methodology defined in Sl. No.14 of Bid Data Sheet (BDS). However, if in the opinion of EIL, the total price or certain item rates quoted by the lowest evaluated bidder are considered high, EIL may invite such bidder for price negotiation. Lowest quoted bidder shall attend such negotiation meetings and if requested by EIL shall provide the analysis of rates/break-up of amount quoted by him for any or all items of Schedule of Rates/ Prices to demonstrate the reasonability. As a result of negotiation, bidder may offer rebate on his earlier quoted Price.

40.0 NOTIFICATION OF AWARD

40.1 Prior to the expiration of the period of bid validity, EIL shall notify the successful bidder, in writing by Letter of Acceptance (LOA)/Detailed Letter of Acceptance (DLOA), that its bid has been accepted.

40.2 Until a formal contract is prepared and executed, the Letter of Acceptance (LOA)/Detailed Letter of Acceptance (DLOA) along with this Bidding Document together with the annexed documents, modifications, deletions agreed upon by the EIL, shall constitute a binding contract between the successful bidder and the EIL.

41.0 SIGNING OF CONTRACT

41.1 Promptly upon issue of LOA, the successful bidder shall sign, the Contract Agreement on a non-judicial stamp paper, purchased from Haryana, and of appropriate value (not less than INR 200/-). The cost of non-judicial stamp paper shall be borne by the successful bidder.

41.2 The Contract document shall consist of the following:

i) Original Bidding Document along with its enclosures issued.
ii) Amendment/Corrigendum to original Bidding Document issued, if any.
iii) Integrity Pact and Undertaking w.r.t. section V of integrity pact.

iv) Letter of Acceptance.
v) Detailed letter of Award/Acceptance along with enclosures attached therewith.
vi) Contract Agreement.

42.0 CONTRACT PERFORMANCE BANK GUARANTEE / SECURITY DEPOSIT

42.1 Within fifteen (15) days of the issue of LOA from EIL, the successful bidder shall comply with the requirement of Contract Performance Bank Guarantee / Security Deposit as per SCC (Special Conditions of Contract).

42.2 Failure of the successful bidder to submit the above-mentioned Contract Performance Bank Guarantee / Security Deposit or sign the Contract shall constitute sufficient grounds for the annulment of the award and forfeiture of the bid security.

43.0 PURCHASE PREFERENCE UNDER PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII) ORDER, 2017

43.1 MoP&NG vide File no. FP-20013/2/2017-FP-PNG-Part(4)(E-41432) dated 26.04.2022, have issued a directive that **Public Procurement (Preference to Make in India) (PPP-MII) Order, 2017** issued by DPIIT and as amended from time to time shall be applicable with effect from 01.04.2022.

Hence, following documents and its amendment thereof has been made integral part of the subject enquiry/bidding document:

i. **PPP-MII Policy O.M. No. P-45021/2/2017-PP (BE-II)-Part(4) Vol. II dated 19.07.2024** issued by DPIIT,

ii. **MoPNG O.M. File No. FP-20013/2/2017-FP-PNG-Part(4)(E-41432)** dated 26.04.2022 and 26.03.2024,

iii. **File No. W-43/4/2019-IPH-W MeitY dated 07.09.2020** and **S.O. No. 4591(E) dated 12.10.2023** issued by MeitY

iv. File No.1(10)/2017-CLES dated 06.12.2019 issued by Meity.

v. File No FP-18-10/2017-IP dated 21.10.2024 issued by Ministry of Telecommunication

The above referred documents are enclosed under **Appendix-IV** to ITB. **However, sl. no. iii, iv & v above are not applicable for this tender**

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Instructions for Online Bid Submission

(Department User may attach this Document as an Annexure in their Tender Document which provides complete Instructions for on line Bid submission for Bidders)

The bidders are required to submit soft copies of their bids electronically on the CPP Portal, using valid Digital Signature Certificates. The instructions given below are meant to assist the bidders in registering on the CPP Portal, prepare their bids in accordance with the requirements and submitting their bids online on the CPP Portal.

More information useful for submitting online bids on the CPP Portal may be obtained at: https://eprocure.gov.in/eprocure/app**.**

REGISTRATION

1) Bidders are required to enroll on the e-Procurement module of the Central Public Procurement Portal (URL: https://eprocure.gov.in/eprocure/app) by clicking on the link "**Online bidder Enrollment**" on the CPP Portal which is free of charge.
2) As part of the enrolment process, the bidders will be required to choose a unique username and assign a password for their accounts.
3) Bidders are advised to register their valid email address and mobile numbers as part of the registration process. These would be used for any communication from the CPP Portal.
4) Upon enrolment, the bidders will be required to register their valid Digital Signature Certificate (Class III Certificates with signing key usage) issued by any Certifying Authority recognized by CCA India (e.g. Sify / nCode / eMudhra etc.), with their profile.
5) Only one valid DSC should be registered by a bidder. Please note that the bidders are responsible to ensure that they do not lend their DSC's to others which may lead to misuse.
6) Bidder then logs in to the site through the secured log-in by entering their user ID / password and the password of the DSC / e-Token.

SEARCHING FOR TENDER DOCUMENTS

1) There are various search options built in the CPP Portal, to facilitate bidders to search active tenders by several parameters. These parameters could include Tender ID, Organization Name, Location, Date, Value, etc. There is also an option of advanced search for tenders, wherein the bidders may combine a number of search parameters such as Organization Name, Form of Contract, Location, Date, Other keywords etc. to search for a tender published on the CPP Portal.
2) Once the bidders have selected the tenders they are interested in, they may download the required documents / tender schedules. These tenders can be moved to the respective 'My Tenders' folder. This would enable the CPP Portal to intimate the bidders through SMS / e-mail in case there is any corrigendum issued to the tender document.
3) The bidder should make a note of the unique Tender ID assigned to each tender, in case they want to obtain any clarification / help from the Helpdesk.

PREPARATION OF BIDS

1) Bidder should take into account any corrigendum published on the tender document before submitting their bids.

2) Please go through the tender advertisement and the tender document carefully to understand the documents required to be submitted as part of the bid. Please note the number of covers in which the bid documents have to be submitted, the number of documents - including the names and content of each of the document that need to be submitted. Any deviations from these may lead to rejection of the bid.

3) Bidder, in advance, should get ready the bid documents to be submitted as indicated in the tender document / schedule and generally, they can be in PDF / XLS / RAR / DWF/JPG formats. Bid documents may be scanned with 100 dpi with black and white option which helps in reducing size of the scanned document.

4) To avoid the time and effort required in uploading the same set of standard documents which are required to be submitted as a part of every bid, a provision of uploading such standard documents (e.g. PAN card copy, annual reports, auditor certificates etc.) has been provided to the bidders. Bidders can use "My Space" or ''Other Important Documents'' area available to them to upload such documents. These documents may be directly submitted from the "My Space" area while submitting a bid, and need not be uploaded again and again. This will lead to a reduction in the time required for bid submission process.

Note: *My Documents space is only a repository given to the Bidders to ease the uploading process. If Bidder has uploaded his Documents in My Documents space, this does not automatically ensure these Documents being part of Technical Bid.*

SUBMISSION OF BIDS

1) Bidder should log into the site well in advance for bid submission so that they can upload the bid in time i.e. on or before the bid submission time. Bidder will be responsible for any delay due to other issues.

2) The bidder has to digitally sign and upload the required bid documents one by one as indicated in the tender document.

3) Bidder has to select the payment option as "offline" to pay the tender fee / EMD as applicable and enter details of the instrument.

4) Bidder should prepare the EMD as per the instructions specified in the tender document. The original should be posted/couriered/given in person to the concerned official, latest by the last date of bid submission or as specified in the tender documents. The details of the DD/any other accepted instrument, physically sent, should tally with the details available in the scanned copy and the data entered during bid submission time. Otherwise the uploaded bid will be rejected.

5) Bidders are requested to note that they should necessarily submit their financial bids in the format provided and no other format is acceptable. If the price bid has been given as a standard BoQ format with the tender document, then the same is to be downloaded and to be filled by all the bidders. Bidders are required to download the BoQ file, open it and complete the white coloured (unprotected) cells with their respective financial quotes and other details (such as name of the bidder). No other cells should be changed. Once the details have been completed, the bidder should save it and submit it online, without changing the filename. If the BoQ file is found to be modified by the bidder, the bid will be rejected.

6) The server time (which is displayed on the bidders' dashboard) will be considered as the standard time for referencing the deadlines for submission of the bids by the bidders, opening of bids etc. The bidders should follow this time during bid submission.

7) All the documents being submitted by the bidders would be encrypted using PKI encryption techniques to ensure the secrecy of the data. The data entered cannot be viewed by unauthorized persons until the time of bid opening. The confidentiality of the bids is maintained using the secured Socket Layer 128 bit encryption technology. Data storage encryption of sensitive fields is done. Any bid document that is uploaded to the server is subjected to symmetric encryption using a system generated symmetric key. Further this key is subjected to asymmetric encryption using buyers/bid opener's public keys. Overall, the uploaded tender documents become readable only after the tender opening by the authorized bid openers.

7) The uploaded tender documents become readable only after the tender opening by the authorized bid openers.

8) Upon the successful and timely submission of bids (i.e. after Clicking "Freeze Bid Submission" in the portal), the portal will give a successful bid submission message & a bid summary will be displayed with the bid no. and the date & time of submission of the bid with all other relevant details.

9) The bid summary has to be printed and kept as an acknowledgement of the submission of the bid. This acknowledgement may be used as an entry pass for any bid opening meetings.

ASSISTANCE TO BIDDERS

1) Any queries relating to the tender document and the terms and conditions contained therein should be addressed to the Tender Inviting Authority for a tender or the relevant contact person indicated in the tender.

2) Any queries relating to the process of online bid submission or queries relating to CPP Portal in general may be directed to the 24x7 CPP Portal Helpdesk.

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ANNEXURE-IV

TO

ITB

[POLICY FOR PUBLIC PROCUREMENT (PREFERENCE TO MAKE IN INDIA) (PPP-MII)]

Annexure-2

FORM – 2

SELF CERTIFICATION BY BIDDER UNDER PPP-MII ORDER, 2017

To

M/s _____ <Insert name of Client>

NAME OF WORK / ITEM:

TENDER /RFQ NO. :

Dear Sir,

We, M/s _____ *<Name of Bidder>* hereby confirm that we meet the mandatory minimum requirement of Local Content (LC) for **Class-I local supplier / Class-II local supplier** *(strike out which is not applicable)* under Public Procurement (Preference to Make in India), Order 2017 (PPP-MII, 2017) and the work / Item shall have **LC of** _____**%.**

The details of the location(s) at which the local value addition is/shall be made, is/ areas under:

.....
.....
.....

We confirm compliance of Public Procurement (Preference to Make in India) (PPP-MII) Order 2017, vide Order No P-45021/2/2017-PP(BE-II)-Part-4)Vol.II, Notifications with respect to Electronics Products [File No. W-43/4/2019-IPHW-Meity dated 07.09.2020 and S.O. No 4591(E) dated 12.10.2023 issued by Meity], Cyber Security Products [File No.1(10)/2017-CLES dated 06.12.2019 issued by Meity] and Telecom Products [File No FP-18-10/2017-IP dated 21.10.2024 issued by Ministry of Telecommunication]. {Strike out which is not applicable}.

We also confirm that, the imported items sourced locally from resellers/distributors are excluded from calculation of local content. The cost of such locally sourced imported items (inclusive of taxes) along with break up on license/royalties paid/technical expertise etc. sourced from outside India shall be submitted at the time of execution as per Form-2A.

We further confirm that in case we fail to meet the minimum local content/domestic value addition, the same shall be treated as false information and Owner reserves the right to take appropriate action for debarment, Penalty after award etc. as per provision of the PPP-MII Order, 2017 and its subsequent Amendments and as more specifically mentioned in the Bidding/ RFQ document.

We also confirm that we are not debarred by any other procuring entity (GOI/PSU/PSE etc.)
or

Our debarment period is completed as on _____ <insert date>, and as such we are eligible to avail purchase preference under this Order.
(## Strike out which is not applicable)

_____
Signature of Bidder

Place:

Name :

Date:

Designation

Seal :

FORM-2A

DETAILS OF IMPORTED COMPONENTS SOURCED FROM RESELLERS/DISTRIBUTORS EXCLUDED UNDER LOCAL CONTENT

RFQ/TENDER No:

ITEM/WORKS DESCRIPTION:

S. No	Cost component	Cost in INR (Refer Note-2)
a.	Locally-sourced imported items from resellers/distributors (inclusive of taxes)	i. ii. iii. iv.
b.	License/Royalties paid/ Technical Expertise cost etc. for the items sourced from outside India i. License ii. Royalties Paid iii. Technical Expertise Cost iv. other	 i. ii. iii. iv.
	DETAILS OF ITEMS SOLD BY BIDDER AS RESELLER	
c.	Details of Items	OEM Certificate for country of origin
	i. ii. iii. iv.	i. ii. iii. iv.

Note –

1. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.
2. As regards cases where currency for above is other than Indian Rupee, exchange rate prevailing on the Bid Due Date shall be considered for the calculation of Local Content.
3. Bidder to enclose OEM Certificate for country of origin as specified in S. No (c) above.

	Signature of Bidder
Place:	Name :
Date:	Designation
	Seal :

ANNEXURE-3

FORM – 3

(FOR CLASS-I LOCAL SUPPLIER/ CLASS-II LOCAL SUPPLIER HAVING VALUE OF PROCUREMENT MORE THAN INR 10 CRORE)

CERTIFICATE UNDER PPP-MII ORDER, 2017 TOWARDS MANDATORY MINIMUM LOCAL CONTENT

To
M/s _____ <Insert name of Client/Owner>

NAME OF WORK / ITEM:

TENDER /RFQ NO.:

Dear Sir,

We, _____, the Statutory Auditor or Cost Auditor of the Company (in case of Companies) or are a practicing Cost Accountant or practicing Chartered Accountant (in respect of supplier other than companies) of M/s. _____ *<Name of Bidder>*, hereby certify that as per definition specified in above policy, M/s. _____ *<Name of Bidder>* is a Class-I Local Supplier / Class-II Local Supplier <as applicable>

We further confirm that M/s _____ *<Name of Bidder>* meet the mandatory minimum Local content requirement specified for Class-I Local supplier/ Class-II Local supplier <as applicable> under Policy for Public Procurement (Preference to Make in India), Order 2017 (PPP-MII) for their offer for the abovementioned Work/ Item and shall have local content of _____% .

The details of the location(s) at which the local value addition is/shall be made, is/ areas under:

.....
.....

We confirm compliance of Public Procurement (Preference to Make in India) (PPP-MII) Order 2017, vide Order No P-45021/2/2017-PP(BE-II)-Part-4)Vol.II, Notifications with respect to Electronics Products [File No. W-43/4/2019-IPHW-Meity dated 07.09.2020 and S.O. No 4591(E) dated 12.10.2023 issued by Meity], Cyber Security Products [File No.1(10)/2017-CLES dated 06.12.2019 issued by Meity] and Telecom Products [File No FP-18-10/2017-IP dated 21.10.2024 issued by Ministry of Telecommunication]. ***{Strike out which is not applicable}.***

We also confirm that, the imported items sourced locally from resellers/distributors are excluded from calculation of local content. The cost of such locally sourced imported items (inclusive of taxes) along with break up on license/royalties paid/technical expertise etc. sourced from outside India is enclosed as Form-3A.

We also confirm that M/s _____ <Name of Bidder> is not debarred by any other procuring entity (GOI/PSU/PSE etc.).
OR
M/s _____<Name of Bidder>'s debarment period is completed as on _____<insert date>, and as such M/s _____ <Name of Bidder> is eligible to availed purchase preference under this Order.
(Strike out which is not applicable)

_____
Signature of certificate issuing authority

Place:

Name :

Date:

Name of Audit Firm:

Designation

Seal :

FORM-3A

DETAILS OF IMPORTED COMPONENTS SOURCED FROM RESELLERS/DISTRIBUTORS EXCLUDED UNDER LOCAL CONTENT

RFQ/TENDER No:

ITEM/WORKS DESCRIPTION:

S. No	Cost component	Cost in INR (Refer Note-2)
a.	Locally-sourced imported items from resellers/distributors (inclusive of taxes)	i. ii. iii.
b.	License/Royalties paid/ Technical Expertise cost etc. for the items sourced from outside India i. License ii. Royalties Paid iii. Technical Expertise Cost iv. other	 i. ii. iii. iv.
DETAILS OF ITEMS SOLD BY BIDDER AS RESELLER		
c.	Details of Items	OEM Certificate for country of origin
	i. ii. iii.	i. ii. iii.

Note –

1. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.
2. As regards cases where currency for above is other than Indian Rupee, exchange rate prevailing on the Bid Due Date shall be considered for the calculation of Local Content.
3. Bidder to enclose OEM Certificate for country of origin as specified in S. No (c) above.
4. The above formats are indicative, the statutory auditor/Cost auditor/Chartered Accountant/ Cost Accountant can modify the format without changing the intent of certification.

_____

Signature of certificate issuing authority

Place:

Name:

Date:

Name of Audit Firm:

Designation

Seal:

Form -2B

Format for Self-Certification regarding Local Content (LC) for Telecom Product, Services or Works to be submitted on non-judicial stamp paper of the value Rs. 100/-

Date:

I__ _____S/o, D/o, W/o, Resident of _____ do hereby solemnly affirm and declare as under:

That I agree to abide by the terms and conditions of Department of Telecommunications, Government of India issued vide Notification No:_____ dated_____.

That the information furnished hereinafter is correct to the best of my knowledge and belief and I undertake to produce relevant records before the procuring entity or any other authority so nominated by the Department of Telecommunications, Government of India for the purpose of assessing the LC.

That the LC for all inputs which constitute the said Telecom Product/Services/Works has been verified by me and I am responsible for the correctness of the claims made therein.

That in the event of the LC of the Telecom Product/Services/Works mentioned herein is found to be incorrect and not meeting the prescribed LC norms, based on the assessment of an authority so nominated by the Department of Telecommunications, Government of India, I and my Statutory auditor or cost auditor (if applicable) will be liable for actions as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024 for all incorrect/false facts and figures.

I agree to maintain detailed breakup / information (separately for each product) to substantiate my claim for LC in the Company's record for a period of 2 years and shall make this available for verification to any authority. I shall also maintain records of local content pertaining to items bought from other domestic manufacturers / traders.

[Please provide following information]

i	Name and details of the local supplier - Registered Office, Manufacturing unit location, nature of legal entity
ii	Date of certificate issuance - Date on which this certificate is issued
iii	Telecom Product/Services/Works - Telecom Product/Services/Works for which the certificate is produced
iv	Procuring agency - Procuring agency to whom the certificate is furnished
v	Percentage of Local Content claimed - Percentage of LC claimed
vi	Manufacturer unit details - Name and contact details of the unit of the manufacturer
vii	Sale Price of the product - Sale Price of the product
viii	Ex-Factory Price of the product - Ex-Factory Price of the product
ix	Freight, insurance and handling - Freight, insurance and handling charges
x	Total Bill of Material - Total Bill of Material

xi	Local inputs cost - List and total cost value of inputs used for manufacture of the Telecom product/Services/Works
xii	Locally sourced inputs - List and total cost of inputs which are locally sourced. Please attach LC certificates from local suppliers, if the input is not produced in-house
xiii	Imported inputs cost - List and cost of inputs which are imported, directly or indirectly

I hereby certify that, having read all the provisions of the above order and principles / basis of calculations, the local content calculation does not include the following:

a. Imported items sourced locally from resellers/distributors.

b. The license fees / royalties paid/ technical charges paid out of India

c. Procurement / supply of repackaged / refurbished/rebranded imported products

I hereby also certify to the best of my knowledge and belief that all the particulars furnished above are correct and complete. I agree to comply with the terms and conditions of the DPIIT PPP-MII order dated 19.07.2024 and DoT PPPMII Notification dated……...

I understand that any incorrect declaration regarding the local content or failure to substantiate the claim of LC will result in penalties as specified in Clause (9) of the DPIIT PPP-MII Order dated 19.07.2024.

I further certify and take personal responsibility that I have applied my mind to the calculations and principles of LC as specified in this order and I shall, having declared the LC shall not seek recourse to change it on any ground. Any changes made by me on any grounds in a bid in LC after bid submission shall make my bid non-responsive and I shall hold myself liable for civil/criminal action arising out of any such change. I understand and agree that any such post bid change in LC content shall also be a valid ground for blacklisting of the firm from future contracts/bids.

Signature:
Name:
Designation: CEO/MD
Address:
Email Address:
Mobile No.:
Place:
Date:

Form-2C

Format for Self-Declaration regarding local supplier' for Cyber Security Products

This is to Certify that the organization_____ registered as_____with registration number_____ do hereby solemnly affirm and declare as under:

That we agree to abide by the terms and conditions of the Notification issued by Ministry of Electronics and Information Technology (MeitY), Government of India no: _____dated_____.

That the information furnished hereinafter is correct and we undertake to produce relevant records before the procuring entity or any other authority so nominated by the Ministry of Electronics and Information Technology (MeitY), Government of India for the purpose of establishing ownership of the Intellectual Property Rights(IPR), legal existence and revenue accrual, local content for the cyber security products nominated by the aforesaid organization.

That all IPR which constitute the said cyber security product has been verified by us and we are responsible for the correctness of the claims made therein and we take complete responsibility of the same.

We agree to maintain all information regarding our claim(s) for IPR ownership, legal existence and revenue accrual, local content in the organization's record throughout the existence of the product and shall make this available for verification to any authorities specified by Government of India.

In case of any change in the IPR ownership, legal existence and revenue accrual, local content we will be accountable to inform Ministry of Electronics and Information Technology, Government of India within one week or before applying for any public procurement or before referring this order for taking any advantage which so ever occurs first.

That in the event of the cyber security product mentioned herein is found to be incorrect and not meeting the prescribed norms, based on the assessment of an authority so nominated by the MeitY, Government of India and we will be liable as under clause 7 (f) of Public Procurement (Preference to Make in India) Order 2019 for cyber security product.

1. Name and details of the organization nominating product under this order (Registered Office, Manufacturing unit location, nature of legal entity)

2. Entity Registration Certificate number
   a. Type of registration

3. Date on which this certificate is issued

4. Percentage of Royalty/License fee to be paid to other entity with respect to estimated cost of the product

5. Name and contact details of the unit of the manufacturer

For and on behalf of_____ (Name of firm/entity)

Authorize signatory (To be duly authorized by the Board of Directors)

FORM – 2D

CERTIFICATE UNDER DOMESTICALLY MANUFACTURED/PRODUCED CYBER SECUIRTY PRODUCTS

(HAVING VALUE OF PROCUREMENT MORE THAN INR 10 CRORE)

To
M/s _____ <Insert name of Client/Owner>

NAME OF WORK / ITEM:

TENDER /RFQ NO.:

Dear Sir,

We, _____, the Statutory Auditor or Cost Auditor of the Company (in case of Companies) or are a practicing Cost Accountant or practicing Chartered Accountant (in respect of supplier other than companies) of M/s. _____ <*Name of Bidder*>, hereby certify offered product(s) by M/s _____ <*Name of Bidder*> meets the definition of 'local supplier' of domestically manufactured/produced Cyber Security Products as per para 4 of Public Procurement (Preference to Make in India) Order 2019 for Cyber Security Products.

_____
Signature of certificate issuing authority

Place:

Name :

Date:

Name of Audit Firm:

Designation

Seal :

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No. P-45021/2/2017-PP (BE-II)-Part(4)Vol.II
Government of India
Ministry of Commerce and Industry
Department for Promotion of Industry and Internal Trade
(Public Procurement Section)

Vanijya Bhawan, New Delhi
Dated: 19 July,2024

To

All Central Ministries/Departments/CPSUs/All concerned

ORDER

Subject: Public Procurement (Preference to Make in India), Order 2017– Revision; regarding.

Department for Promotion of Industry and Internal Trade, in partial modification [Paras 2, 3, 5, 10 & 13] of Order No.P-45021/2/2017-B.E.-II dated 15.6.2017 as amended by Order No.P-45021/2/2017-B.E.-II dated 28.05.2018, Order No.P-45021/2/2017-B.E.-II dated 29.05.2019, Order No.P-45021/2/2017-B.E.-II dated 04.06.2020 and Order No.P-45021/2/2017-B.E.-II dated 16.09.2020 hereby issues the revised 'Public Procurement (Preference to Make in India), Order 2017" dated 19.07.2024 effective with immediate effect.

Whereas it is the policy of the Government of India to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment, and

Whereas procurement by the Government is substantial in amount and can contribute towards this policy objective, and

Whereas local content can be increased through partnerships, cooperation with local companies, establishing production units in India or Joint Ventures (JV) with Indian suppliers, increasing the participation of local employees in services and training them,

Now therefore the following Order is issued:

1. This Order is issued pursuant to Rule 153 (iii) of the General Financial Rules 2017.
2. **Definitions**: For the purposes of this Order:
   'Local content' means the amount of value added in India which shall, unless otherwise prescribed by the Nodal Ministry, be the total value of the item procured (excluding net domestic indirect taxes) minus the value of imported content in the item (including all customs duties) as a proportion of the total value, in percent.

Explanatory notes for calculation of local content given above

a. Imported items sourced locally from resellers/distributors shall be excluded from calculation of local content.
b. The license fees/royalties paid/ technical charges paid out of India shall be excluded from local content calculation.

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c. Procurement/Supply of repackaged/refurbished/rebranded imported products as understood commonly shall be treated as reselling of imported products and shall be excluded from calculation of local content. The definition of repackaged/refurbished/rebranded imported products is as follows;

'Refurbishing' means repair or reconditioning of an imported product does not amount to manufacture because no new goods come into existence.

'Repackaging' means repacking of imported goods from bulk pack to smaller packs would not ordinarily amount to manufacture of a new item.

'Rebranding' means relabeling or renaming or change in symbol or logo/makes or corporate image of a company/organization/ firm for an imported product would amount to rebranding.

d. To ensure that imported items sourced locally from resellers/distributors are excluded from calculation of local content, procuring entities to obtain from bidders, the cost of such locally-sourced imported items (Inclusive of taxes) along with break-up on license/royalties paid/technical expertise cost etc. sourced from outside India. For items sold by bidder as reseller, OEM certificate for country of origin to be submitted.

e. For contracts involving supply of multiple items, weighted average of all items to be taken while calculating the local content.

'*Class-I local supplier*' means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-I local supplier' under this Order.

'Class-II local supplier' means a supplier or service provider, whose goods, services or works offered for procurement, meets the minimum local content as prescribed for 'Class-II local supplier' but less than that prescribed for 'Class-I local supplier' under this Order.

'Non - Local supplier' means a supplier or service provider, whose goods, services or works offered for procurement, has local content less than that prescribed for 'Class-II local supplier' under this Order.

'L1' means the lowest tender or lowest bid or the lowest quotation received in a tender, bidding process or other procurement solicitation as adjudged in the evaluation process as per the tender or other procurement solicitation.

'Margin of purchase preference' means the maximum extent to which the price quoted by a "Class-I local supplier" may be above the L1 for the purpose of purchase preference.

'Nodal Ministry' means the Ministry or Department identified pursuant to this order in respect of a particular item of goods or services or works.

'Procuring entity' means a Ministry or department or attached or subordinate office of, or autonomous body controlled by, the Government of India and includes Government companies as defined in the Companies Act.

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'Works' means all works as per Rule 130 of GFR- 2017, and will also include *'turnkey works'*.

2A. *Special treatment for items covered under PLI Scheme*

The manufacturers manufacturing an item under PLI scheme shall be treated as deemed Class II local supplier for that item unless they have minimum local content equal to or higher than that notified for Class-I local supplier for that item, provided the manufacturer has received incentive from the concerned PLI Ministry for the item. The above shall be applicable for the specific time period only, as notified by concerned PLI Ministry.

3. Eligibility of 'Class-I local supplier'/ 'Class-II local supplier'/ 'Non-local suppliers' for different types of procurement

(a) In procurement of all goods, services or works in respect of which the Nodal Ministry / Department has communicated that there is sufficient local capacity and local competition, only 'Class-I local supplier', as defined under the Order, shall be eligible to bid irrespective of purchase value.

(b) Only 'Class-I local supplier' and 'Class-II local supplier', as defined under the Order, shall be eligible to bid in procurement undertaken by procuring entities, except when Global tender enquiry has been issued. In global tender enquiries, 'Non-local suppliers' shall also be eligible to bid along with 'Class-I local suppliers' and 'Class-II local suppliers'. In procurement of all goods, services or works, not covered by sub-para 3(a) above, and with estimated value of purchases less than Rs. 200 Crore, in accordance with Rule 161(iv) of GFR, 2017, Global tender enquiry shall not be issued except with the approval of competent authority as designated by Department of Expenditure.

(c) For the purpose of this Order, works includes Engineering, Procurement and Construction (EPC) contracts and services include System Integrator (SI) contracts.

3.1 Mandatory sourcing of items, with sufficient local capacity and competition, from Class-I local suppliers in SI/EPC/Turnkey Contracts/Service Tenders

a. The items, notified as having sufficient local capacity and competition, shall mandatory be sourced from Class-I local suppliers in SI/EPC/Turnkey Contracts/ Services tenders. This provision will be applicable only for those items which have been notified by the Nodal Ministry as Class I i.e. having sufficient local capacity and competition, with specific HSN codes."

b. Notwithstanding above, if in any project, it is considered that it is not practically feasible to source such items from Class I local suppliers, it may take relaxation from such stipulation with the approval of Secretary of the administrative Ministry/ Department concerned or with the approval of the Competent Authority specified by the Administrative Ministry/Department, on case-specific basis.

3A. Purchase Preference

(a) Subject to the provisions of this Order and to any specific instructions issued by the Nodal Ministry or in pursuance of this Order, purchase preference shall be given to 'Class-I local supplier' in procurement undertaken by procuring entities in the manner specified here under.

(b) In the procurement of goods or works, which are covered by para 3(b)

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above and which are divisible in nature, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is 'Class-I local supplier', the contract for full quantity will be awarded to L1.
ii. If L1 bid is not a 'Class-I local supplier', 50% of the order quantity shall be awarded to L1. Thereafter, the lowest bidder among the 'Class-I local supplier' will be invited to match the L1 price for the remaining 50% quantity subject to the Class-I local supplier's quoted price falling within the margin of purchase preference, and contract for that quantity shall be awarded to such 'Class-I local supplier' subject to matching the L1 price. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price or accepts less than the offered quantity, the next higher 'Class-I local supplier' within the margin of purchase preference shall be invited to match the L1 price for remaining quantity and so on, and contract shall be awarded accordingly. In case some quantity is still left uncovered on Class-I local suppliers, then such balance quantity may also be ordered on the L1 bidder.

(c) In the procurement of goods or works, which are covered by para 3(b) above and which are not divisible in nature, and in procurement of services where the bid is evaluated on price alone, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

i. Among all qualified bids, the lowest bid will be termed as L1. If L1 is Class -I local supplier', the contract will be awarded to L1.
ii. If L1 is not 'Class-I local supplier', the lowest bidder among the 'Class-I local supplier', will be invited to match the L1 price subject to Class-I local supplier's quoted price falling within the margin of purchase preference, and the contract shall be awarded to such 'Class-I local supplier' subject to matching the L1 price.
iii. In case such lowest eligible 'Class-I local supplier' fails to match the L1 price, the 'Class-I local supplier' with the next higher bid within the margin of purchase preference shall be invited to match the L1 price and so on and contract shall be awarded accordingly. In case none of the 'Class-I local supplier' within the margin of purchase preference matches the L1 price, the contract may be awarded to the L1 bidder.

(d) "Class-II local supplier" will not get purchase preference in any procurement, undertaken by procuring entities.

3B. Applicability in tenders where contract is to be awarded to multiple bidders- In tenders where contract is awarded to multiple bidders subject to matching of L1 rates or otherwise, the 'Class-I local supplier' shall get purchase preference over 'Class-II local supplier' as well as 'Non-local supplier', as per following procedure:

a. In case there is sufficient local capacity and competition for the item to be procured, as notified by the nodal Ministry, only Class I local suppliers shall be eligible to bid. As such, the multiple suppliers, who would be awarded the contract, should be all and only 'Class I Local suppliers'.
b. In other cases, 'Class II local suppliers' and 'Non local suppliers' may also participate in the bidding process along with 'Class I Local suppliers' as per provisions of this Order.
c. If 'Class I Local suppliers' qualify for award of contract for at least

50% of the tendered quantity in any tender, the contract may be awarded to all the qualified bidders as per award criteria stipulated in the bid documents. However, in case 'Class I Local suppliers' do not qualify for award of contract for at least 50% of the tendered quantity, purchase preference should be given to the 'Class I local supplier' over 'Class II local suppliers'/ 'Non local suppliers' provided that their quoted rate falls within 20% margin of purchase preference of the highest quoted bidder considered for award of contract so as to ensure that the 'Class I Local suppliers' taken in totality are considered for award of contract for at least 50% of the tendered quantity.

d. First purchase preference has to be given to the lowest quoting 'Class-I local supplier', whose quoted rates fall within 20% margin of purchase preference, subject to its meeting the prescribed criteria for award of contract as also the constraint of maximum quantity that can be sourced from any single supplier. If the lowest quoting 'Class-I local supplier', does not qualify for purchase preference because of aforesaid constraints or does not accept the offered quantity, an opportunity may be given to next higher 'Class-I local supplier', falling within 20% margin of purchase preference, and so on.

e. To avoid any ambiguity during bid evaluation process, the procuring entities may stipulate its own tender specific criteria for award of contract amongst different bidders including the procedure for purchase preference to 'Class-I local supplier' within the broad policy guidelines stipulated in sub- paras above.

4. **Exemption of small purchases**: Notwithstanding anything contained in paragraph 3, procurement where the estimated value to be procured is less than Rs. 5 lakhs shall be exempt from this Order. However, it shall be ensured by procuring entities that procurement is not split for the purpose of avoiding the provisions of this Order.

4A. Exemption in sourcing of spares and consumables of closed systems:

Procurement of spare parts, consumables for closed systems and Maintenance/ Service contracts with Original Equipment Manufacturer/Original Equipment Supplier/Original Part Manufacturer shall be exempted from this Order.

5. **Minimum local content**: The 'local content' requirement to categorize a supplier as 'Class-I local supplier' is minimum 50%. For 'Class-II local supplier', the 'local content' requirement is minimum 20%. Nodal Ministry/ Department may prescribe only a higher percentage of minimum local content requirement to categorize a supplier as 'Class-I local supplier'/ 'Class- II local supplier'. For the items, for which Nodal Ministry/ Department has not prescribed higher minimum local content notification under the Order, it shall be 50% and 20% for 'Class-I local supplier'/ 'Class-II local supplier' respectively.

6. **Margin of Purchase Preference**: The margin of purchase preference shall be 20%.

7. **Requirement for specification in advance**: The minimum local content, the margin of purchase preference and the procedure for preference to Make in India shall be specified in the notice inviting tenders or other form of procurement solicitation and shall not be varied during a particular procurement transaction.

8. **Government E-marketplace**: In respect of procurement through the Government E-marketplace (GeM) shall, as far as possible, specifically mark the items which meet the minimum local content while registering the item for

display, and shall, wherever feasible, make provision for automated comparison with purchase preference and without purchase preference and for obtaining consent of the local supplier in those cases where purchase preference is to be exercised.

9. **Verification of local content**:

a. The 'Class-I local supplier'/ 'Class-II local supplier' at the time of tender, bidding or solicitation shall be required to indicate percentage of local content and provide self-certification that the item offered meets the local content requirement for 'Class-I local supplier'/ 'Class-II local supplier', as the case may be. They shall also give details of the location(s) at which the local value addition is made.

b. In cases of procurement for a value in excess of Rs. 10 crores, the 'Class-I local supplier'/ 'Class-II local supplier' shall be required to provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

c. The bidder shall give self-certification for local content in the quoted item (goods/works/services) at the time of tendering. However, at the time of execution of the project, for all contracts above INR 10 Crore, the contractor/ supplier shall be required to give local content certification duly certified by cost/ chartered accountant in practice. For cases where it is not possible to provide certification by Cost/Chartered Accountant at the time of execution of project, the supplier shall be permitted to provide the certificate for local content from Cost/ Chartered Accountant after completion of the contract, within time limit acceptable to the procuring entity. In case the contractor/ supplier does not meet the stipulated local content requirement and the category of the supplier changes from Class-I to Class-II/ Non-local or from Class-II to Non-local, a penalty upto 10% of the contract value may be imposed. However, contract once awarded shall not be terminated on this account.

d. Decisions on complaints relating to implementation of this Order shall be taken by the competent authority which is empowered to look into procurement-related complaints relating to the procuring entity.

e. Nodal Ministries may constitute committees with internal and external experts for independent verification of self-declarations and auditor's/ accountant's certificates on random basis and in the case of complaints.

f. Nodal Ministries and procuring entities may prescribe fees for such complaints.

g. False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules for which a bidder or its successors can be debarred for up to two years as per Rule 151 (iii) of the General Financial Rules along with such other actions as may be permissible under law.

h. A supplier who has been debarred by any procuring entity for violation of this Order shall not be eligible for preference under this Order for procurement by any other procuring entity for the duration of the debarment. The debarment for such other procuring entities shall take effect prospectively from the date on which it comes to the notice of other procurement entities, in the manner prescribed under paragraph 9

i below.

i. The Department of Expenditure shall issue suitable instructions for the effective and smooth operation of this process, so that:
   i. The fact and duration of debarment for violation of this Order by any procuring entity are promptly brought to the notice of the Member-Convenor of the Standing Committee and the Department of Expenditure through the concerned Ministry /Department or in some other manner;
   ii. On a periodical basis such cases are consolidated and a centralized list or decentralized lists of such suppliers with the period of debarment is maintained and displayed on website(s);
   iii. In respect of procuring entities other than the one which has carried out the debarment, the debarment takes effect prospectively from the date of uploading on the website(s) in the such a manner that ongoing procurement are not disrupted.

10. **Specifications in Tenders and other procurement solicitations**:
   a. Every procuring entity shall ensure that the eligibility conditions in respect of previous experience fixed in any tender or solicitation do not require proof of supply in other countries or proof of exports.
   b. Procuring entities shall endeavour to see that eligibility conditions, including on matters like turnover, production capability and financial strength do not result in unreasonable exclusion of 'Class-I local supplier'/ 'Class-II local supplier' who would otherwise be eligible, beyond what is essential for ensuring quality or creditworthiness of the supplier.
   c. Procuring entities shall, within 2 months of the issue of this Order review all existing eligibility norms and conditions with reference to sub-paragraphs 'a' and 'b' above.
   d. **Reciprocity Clause**
      i. When a Nodal Ministry/Department identifies that Indian suppliers of an item are not allowed to participate and/ or compete in procurement by any foreign government, due to restrictive tender conditions which have direct or indirect effect of barring Indian companies such as registration in the procuring country, execution of projects of specific value in the procuring country etc., it shall provide such details to all its procuring entities including CMDs/CEOs of PSEs/PSUs, State Governments and other procurement agencies under their administrative control and GeM for appropriate reciprocal action.
      ii. Entities of countries which have been identified by the nodal Ministry/Department as not allowing Indian companies to participate in their Government procurement for any item related to that nodal Ministry shall not be allowed to participate in Government procurement in India for all items related to that nodal Ministry/ Department, except for the list of items published by the Ministry/ Department permitting their participation.
      iii. The stipulation in (ii) above shall be part of all tenders invited by the Central Government procuring entities stated in (i) above. All purchases on GeM shall also necessarily have the above provisions for items identified by nodal Ministry/ Department.
      iv. State Governments should be encouraged to incorporate similar provisions in their respective tenders.
      v. The term 'entity' of a country shall have the same meaning as under the FDI Policy of DPIIT as amended from time to time.
   e. Specifying foreign certifications/ unreasonable technical specifications/

brands/ models in the bid document is restrictive and discriminatory practice against local suppliers. If foreign certification is required to be stipulated because of non-availability of Indian Standards and/or for any other reason, the same shall be done only after written approval of Secretary of the Department concerned or any other Authority having been designated such power by the Secretary of the Department concerned.

f. "All administrative Ministries/Departments *whose procurement exceeds Rs. 1000 Crore per annum* shall notify/update their procurement projections every year, including those of the PSEs/PSUs, for the next 5 years on their respective website."

10A. Action for non-compliance of the Provisions of the Order: In case restrictive or discriminatory conditions against domestic suppliers are included in bid documents, an inquiry shall be conducted by the Administrative Department undertaking the procurement (including procurement by any entity under its administrative control) to fix responsibility for the same. Thereafter, appropriate action, administrative or otherwise, shall be taken against erring officials of procurement entities under relevant provisions. Intimation on all such actions shall be sent to the Standing Committee.

11. **Assessment of supply base by Nodal Ministries:** The Nodal Ministry shall keep in view the domestic manufacturing / supply base and assess the available capacity and the extent of local competition while identifying items and prescribing the higher minimum local content or the manner of its calculation, with a view to avoiding cost increase from the operation of this Order.

12. **Increase in minimum local content**: The Nodal Ministry may annually review the local content requirements with a view to increasing them, subject to availability of sufficient local competition with adequate quality.

13. **Manufacture under license/ technology collaboration agreements with phased indigenization**: While notifying the minimum local content, Nodal Ministries may make special provisions for exempting suppliers from meeting the stipulated local content if the product is being manufactured in India under a license from a foreign manufacturer who holds intellectual property rights and where there is a technology collaboration agreement / transfer of technology agreement for indigenous manufacture of a product developed abroad with clear phasing of increase in local content.

13A. In procurement of all goods, services or works in respect of which there is substantial quantity of public procurement and for which the nodal ministry has not notified that there is sufficient local capacity and local competition, the concerned nodal ministry shall notify an upper threshold value of procurement beyond which foreign companies shall enter into a joint venture with an Indian company to participate in the tender. Procuring entities, while procuring such items beyond the notified threshold value, shall prescribe in their respective tenders that foreign companies may enter into a joint venture with an Indian company to participate in the tender. The procuring Ministries/Departments shall also make special provisions for exempting such joint ventures from meeting the stipulated minimum local content requirement, which shall be increased in a phased manner.

14. **Powers to grant exemption and to reduce minimum local content**: The administrative Department undertaking the procurement (including

procurement by any entity under its administrative control), with the approval of their Minister-in-charge, may by written order, for reasons to be recorded in writing,

a. reduce the minimum local content below the prescribed level; or
b. reduce the margin of purchase preference below 20%; or
c. exempt any particular item or supplying entities from the operation of this Order or any part of the Order.

The Administrative Department, while seeking exemption under this para, shall certify that such an item(s) has not been notified by Nodal Ministry/ Department concerned under para 3 (a) of the Order.

A copy of every such order shall be provided to the Standing Committee and concerned Nodal Ministry / Department. The Nodal Ministry / Department concerned will continue to have the power to vary its notification on Minimum Local Content.

15. **Directions to Government companies**: In respect of Government companies and other procuring entities not governed by the General Financial Rules, the administrative Ministry or Department shall issue policy directions requiring compliance with this Order.
16. **Standing Committee**: A standing committee is hereby constituted with the following membership:
Secretary, Department for Promotion of Industry and Internal Trade - Chairman
Secretary, Commerce—Member
Secretary, Ministry of Electronics and Information Technology—Member Joint Secretary (Public Procurement), Department of Expenditure—Member Joint Secretary (DPIIT)—Member-Convenor

The Secretary of the Department concerned with a particular item shall be a member in respect of issues relating to such item. The Chairman of the Committee may co-opt technical experts as relevant to any issue or class of issues under its consideration.

17. **Functions of the Standing Committee:** The Standting Committee shall meet as often as necessary, but not less than once in six months. The Committee

a. shall oversee the implementation of this order and issues arising therefrom, and make recommendations to Nodal Ministries and procuring entities.
b. shall annually assess and periodically monitor compliance with this Order
c. shall identify Nodal Ministries and the allocation of items among them for issue of notifications on minimum local content
d. may require furnishing of details or returns regarding compliance with this Order and related matters
e. may, during the annual review or otherwise, assess issues, if any, where it is felt that the manner of implementation of the order results in any restrictive practices, cartelization or increase in public expenditure and suggest remedial measures
f. may examine cases covered by paragraph 13 above relating to manufacture under license/ technology transfer agreements with a view to satisfying itself that adequate mechanisms exist for enforcement of such agreements and for attaining the underlying objective of progressive indigenization

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g. may consider any other issue relating to this Order which may arise.

18. **Removal of difficulties**: Ministries /Departments and the Boards of Directors of Government companies may issue such clarifications and instructions as may be necessary for the removal of any difficulties arising in the implementation of this Order.

19. **Ministries having existing policies**: Where any Ministry or Department has its own policy for preference to local content approved by the Cabinet after 1st January 2015, such policies will prevail over the provisions of this Order. All other existing orders on preference to local content shall be reviewed by the Nodal Ministries and revised as needed to conform to this Order, within two months of the issue of this Order.

20. **Transitional provision**: This Order shall not apply to any tender or procurement for which notice inviting tender or other form of procurement solicitation has been issued before the issue of this Order.

19/2/24

(Himani Pande)
Additional Secretary to the Government of India
Tel: 011-23038888
E-mail: ashp.dpiit@gov.in

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File No: FP-20013/2/2017-FP-PNG-Part (4) (E-41432)
Government of India
Ministry of Petroleum and Natural Gas
(Flagship Programme Cell)
****

Shastri Bhawan, New Delhi
Dated: 26th March, 2024

To

1. Chairman, IOCL
2. C&MD, ONGC/ BPCL/ HPCL/ OIL/ GAIL/ EIL/ Balmer Lawrie
3. Managing Director, CPCL/ NRL/ MRPL/ BCPL/ OVL
4. DG, DGH
5. DG, PPAC
6. Secretary, OIDB
7. ED, OISD
8. ED, CHT
9. Director, RGIPT/ IIPE
10. Secretary, PNGRB
11. CEO & MD, ISPRL

Subject: Public Procurement (Preference to Make in India) Order, 2017-reg.

Sir/ Madam,

I am directed to refer to this Ministry's letter of even number dated 26.04.2022 on the above mentioned subject.

2. In this regard, it is stated that the sector specific relaxation granted under para 2(b) of aforementioned letter, has been reviewed in the Ministry and it has been decided that scope of this relaxation shall be limited to the items (list enclosed) to be installed/ operated in flammable environment of oil and gas process industry.

3. This issues with the approval of Hon'ble Minister, P&NG.

Yours faithfully

Kala 26/3/24
(Kala)
Under Secretary to the Govt. of India
Tel.: 011-23381029

Encl.: as above

Copy to:

a. PS to Hon'ble Minister, P&NG
b. PS to Hon'ble MoS, P&NG
c. PPS/ PS to Secretary, P&NG
d. PPS/PS to AS&FA/ AS, MoPNG
e. PPS/ PS to JS (E & BR)/ JS(GP)/ JS (M& OR)/ JS (IC)/ JS (G)/ JS (IFD)/ DDG, MoPNG
f. Technical Director, NIC: with a request to upload the letter on MoPNG website

Copy for information to,

Secretary, DPIIT

File No: FP-20013/2/2017-FP-PNG-Part (4) (E-41432)
Government of India
Ministry of Petroleum and Natural Gas
(Flagship Programme Cell)
****

Shastri Bhawan, New Delhi
Dated 26th April, 2022

To,

1. Chairman, IOCL
2. C&MD, BPCL/ HPCL/ ONGC/ OIL/ GAIL/ EIL/ Balmer Lawrie
3. Managing Director, MRPL/NRL/CPCL// BCPL/ OVL
4. DG, DGH
5. DG, PPAC
6. Secretary, OIDB
7. ED, PCRA
8. ED, OISD
9. ED, CHT
10. Director, RGIPT
11. Secretary, PNGRB
12. CEO & MD, ISPRL

Sub: Public Procurement (Preference to Make in India) (PPP-MII) Order, 2017-reg.

Sir/Madam,

I am directed to refer to this Ministry's letter of even number dated 23.02.2022 regarding Policy to Provide Purchase Preference (linked with local content) (PP-LC) in all Public Sector Undertakings under the Ministry of Petroleum and Natural Gas (MoP&NG) and to say that Public Procurement (Preference to Make in India) Order, 2017 issued by DPIIT and as amended time to time shall be applicable to all the Public Sector Undertakings and their wholly owned subsidiaries under MoP&NG; Joint Ventures that have 51% or more equity by one or more Public Sector Undertakings under MoP&NG; attached and subordinate offices of MoPNG w.e.f. 01.04.2022.

2. Moreover, as per para 14 of the PPP-MII Order, the following modifications in the order shall be applicable on the procuring entities under this Ministry:

a. Limit for exemption of small purchase under para 4 of the PPP-MII Order, 2017 shall be Rs. 1 crore.

b. Local value addition through services such as transportation, insurance, installation, commissioning, training and after sales services support like AMC/ CMC etc. shall continue to be considered in local content calculation.

c. HP-HT operations in upstream oil and gas business activities shall be exempted from applicability of the Order.

3. This issues with the approval of Hon'ble Minister, Petroleum and Natural Gas.

Yours faithfully

26/04/2022

(Santanu Dhar)
Under Secretary to the Govt. of India
Tel.: 011-23388652

Copy to:

a. PS to Minister, PNG
b. PPS/ PS to Secretary/ AS&FA/ Sr. Economic Advisor, MoPNG
c. PPS/ PS to AS (E)/ JS(R)/ JS (M& GP)/ OSD (IC)/ JS (G)/ JS (IFD)/ DDG (ED), MoPNG
d. PPS/PS to Dir.(BR)/Dir.(E-II)/Dir.(E-I)/DS(GP)/DS(Mkt.)/DS(LPG)/DS(Admn.)/DS(RTI)/ DS (Gen) MoPNG

Copy for information to:

Secretary, DPIIT

Items specifically to be used in flammable environment of oil and gas process industry in which value addition through services such as transportation, insurance installation, commissioning, training and after sales service support like AMC/CMC shall be continued to be conserved wile computing Local Content:

Sl.	Items Category of procurement
1	**Instrumentation items** like DCS/ ESD/ PLC, Emission Monitoring System, Machine Monitoring System, Condition Monitoring System, Fire Detection & Alarm System, Gas & Liquid Metering Systems, Mass Flow Meter, Process Analysers, Ultrasonic flowmeter, Anti surge & Governor Control system, Master control station for MOVs, Actuators, Transmitters, Radar gauges, multi-spot temperature sensors, Batch Controller unit, Additive blocks, Hydrocarbon detectors, Field instruments like Radar Gauges, Nucleonic gauges, Servo level gauging, Hydrastep, SMART Positioner in control valves, Multi point Reactor Thermocouple, Flame scanner, Viscosity cum Density meter, High Pressure/Temperature Special type valves, IS Test Equipment, Flare flow meter, Tank Farm Management System, Loading Automation System, Gas Detection System, Corrosion Monitoring System, Wireless Instrumentation, Surge Relief Valve Skid, Meter Provers, Pipeline Leak detection system (Negative Pressure wave type) etc
2	Equipment involved in drilling, completion, testing and production of oil and gas wells, Electronic carousel, Safety Relief valves, Compressors, turbines and blowers, heat ejectors, exchangers, condensers where SITC and / Expert Supervisory Services are involved, Equipment for which Life Cycle cost evaluation is done considering AMC/CAMC etc.
3	Electrical Equipment like Flameproof Plant Communication system, GIS (Gas Insulated Switchgear), Numerical Relays, Flameproof and/or explosion proof CCTV, Synchronous Machines, TETRA System etc
4	Laboratory and R&D Equipment like Gas Chromatographs, Spectrometers, Analytical equipment, Automatic liquid sampler, Dry colorimetric (tape) detectors; Mercury Free PVT Equipment; HT-HP Corrosion cell; Wheel Test Machine; Atmospheric and HT-HP- Consistometer; Ultra Sonic Cement Analyzer / HT-Ultra Sonic Cement Analyzer; Compressive strength tester; Stirred fluid loss apparatus; Total Sulfur analyzer; Colony counter; Laminar flow systems; Microscope with digital camera; Anaerobic Chamber; RockEval; TOC analyser; Simdist analyser; Cold Finger test apparatus; Microcoulometer; Atomic Absorption Spectrometer; High Performance Ion Chromatograph; Permeameter; Helium Porosimeter; Laser Scattering Particle Size Distribution Analyser; Microscope high magnification; Flame Photometer; U.V.- Visible Spectrophotometers; EP Lube tester; Differential sticking tester; Electrical stability Meter; Stemi-2000 microscope/ equivalent; Core Gama Logger; Energy Dispersive Spectrometer; Thin Section Machine; X-Ray Diffractometer; Wettability tester; Ambient Resistivity System; Flouroscope; Spin Drop Tensiometer; Fluid Eval; Mercury Inclusion Porosity meter; Tri-Axial test machine; Smoke point detector; Vitrinite Reflectance VRo Microscope; Curing Chamber/ HT curing chamber; Source Rock Pyrolyser with Sulphur/ without sulphur; NGA Gas Analyzer Flash Point Apparatus/ automatic; Compressive Strength Analyser; HT-HP Curing Chamber; Crush resistance test equipment; Manual Dry bath pore point Apparatus; Bench Type Dissolved Oxygen meter; Bench Type GRAIN Moisture meter; Rotational Viscometer; Capillary pressure instrument; Core Plugging Machine; Core Trimming machine; HP-HT filter press; BENCH TOP DENSITY METER; HP-HT ROLLER OVEN with AGING CELLS; Crude Oil Analyser; Static Gel Strength analyser; Oilwell cement Mechanical properties analyser; Poroperm; Acoustic velocity system; Auto Saturator; Porosimeter cum permeameter; Rock Testing System; Auto Core Saturator; Auto Imbibiometer for reverse permeability; Proppant Conductivity Tester etc

5	Pipeline Intrusion and Detection System (PIDS), SCADA & APPS system; Rim seal protection system, Chemical Treatment program which involves supply of Process chemicals, Dosing & monitoring the parameters etc
6	**Geophysical Services** Seismic Data Acquisition System; VSP Data Acquisition System; Field Processing Unit; Geophysical equipment (non-Seismic including Gravity Magnetic, MT, EM etc.); Seismic Data Processing Software ; Seismic Data Interpretation Software ; Hydrocarbon Reservoir Software ; Seismic Data Archival Software ; Petro -Physical Software
7	**Geophysical Equipment** Field Processing Unit, Global Navigation Satellite System, Specialised Geological Lab Equipment, Seismic Data Acquisition System, Seismic Data Processing/ Imaging Software, Tape Drive Unit, VSP Data Acquisition System, VSP Processing Software; High-End Servers for G&G Applications, HPCC Solution; Virtualization and Container Software
8	**Logging Services** Logging unit, equipment and tools rated for hostile HPHT environment (Temperature > 300°F & Pressure > 10.000 psi).

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रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-07092020-221592
CG-DL-E-07092020-221592

असाधारण
EXTRAORDINARY

भाग I—खण्ड 1
PART I—Section 1

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 232] नई दिल्ली, सोमवार, सितम्बर 7, 2020/भाद्र 16, 1942
No. 232] NEW DELHI, MONDAY, SEPTEMBER 7, 2020/BHADRA 16, 1942

इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

(आई.पी.एच.डब्ल्यू.)

अधिसूचना

नई दिल्ली, 7 सितंबर, 2020

विषय: सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के अनुक्रम में इलेक्ट्रॉनिक उत्पादों को अधिसूचित करना

संदर्भ : उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017

फा. सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई.—सरकार ने 'मेक इन इंडिया' को प्रोत्साहित करने और आय और रोजगार बढ़ाने के उद्देश्य से भारत में वस्तुओं और सेवाओं के विनिर्माण और उत्पादन को बढ़ावा देने के लिए उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II, दिनांक 15.06.2017 के तहत सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश, 2017 जारी किया है।

2. उपर्युक्त संदर्भ के जरिए अधिसूचित सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश, 2017 [पीपीपी-एमआईआई आदेश 2017] के अनुक्रम में और इसके तहत जारी की गई दिनांक 14.09.2017 की इलेक्ट्रॉनिक उत्पाद अधिसूचना संख्या 33(1)/2017-आईपीएचडब्ल्यू और दिनांक 01.08.2018 की अधिसूचना संख्या 33(5)/2017-आईपीएचडब्ल्यू के अधिक्रमण में इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) एतदद्वारा अधिसूचित करता है कि समय-समय पर संशोधित पूर्वोक्त आदेश के अनुसार स्थानीय रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों को सभी क्रय संस्थाओं द्वारा वरीयता प्रदान की जाएगी।

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3. इस अधिसूचना के उद्देश्य से:

क. श्रेणी-I स्थानीय आपूर्तिकर्ता, श्रेणी-II स्थानीय आपूर्तिकर्ता और गैर-स्थानीय आपूर्तिकर्ता की परिभाषा समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 2 के अनुसार होगी। समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 5 के अनुसार इस अधिसूचना में अधिसूचित प्रत्येक इलेक्ट्रॉनिक उत्पाद के लिए स्थानीय सामग्री की गणना के लिए तंत्र निर्धारित किया गया है।

ख. समय-समय पर यथासंशोधित डीपीआईआईटी पीपीपी-एमआईआई आदेश, 2017 संख्या पी-45021/2/2017-पीपी (बीई-II), दिनांक 04.06.2020 के पैरा 3क क्रय के प्रतिशत के लिए संदर्भित किया जाएगा जिसके लिए अधिमानतः घरेलू स्तर पर विनिर्मित इलेक्ट्रॉनिक उत्पादों (मूल्य के संदर्भ में) को वरियता दी जानी है।

4. सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत निम्नलिखित इलेक्ट्रॉनिक उत्पाद अधिसूचित किए गए हैं:

4.1 डेस्कटॉप पर्सनल कंप्यूटर (पीसी)

(क) परिभाषा:

इस अधिसूचना के प्रयोजन से एक डेस्कटॉप पीसी में आवश्यक रूप से एक सीपीयू, मेमोरी, हार्ड डिस्क ड्राइव, की-बोर्ड, माउस और एक अलग या एकीकृत डिस्प्ले यूनिट शामिल होगी और इसे स्वतंत्र रूप से कार्य करने में सक्षर्थ होना चाहिए।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र:

डेस्कटॉप पीसी की सामग्री का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बी.ओ.एम के प्रमुख इनपुट/डेस्कटॉप पीसी के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री**
1	**2**
मुख्य बोर्ड/मदरबोर्ड और सीपीयू/जीपीयू	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार डेस्कटॉप पीसी के कुल बीओएम के 30% से अधिक नहीं होगा।
मेमोरी मॉड्यूल	बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* एवं परीक्षण।
हार्ड डिस्क ड्राइव/सॉलिड स्टेट ड्राइव (एसएसडी)	बेयर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* एवं फाइनल उत्पाद असेम्बली और परीक्षण।
एलसीडी/एलईडी मॉनिटर	आयातित/घरेलू रूप से असेम्बल किए गए एलसीडी/एलईडी पैनल वाले कलपुर्जों से एलसीडी/एलईडी मॉनीटर की घरेलू स्तर पर असेम्बली और परीक्षण और घरेलू पीसीबी असेंबली*, घरेलू प्लास्टिक मोल्डिंग और बेयर पीसीबी के मूल्य को छोड़कर धातुई कलपूर्जों की स्टैम्पिंग।

डीवीडी ड्राइव	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
कैबिनेट + एमएसपीएस	घरेलू रूप से विनिर्मित कैबिनेट और घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से एसएमपीएस की फाइनल असेम्बली और परीक्षण, इस शर्त के अध्यधीन कि "एसएमपीएस" की असेम्बली में उपयोग किए जाने वाले घरेलू विनिर्मित कलपुर्जे और संघटक न्यूनतम 20% होंगे ("एसएमपीएस" के विनिर्माण में उपयोग किए जाने वाले कलपुर्जों और संघटकों के कुल मूल्य के)।
की-बोर्ड और माउस	घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से फाइनल असेम्बली और परीक्षण।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित।
(i) फाइनल असेंबली/परीक्षण और (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.2 थिन क्लाइंट

(क) परिभाषा:

इस अधिसूचना के प्रयोजन से किसी थिन क्लाइंट (टीसी) में अनिवार्य रूप से सीपीयू, मेमोरी, डोम, की-बोर्ड, माउस और एक अलग या एकीकृत डिस्प्ले यूनिट शामिल होते हैं और यह स्वतंत्र रूप से कार्य करने में सक्षम होना चाहिए।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र:

थिन क्लाइंट की सामग्री का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/थिन क्लाइंट के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री**
1	**2**
मुख्य बोर्ड/मदरबोर्ड और सीपीयू	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार थिन क्लाइंट के कुल बीओएम के 30% से अधिक नहीं होगा।

मेमोरी मॉड्यूल/डोम	बेयर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* और परीक्षण।
एसएमपीएस/पावर अडैप्टर	घरेलू रूप से पीसीबी असेंबलीं * और आयातित/ घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से एसएमपीएस / पावर अडैप्टर की फाइनल असेंबली और टेस्टिंग, इस शर्त के अधीन है कि "एसएमपीएस" की असेंबली में प्रयुक्त घरेलू विनिर्मित पुर्जे और कलपुर्जे न्यूनतम 20% होंगे ("एसएमपीएस") के विनिर्माण में उपयोग किए जाने वाले कलपुर्जों और संघटकों के कुल मूल्य के)।
एलसीडी/एलईडी मॉनिटर	आयातित/घरेलू रूप से असेंबली किए गए एलसीडी/एलईडी पैनल वाले कलपुर्जों से एलसीडी/एलईडी मॉनीटर की घरेलू स्तर पर असेम्बली और परीक्षण और घरेलू पीसीबी असेंबली*, घरेलू प्लास्टिक मोल्डिंग और बेयर पीसीबी के मूल्य को छोड़कर धातुई कलपूर्जों की स्टैम्पिंग।
कैबिनेट	घरेलू तौर पर विनिर्मित।
की-बोर्ड और माउस	घरेलू पीसीबी असेम्बली* और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से फाइनल असेम्बली और परीक्षण।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित ।
(i) फाइनल असेंबली / परीक्षण और (ii) डिजाइन / विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.3 लैपटॉप पर्सनल कंप्यूटर (पीसी)

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से किसी लैपटॉप पीसी (जिसे आमतौर पर लैपटॉप/नोटबुक/नेटबुक/अल्ट्राबुक आदि के रूप में बाजार में जाना जाता है) में आवश्यक रूप से सीपीयू, मेमोरी, हार्ड डिस्क ड्राइव, कीबोर्ड, टचपैड और/या ट्रैकपॉइंट एकीकृत प्रदर्शन इकाई, एकीकृत बैटरी शामिल होंगे और यह स्वतंत्र रूप से प्रचालित होने में सक्षम होना चाहिए।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र:

लैपटॉप पीसी का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम प्रमुख इनपुट लैपटॉप के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/ स्थानीय सामग्री**
1	2
मुख्य बोर्ड/मदरबोर्ड और सीपीयू/जीपीयू	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार लैपटॉप के कुल बीओएम के 35% से अधिक नहीं हो
पावर मॉड्यूल	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण ।
मेमोरी मॉड्यूल	बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेयर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों से घरेलू पीसीबी असेंबली* और परीक्षण ।
हार्ड डिस्क ड्राइव/सॉलिड स्टेट ड्राइव (एसएसडी)	बेयर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और फाइनल उत्पाद असेम्बली और परीक्षण।
डिस्प्ले पैनल (एलसीडी, एलईडी, आदि)	बैक कवर और बेज़ेल में घरेलू असेंबली और बैक कवर और बेज़ेल के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर डिस्प्ले पैनल, एलईडी बैक लाइट, एंटेना से फाइनल परीक्षण।
डीवीडी ड्राइव	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण ।
पावर अडैप्टर	घरेलू पीसीबी असेंबली के साथ आयातित/घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली* और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का) ।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित।
कीबोर्ड/टचपैड और/या ट्रैकपॉइंट	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण ।
बैटरी	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण ।
बॉटम कवर, बैक कवर, कीबोर्ड फेस बेजेल और डिस्प्ले फेस बेजल और हिंगेस सहित लैपटॉप के कैबिनेट/चेसिस	आयातित/घरेलू इनपुट का उपयोग करके इंजेक्शन मोल्डिंग / स्टांपिंग के माध्यम से घरेलू स्तर पर विनिर्मित ।
(i) फाइनल असेंबली/परीक्षण और (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.4 कंप्यूटर मॉनिटर

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से, एक कंप्यूटर मॉनीटर (जिसे आमतौर पर बाजार में मॉनीटर के रूप में जाना जाता है) में एक एलसीडी/एलईडी डिस्प्ले असेंबली, लॉजिक कार्ड, पॉवर सप्लाई अडैप्टर और कैबिनेट होता है जो इसे डेस्कटॉप पीसी या लैपटॉप पीसी या टैबलेट पीसी से कनेक्ट करने के लिए डिस्प्ले पोर्ट्स से युक्त होता है।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

कंप्यूटर मॉनिटर का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/कंप्यूटर मॉनिटर के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री**
1	**2**
लॉजिक कार्ड/माइक्रो कंट्रोलर	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स का मूल्य शामिल है और बेयर पीसीबी का मूल्य शामिल नहीं है।
एलसीडी/एलईडी पैनल	कैबिनेट/चेसिस के मूल्य को छोड़कर, मॉनिटर कैबिनेट/चेसिस में आयातित/घरेलू रूप से एकत्रित एलसीडी/एलईडी पैनल *** का घरेलू एकीकरण और परीक्षण । हालाँकि, एलसीडी/एलईडी पैनल के कुल मूल्य का भार कंप्यूटर मॉनीटर के कुल बीओएम के 35% से अधिक नहीं होगा।
केबल्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित और परीक्षण किया गया।
पावर अडैप्टर	घरेलू पीसीबी असेंबली के साथ आयातित/ घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली* और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित।
कैबिनेट/चेसिस	मॉनिटर बेज़ेल, बैक कवर, स्टैंड, बेस और चेसिस जिसमें प्लास्टिक मोल्डिंग और धातु के हिस्सों की स्टैम्पिंग को आयातित/घरेलू इनपुट का उपयोग करके घरेलू स्तर पर किया जाता है।

(i) फाइनल असेंबली/परीक्षण और (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर (एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

**** इसकी समीक्षा तब की जाएगी जब भारत में कंप्यूटर मॉनिटर्स (प्रत्येक आकार और प्रकार के) का एलसीडी / एलईडी पैनल विनिर्माण संचालन में हो।*

4.5 <u>टैबलेट पर्सनल कंप्यूटर (पीसी)</u>

क. परिभाषा :

इस अधिसूचना के प्रयोजन से, एक टैबलेट पीसी में आवश्यक रूप से एक एकीकृत मदरबोर्ड जिसमें सीपीयू/प्रोसेसर, मेमोरी और पावर मॉड्यूल और बोर्ड होंगे शामिल होगा; डिस्प्ले पैनल (टच पैनल + एलसीडी/एलईडी मॉड्यूल) और एकीकृत बैटरी होंगे और यह स्वतंत्र रूप से संचालित करने में सक्षम होना चाहिए।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

टैबलेट पीसी का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/टैबलेट पीसी के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री**
1	**2**
ऑन बोर्ड सीपीयू/जीपीयू/प्रोसेसर के साथ इंटीग्रेटेड मदरबोर्ड	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, जिसमें सेमीकंडक्टर्स** और प्रोसेसर/ सीपीयू/जीपीयू** का मूल्य शामिल है और बेयर पीसीबी का मूल्य इसमें शामिल नहीं है। हालाँकि, सीपीयू के कुल मूल्य का भार टैबलेट पीसी के कुल बीओएम के 35% से अधिक नहीं होगा।
मेमोरी और पावर मॉड्यूल	बेयर पीसीबी के मूल्य को छोड़कर, आयातित/ घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण ।
डिस्प्ले पैनल (टच पैनल + एलसीडी/एलईडी मॉड्यूल)	आयातित/घरेलू रूप से विनिर्मित टच पैनल, एलसीडी/एलईडी मॉड्यूल या संयोजन से घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि डिस्प्ले पैनल का बैकलाइट असेंबली और परीक्षण घरेलू स्तर पर किया जाएगा।
पावर अडैप्टर	घरेलू पीसीबी असेंबली के साथ, आयातित/घरेलू स्तर पर विनिर्मित पूर्जों और संघटकों से फाइनल घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि "पावर अडैप्टर" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित

	कलपूर्जों और संघटकों का मूल्य न्यूनतम 40% होगा ("पावर अडैप्टर" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित।
केसिंग	घरेलू स्तर पर विनिर्मित केसिंग।
बैटरी	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
ऐक्सेसरी (कैमरा, स्पीकर, वाईफाई एंटीना, आदि)	आयातित/घरेलू स्तर पर कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
(i) फाइनल असेंबली/परीक्षण और (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर सीपीयू (एस)/जीपीयू/प्रोसेसर(एस) कलपुर्जों/संघटकों के प्रिंटेड सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.6 डॉट मैट्रिक्स प्रिंटर

(क) परिभाषा :

डॉट मैट्रिक्स प्रिंटर एक प्रकार का प्रभावी प्रिंटर है, जो 0.2 मिमी से 0.3 मिमी के व्यास के धातु पिन द्वारा कागज पर डॉट बनाता है, जो सोलनॉइड सिद्धांत के आधार पर इलेक्ट्रोमैग्नेट द्वारा संचालित होता है और डॉट मैट्रिक्स प्रिंटहेड केन क्षैतिज और ऊर्ध्वाधर रिजोलूशन द्वारा अपेक्षित कैरेक्टर का मैट्रिक्स उतपन्न होता है। डॉट मैट्रिक्स प्रिंटर पिन के यांत्रिक दबाव के आधार पर कार्बन प्रतियां और कार्बन रहित प्रतियां बना सकता है।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

डॉट मैट्रिक्स प्रिंटर का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग- अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/डॉट मैट्रिक्स प्रिंटर के विनिर्माण के लिए चरण	**घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/ स्थानीय सामग्री**
1	**2**
मुख्य पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण, इस शर्त के अधीन है कि "मुख्य पीसीबी" की असेंबली में प्रयुक्त घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों का मूल्य न्यूनतम 15% होगा (मुख्य पीसीबी के विनिर्माण में प्रयुक्त कलपूर्जों और संघटकों के कुल मूल्य का), बेयर पीसीबी के मूल्य को छोड़कर।
बेयर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू रूप से विनिर्मित।

एसएमपीएस	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन है कि "एसएमपीएस" की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित कल-पूर्जों और संघटकों का मूल्य न्यूनतम 20% होगा ("एसएमपीएस" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)।
कैरिज मोटर्स और पेपर फीड मोटर्स	उप-असेंबली के रूप में आयात किया गया और मुख्य प्रिंटर तंत्र के साथ घरेलू रूप से परीक्षण किया गया।
फ्रंट कंट्रोल पैनल	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
होम पोजीशन / पेपर एंड सेंसर	आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
मुख्य प्रिंटर कैबिनेट और अन्य छोटे प्लास्टिक घटक	प्रिंटर कैबिनेट और अन्य भागों के घरेलू मोल्डिंग ।
प्रिंटर मेकेनिज़्म असेंबली	घरेलू स्तर पर विनिर्मित रबर प्लेट्स, छोटे रबर भागों, शीट धातु के घटकों, प्लास्टिक गियर और टण्ड स्टील शाफ्ट के साथ अन्य प्लास्टिक भागों और ऊपर वर्णित सेंसर और मोटर्स का उपयोग करके घरेलू असेंबली।
प्रिंट हेड्स और इंटरकनेक्टिंग केबल्स	उप- असेंबली के रूप में आयात किया गया और मुख्य प्रिंटर तंत्र के साथ घरेलू रूप से परीक्षण किया गया।
(i) फाइनल असेंबली/परीक्षण और (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर कल पूर्जों/ संघटकों के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में किया जाना चाहिए।*

4.7 स्मार्ट कार्ड

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से, स्मार्ट कार्ड आमतौर पर एक क्रेडिट कार्ड के आकार का प्लास्टिक कार्ड होता है, जिसमें एक एकीकृत सर्किट (आईसी) होता है। इस आईसी में एक माइक्रोप्रोसेसर और मेमोरी होती है। स्मार्ट कार्ड संपर्क, संपर्क रहित या दोहरे इंटरफ़ेस (संपर्क और संपर्क रहित दोनों) पर आधारित हो सकते हैं। स्मार्ट कार्ड के कुछ अनुप्रयोगों में पहचान पत्र, बैंकिंग कार्ड, स्वास्थ्य कार्ड, वाहन पंजीकरण कार्ड आदि हैं।

I (ख) कांटैक्ट स्मार्ट कार्ड के लिए स्थानीय सामग्री की गणना के लिए तंत्र

कांटैक्ट स्मार्ट कार्ड का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/कॉन्टैक्ट स्मार्ट कार्ड के विनिर्माण के लिए चरण	घरेलू बीओएम के रूप में वर्गीकृत किए जाने वाले इनपुट के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री
1	2
प्लास्टिक कार्ड बॉडी	आयातित/घरेलू रूप से विनिर्मित, कलपुर्जों और संघटकों का उपयोग करके शीट कटिंग और पंचिंग, प्रिंटिंग, लेमिनेशन और परीक्षण सहित घरेलू विनिर्माण ।
आईसी चिप मॉड्यूल	आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करते हुए, आईसी चिप मॉड्यूल* की घरेलू असेंबली, पैकेजिंग और परीक्षण।
प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग	प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग घरेलू स्तर पर करना।
(i) फाइनल असेंबली और टेस्टिंग (ii) डिजाइन / विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

II (ख) कॉन्टैक्टलेस स्मार्ट कार्ड के लिए स्थानीय सामग्री की गणना के लिए क्रियाविधि

कॉन्टैक्टलेस स्मार्ट कार्ड का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम में प्रमुख इनपुट/कॉन्टैक्टलेस स्मार्ट कार्ड के विनिर्माण के लिए चरण	इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने के लिए आवश्यक मूल्यवर्धन/स्थानीय सामग्री
1	2
प्लास्टिक कार्ड बॉडी	आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करके शीट कटिंग और पंचिंग, प्रिंटिंग, लेमिनेशन और परीक्षण सहित घरेलू विनिर्माण ।
कार्ड इनले (एंटीना)	घरेलू स्तर पर विनिर्मित आयातित कच्चे माल, कलपुर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
आईसी चिप मॉड्यूल	आयातित/घरेलू रूप से विनिर्मित कच्चे माल, कलपुर्जों और संघटकों का उपयोग करके आईसी चिप* मॉड्यूल की घरेलू असेंबली, पैकेजिंग और परीक्षण।
प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग	प्लास्टिक कार्ड पर आईसी चिप मॉड्यूल की मिलिंग और एंबेडिंग घरेलू स्तर पर करना ।
(i) फाइनल असेंबली और टेस्टिंग (ii) डिजाइन / विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.8 एलईडी उत्पाद

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से, एलईडी उत्पाद वे हैं जिनका कार्य एलईडी द्वारा उत्पादित प्रकाश का उपयोग करना और निम्नलिखित क्षेत्रों में इसका उपयोग बढ़ाना है:- (i) रोशनी, (ii) टू एलईडी टीवी सहित ऑप्टिकल डिस्प्ले, (iii) बैकलाइटिंग, (iv)) सिग्नलिंग और इंडिकेशन और (v) परिवहन।

(ख) स्थानीय सामग्री की गणना के लिए क्रियाविधि :

एलईडी उत्पादों का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें: हालाँकि, (घ) हीट सिंक या थर्मल मैनेजमेंट सॉल्यूशंस, (ङ) सेकेंडरी ऑप्टिक्स और (च) सिस्टम फिक्सेटर और फिटिंग के कुल मूल्य का भार एलईडी उत्पाद के कुल बीओएम से 20% से अधिक नहीं होगा:

बीओएम के प्रमुख इनपुट/एलईडी उत्पादों के विनिर्माण के लिए चरण	**इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन**
1	2
एलईडी एमिटर	आयातित/घरेलू रूप से विनिर्मित बेयर एलईडी डाई से पैकेजिंग, इस शर्त के अधीन है कि बेयर एलईडी डाई को आयातित/घरेलू विनिर्मित आदानों का उपयोग करके घरेलू रूप से विनिर्मित किया जाएगा।
ड्राइविंग इलेक्ट्रॉनिक्स	घरेलू असेंबली* और आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से परीक्षण, इस शर्त के अध्यधीन है कि "ड्राइविंग इलेक्ट्रॉनिक्स " की असेंबली में इस्तेमाल होने वाले घरेलू स्तर पर विनिर्मित कल-पूर्जों और संघटकों (बेयर पीसीबी का मूल्य छोड़कर) का मूल्य न्यूनतम 30% होगा ("ड्राइविंग इलेक्ट्रॉनिक्स" के विनिर्माण में उपयोग किए जाने वाले कलपूर्जों और संघटकों के कुल मूल्य का)।
एमसीपीसीबी सहित बेयर पीसीबी	घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित।
हीट सिंक या थर्मल प्रबंधन समाधान	घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित।
माध्यमिक प्रकाशिकी	घरेलू रूप से आयातित/घरेलू स्तर पर विनिर्मित इनपुट का उपयोग करके विनिर्मित।
सिस्टम फिक्सर और फिटिंग	घरेलू तौर पर विनिर्मित।
फाइनल असेंबली/परीक्षण	समय-समय पर अधिसूचित भारतीय मानकों के अनुसार घरेलू रूप से असेंबली/परीक्षण किए गए।

4.9 <u>बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस</u>

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से, बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस में *अन्य बातों के साथ-साथ* एक फिंगर प्रिंट सेंसर/आइरिस सेंसर, नियंत्रक मॉड्यूल और बिजली की आपूर्ति शामिल होगी। इसमें डिस्प्ले यूनिट हो सकती है या नहीं भी। बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस के कुछ एप्लिकेशन फिजिकल एक्सेस कंट्रोल, टाइम और अटेंडेंस कंट्रोल आदि हैं।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट बायोमेट्रिक एक्सेस कंट्रोल/ऑथेंटिकेशन डिवाइस के विनिर्माण के लिए चरण	**इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन**
1	2
फिंगर प्रिंट सेंसर/आइरिस सेंसर	घरेलू स्तर पर विनिर्मित जैसा कि अधिसूचित है (पैराग्राफ 4.10 और 4.11 को देखें)।
मुख्य पीसीबी (नियंत्रक मॉड्यूल)	घरेलू असेंबली और आयातित/घरेलू स्तर पर विनिर्मित कलपुर्जों और संघटकों से परीक्षण, बेयर पीसीबी के मूल्य को छोड़कर।
बेअर पीसीबी	आयातित/घरेलू स्तर पर विविनिर्मित इनपुट से घरेलू स्तर पर विविनिर्मित ।
बिजली की आपूर्ति/बैटरी (यदि अलग हो)	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
डिस्प्ले यूनिट	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
वैकल्पिक विशेषताएं जैसे कि कैमरा, कीबोर्ड, आरएफआईडी, स्मार्ट कार्ड रीडर, जीपीआरएस मॉड्यूल, वाई-फाई, ब्लू टूथ आदि।	आयातित/घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों से घरेलू असेंबली और परीक्षण।
प्लास्टिक हाउसिंग	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित।
युएसबी केबल्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित।
(i) फाइनल असेंबली और परीक्षण (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

4.10 बायोमेट्रिक फिंगर प्रिंट सेंसर

(क) परिभाषा :

इस अधिसूचना के उद्देश्य से, बॉयोमीट्रिक फिंगर प्रिंट सेंसर में एक नियंत्रक मॉड्यूल, सीएमओएस सेंसर और ऑप्टिक्स शामिल हैं। बायोमेट्रिक फिंगर प्रिंट सेंसर के अनुप्रयोग व्यक्तिगत पहचान और सत्यापन आदि हैं।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र:

बायोमेट्रिक फिंगर प्रिंट सेंसर की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख मुख्य इनपुट/बॉयोमीट्रिक फिंगर प्रिंट सेंसर के निर्माण के लिए चरण	इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन
1	2
मुख्य पीसीबी (नियंत्रक मॉड्यूल)	बेअर पीसीबी के मूल्य को छोड़कर आयातित / घरेलू स्तर पर विनिर्मित कलपूर्जों और संघटकों का उपयोग करके घरेलू असेंबली और परीक्षण ।
ऑप्टिक्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित ।
सीएमओएस सेंसर	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से उपयोग करके सीएमओएस सेंसर की घरेलू असेंबली, पैकेजिंग और परीक्षण*।
बेअर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण।
प्लास्टिक हाउसिंग	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण।
यूएसबी केबल्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण।
(i) फाइनल असेंबली और टेस्टिंग (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.11 बायोमेट्रिक आइरिस सेंसर

(क) परिभाषा :

इस अधिसूचना के उद्देश्य से, बॉयोमीट्रिक आइरिस सेंसर में एक नियंत्रक मॉड्यूल, सीएमओएस सेंसर और ऑप्टिक्स शामिल हैं। बायोमेट्रिक आइरिस सेंसर के आवेदन व्यक्तिगत पहचान और सत्यापन आदि हैं।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र:

बायोमेट्रिक आइरिस सेंसर का का घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/बॉयोमीट्रिक फिंगर प्रिंट सेंसर के विनिर्माण के लिए चरण	इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन
1	2
मुख्य पीसीबी (नियंत्रक मॉड्यूल)	बेअर पीसीबी के मूल्य को छोड़कर आयातित/ घरेलू स्तर पर विनिर्मित भागों और संघटकों का उपयोग करके घरेलू असेंबली और परीक्षण ।
ऑप्टिक्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित ।

सीएमओएस सेंसर	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से उपयोग करके सीएमओएस सेंसर की घरेलू असेंबली, पैकेजिंग और परीक्षण *
बेअर पीसीबी	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण।
प्लास्टिक हाउसिंग	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण ।
यूएसबी केबल्स	आयातित/घरेलू स्तर पर विनिर्मित इनपुट से घरेलू स्तर पर विनिर्माण ।
(i) फाइनल असेंबली और परीक्षण (ii) डिजाइन/विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

* *भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी ।*

4.12 सर्वर

(क) परिभाषा :

इस अधिसूचना के प्रयोजन से, एक सर्वर में आवश्यक रूप से एक मदर बोर्ड, सीपीयू, मेमोरी (रैम), हार्ड डिस्क ड्राइव (एचडीडी)/सॉलिड स्टेट स्टोरेज ड्राइव (एसएसएसडी), पावर सप्लाई यूनिट (एसएमपीएस), चेसिस, कनेक्टिंग केबल्स और फर्मवेयर और ओएस शामिल होंगे।

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

सर्वर की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करें:

बीओएम के प्रमुख इनपुट/सर्वर के विनिर्माण के लिए चरण	**इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन**
1	**2**
सर्वर बोर्ड/मदर बोर्ड और सीपीयू(एस)/जीपीयू (एस)	सेमीकंडक्टर्स** और सीपीयू (एस)/जीपीयू (एस)को शामिल करके** और बेअर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण
मेमोरी मॉड्यूल	पीसीबी असेंबली और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण।
हार्ड डिस्क ड्राइव/सॉलिड स्टेट स्टोरेज ड्राइव (एसएसडी)	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण।
कैबिनेट + एसएमपीएस	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू रूप से घरेलू स्तर पर विनिर्मित कैबिनेट और एसएमपीएस का घरेलू असेंबली और परीक्षण, इस शर्त के

	अध्यधीन कि "एसएमपीएस" की असेंबली में उपयोग किए गए घरेलू स्तर पर विनिर्मित भागों और संघटकों का मूल्य न्यूनतम 25% होगा ("एसएमपीएस " के विनिर्माण में उपयोग किए जाने वाले भागों और संघटकों का कुल मूल्य)
बेअर पीसीबी	आयातित/घरेलू विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित
सहायक उपकरण (पावर केबल, कनेक्टर्स,आदि)	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण।
(i) फाइनल असेंबली और टेस्टिंग (ii) डिजाइन और विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** यह आवश्यक है कि सीपीयू (एस) /जीपीयू (एस) /प्रोसेसर (एस) के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए), एसएमटी प्रक्रिया का उपयोग कर बेअर पीसीबी पर भागों/संघटकों को अनिवार्य रूप से भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

4.13 सेल्युलर मोबाइल फ़ोन

(क) परिभाषा :

इस अधिसूचना के प्रयोजन के लिए, एक सेलुलर मोबाइल फोन (फीचर फोन या स्मार्ट फोन) में मुख्य रूप से मुद्रित सर्किट बोर्ड (पीसीबी), बैटरी पैक, डिस्प्ले यूनिट, कुंजी पैड/टच पैनल, चार्जर/एडाप्टर, माइक्रोफोन और रिसीवर वाइब्रेटर मोटर/रिंगर और मैकेनिक्स शामिल होंगे। ,

(ख) स्थानीय सामग्री की गणना के लिए तंत्र :

सेल्युलर मोबाइल फ़ोनों के घरेलू बीओएम में निम्न तालिका के कॉलम1 में विनिर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्य अतिरिक्त आवश्यकता को पूरा करते हैं:

बीओएम के प्रमुख इनपुट/सेलुलर मोबाइल फोन के निर्माण के लिए चरण	**इनपुट को घरेलू बीओएम के तौर पर वर्गीकृत किए जाने वाले के लिए आवश्यक मूल्यवर्धन /स्थानीय सामग्री**
1	2
मुख्य पीसीबी*	प्रोसेसर/सेमीकंडक्टर** बीओएम(यानी मेन पीसीबी पर सेमीकंडक्टर चिप्स और मॉड्यूल),को शामिल करके और बेअर पीसीबी के मूल्य को छोड़कर ,आयातित / घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबलीऔर परीक्षण।
बेयर पीसीबी	घरेलू रूप से आयात सामग्री का विनिर्माण/घरेलू स्तर पर विनिर्मित इनपुट।
बैटरी पैक	आयात सामग्री की घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
चार्जर/एडाप्टर	आयात सामग्री से घरेलू असेंबली और परीक्षण/ घरेलू स्तर पर विनिर्मित इनपुट।
वायर्ड हेडसेट	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
यांत्रिकी***	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
डाई कट कलपुर्ज़े***	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
माइक्रोफोन और रिसीवर	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
की-पैड	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।

यूएसबी केबल	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
कैमरा मॉड्यूल	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
कनेक्टर्स	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
डिसप्ले यूनिट	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
टच पैनल/कवर ग्लास असेंबली	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
वाइब्रेटर मोटर/रिंगर	आयात सामग्री से घरेलू असेंबली और परीक्षण/घरेलू स्तर पर विनिर्मित इनपुट।
(i) अंतिम असेंबली और परीक्षण (ii) डिजाइन और विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

**यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करते हुए बेयर पीसीबी पर संसाधक/संघटक की प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर फैब प्रचालनरत होने पर इसकी समीक्षा की जाएगी।*

**** अनुबंध का संदर्भ लें।*

5. अधिसूचना तुरंत प्रभाव से लागू है। संशोधित अधिसूचना जारी होने तक यह अधिसूचना मान्य रहेगी।

6. सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत कोई भी इलेक्ट्रॉनिक उत्पाद अधिसूचना का भूतलक्षी प्रभाव नहीं होगा।

7. उपरोक्त इलेक्ट्रॉनिक उत्पादों की क्रय के लिए दिनांक 04.06.2020 के सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 में उल्लिखित प्रावधानों के अनुसार क्रय वरीयता प्रदान की जाएगी।

8. यदि भारत सरकार द्वारा परियोजना या योजना पूरी तरह से या आंशिक रूप से वित्त पोषित होती है, तो राज्यों और स्थानीय निकायों द्वारा बनाए गए इलेक्ट्रॉनिक उत्पादों की क्रय के लिए अधिसूचना सभी केंद्रीय योजनाओं (सीएस)/केंद्रीय क्षेत्र की योजनाओं (सीएसएस) पर भी लागू होगी।

9. स्थानीय सामग्री/घरेलू मूल्यवर्धन की गणना करने हेतु प्रक्रिया

9.1 घरेलू विनिर्माताओं (डीओएम-बीओएम) से प्राप्त सामग्री के बिल की गणना उपलब्ध आंकड़ों के आधार पर निम्नलिखित में से किसी एक के आधार पर की जा सकती है। इनमें से प्रत्येक गणना के सुसंगत परिणाम प्राप्त होने चाहिए।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और जिनका आयात प्रत्यक्ष रूप से या घरेलू व्यापारी या माध्यस्थ के माध्यम से नहीं किया गया है।

ख. उत्पाद के फैक्ट्री बाह्य मूल्य से उत्पाद के उत्पादन में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल (प्रत्यक्ष या अप्रत्यक्ष रूप से) को घटाकर (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और उसमें से वारंटी लागत को घटाकर।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर, उसमें से कर पश्चात लाभ, वारंटी लागत को घटाया जाता है, उसमें से उत्पादों के उत्पादन (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ लिया जा सकता है) में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल के योग को घटाया जाता है और बिक्री और विपणन खर्च को घटाया जाता है।

9.2 सामग्री के कुल बिल (कुल-बीओएम) की गणना उपलब्ध आंकड़ों पर आधारित निम्नलिखित में से किसी एक के आधार पर की जा सकती है। इनमें से प्रत्येक गणना के सुसंगत परिणाम प्राप्त होने चाहिए।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है)।

ख. उत्पाद के फैक्टरी बाह्य मूल्य से कर पश्चात लाभ और वारंटी लागतों को घटाया जाता है।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर उसमें से कर पश्चात लाभ, वारंटी लागत, बिक्री और विपणन खर्च घटाया जाता है।

9.3 निम्नलिखित फॉर्मूला के अनुसार प्रस्तुत जानकारी के आधार पर घरेलू मूल्य-वृद्धि के प्रतिशत की गणना की जा सकती है:

स्थानीय सामग्री/घरेलू मूल्य-वृद्धि का प्रतिशत $= \frac{\text{डीओएम} - \text{बीओएम}}{\text{कुल} - \text{बीओएम}} \times 100$

यह सिफ़ारिश की जाती है कि आकलन करने वाली प्रत्येक एजेंसी को उपरोक्त सूत्रों में से कम से कम दो का उपयोग करके स्थानीय सामग्री/घरेलू मूल्य-वृद्धि की गणना करनी चाहिए ताकि इस संबंध में आकलन को मान्य किया जा सके और यह सुनिश्चित किया जा सके कि दावाकृत घरेलू मूल्य सुसंगत है।

10. स्थानीय सामग्री/घरेलू मूल्यवृद्धि का सत्यापन

क. निविदा, बोली प्रक्रिया या सिफ़ारिश के समय स्थानीय आपूर्तिकर्ता स्व-प्रमाणन प्रदान करेगा कि प्रसतावित की गई वस्तुएं न्यूनतम स्थानीय सामग्री की आवश्यकताओं को पूरा करती हैं और उस स्थान (स्थानों) का विवरण देगा, जिस पर स्थानीय मूल्य वृद्धि की गई है।

ख.10 करोड़ रुपए से अधिक मूल्य की क्रय के मामलों में, स्थानीय आपूर्तिकर्ता स्थानीय सामग्री का प्रतिशत देते हुए कंपनी के सांविधिक लेखा परीक्षक (कंपनियों के मामले में) या लागत लेखापरीक्षक या किसी पेशेवर लागत लेखाकार या पेशेवर चार्टेड लेखाकार (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाणपत्र उपलब्ध कराएगा।

ग. यदि किसी इलेक्ट्रॉनिक उत्पाद के संबंध में स्थानीय सामग्री/घरेलू मूल्य वृद्धि के संबंध में बोलीकर्ता के दावे के खिलाफ क्रय एजेंसी या संबंधित मंत्रालय/विभाग द्वारा शिकायत प्राप्त की जाती है, तो उसे एसटीक्यूसी के पास भेजा जाएगा।

घ. एसटीक्यूसी को संदर्भित कोई भी शिकायत 4 सप्ताह के भीतर निपटा दी जाएगी। बोलीकर्ता को एसटीक्यूसी हेतु किसी इलेक्ट्रॉनिक उत्पाद में दावा की गई घरेलू मूल्य वृद्धि के समर्थन में आवश्यक दस्तावेज प्रस्तुत करने की आवश्यकता होगी। यदि बोलीकर्ता के द्वारा कोई जानकारी प्रस्तुत नहीं की जाती है, तो ऐसी प्रयोगशालाएं दावे की वास्तविकता को सिद्ध करने के लिए अगली आवश्यक कार्रवाई कर सकती हैं ।

ड़. 2 लाख रुपए या खरीदे जा रहे घरेलू रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों की कीमत का 1% शिकायत शुल्क (5 लाख रुपए की अधिकतम सीमा के अध्यधीन), जो भी अधिक हो, का डिमांड ड्राफ्ट द्वारा भुगतान किया जाएगा, जो एसटीक्यूसी में जमा जमा होगा। यदि शिकायत गलत पाई जाती है, तो शिकायत शुल्क जब्त कर लिया जाएगा। यदि, शिकायत को बरकरार रखा जाता है और काफी हद तक सही पाया जाता है तो शिकायतकर्ता को जमा शुल्क बिना किसी ब्याज के वापस कर दिया जाएगा।

च. सामान्य वित्तीय नियमों के विनियम 175(1) (i) (h) के तहत अखंडता संहिता के उल्लंघन में झूठी घोषणाएं की जाएगी तो इसके लिए एक बोलीकर्ता या उसके उत्तराधिकारियों पर सामान्य वित्तीय नियमों के विनियम 151(iii) के अनुसार दो साल तक के लिए रोक लगा दी जाएगी, इसके साथ-साथ कानून के तहत स्वीकार्य होने वाली अन्य कार्रवाई भी की जा सकती है।

11. इलेक्ट्रॉनिक उत्पाद अधिसूचना के कार्यान्वयन की निगरानी के लिए नोडल मंत्रालय एमईआईटीवाई होगा।

12. यदि प्रश्न उठता है कि क्या खरीदी जा रही कोई वस्तु एक इलेक्ट्रॉनिक उत्पाद है, जिसे सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत शामिल किया जाना है, तो इस मामले को स्पष्टीकरण के लिए इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय को संदर्भित किया जाएगा।

सौरभ गौड़, संयुक्त सचिव

अनुबंध

यान्त्रिकी और डाई कट कलपुर्ज़े की सूची

क. यान्त्रिकी (मैकेनिक्स)

1. बैटरी कवर (एचएस 39209999)
2. फ्रंट कवर (एचएस 39209999)
3. फ्रंट कवर (जिंक कास्टिंग के साथ) (एचएस 39209999)
4. मिडल कवर (एचएस 39209999)
5. जीएसएम एंटीना/किसी भी प्रौद्योगिकी का एंटीना (एचएस 39209999)
6. साइड की (एचएस 85389000)
7. मेन लेंस (एचएस 39209999)
8. कैमरा लेंस (एचएस 39209999)
9. पेंच (एचएस 73181500)
10. माइक्रो रबर केस (एचएस 40169990)
11. सेंसर रबड़ केस/सीलबंद गैसकेटों सहित सीलबंद गैसकेट/रबड़ केस यानि एसबीआर, ईपीडीएम, सीआर, सीएस, सिलिकॉन और सभी अन्य विशेष रबड़ या संयोजन/रबड़ के संयोजन (एचएस 40169990)

    11.1 पीयू केस /सीलबंद गैसकेट (एचएस 39269091) - सीलबंदी गैसकेट/केस की तरह पॉलीयुरेथेन फोम की अन्य सामग्री।

    11.2 सीलबंदी गास्केट/पीई, पीपी,ईपीएस, पीसीसे केस और सभी अन्य विशेष बहुलक या संयोजन/बहुलकों का संयोजन(एच एस 39269099)

12. सिम सॉकेट/अन्य मैकेनिकल (यान्त्रिकी) मदें (धातु) (एचएस 73269099)
13. सिम सॉकेट/अन्य मैकेनिकल (यान्त्रिकी) मदें (प्लास्टिक) (एचएस 39269099)
14. बैक कवर (एचएस 39209999)

ख. डाई कट कलपुर्ज़े

1.सुचालक कपड़ा (एचएस 39269099)
2. ऊष्मा उत्सर्जक स्टीकर बैटरी कवर (एचएस 39199090)
3. स्टीकर-बैटरी स्लॉट (एचएस 39199090)
4. मैन लेंस के लिए प्रोटेक्टिव फिल्म (एचएस 39199090)
5. एलसीडी एफपीसी के लिए माइलर (एचएस 39199090)
6. एलसीडी सुचालक फोम (एचएस 39269099)
7. फिल्म-फ्रंट फ्लैश (एचएस 39199090)
8. एलसीडी फोम (एचएस 39269099)
9. बीटी फोम (एचएस 39269099)

MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY

(IPHW DIVISION)

NOTIFICATION

New Delhi, the 7th September, 2020

Subject : Public Procurement (Preference to Make in India) Order 2017-Notifying Electronic Products in furtherance of the Order

Reference : Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019 and 04.06.2020

F. No. W-43/4/2019-IPHW-MeitY.—The Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019 and 04.06.2020, to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

2. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017] notified vide reference cited above, and in supersession of the Electronic Product Notification Nos.33(1)/2017-IPHW dated 14.09.2017 and 33(5)/2017-IPHW dated 01.08.2018 issued thereunder, the Ministry of Electronics and Information Technology (MeitY) hereby notifies that preference shall be provided by all procuring entities to locally manufactured Electronic Products as per the aforesaid Order, as amended from time to time.

3. For the purpose of this notification:

a. The definition of Class-I local supplier, Class-II local supplier and Non-local supplier shall be as per paragraph 2 of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time. The mechanism for calculation of local content has been prescribed for each notified Electronic Product in this notification, in accordance with paragraph 5 of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time.

b. Paragraph 3A of the DPIIT PPP-MII Order 2017 No.P-45021/2/2017-PP(BE-II) dated 04.06.2020, as amended from time to time, shall be referred for percentage of procurement for which preference to domestically manufactured Electronic Products is to be provided (in value terms).

4. Following Electronic Products are notified under the Public Procurement (Preference to Make in India) Order 2017:

4.1 <u>Desktop Personal Computers (PCs)</u>

(A) Definition:

For the purpose of this Notification, a Desktop PC shall necessarily consist of a CPU, Memory, Hard disk drive, Keyboard, Mouse and a separate or integrated display unit and should be able to operate independently.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of Desktop PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/stages for manufacture of Desktop PC	**Value addition/local content required for the input to be classified as domestic BOM**
1	**2**
Main Board / Motherboard and CPU / GPU	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU/ GPU** and excluding

	the value of bare PCB. However, the weightage of total value of CPU shall not exceed 30% of the total BOM of the Desktop PC.
Memory Module	Domestic PCB Assembly* and testing from imported / domestically manufactured memory chips** and parts / components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB.
Hard Disk Drive / Solid State Drive (SSD)	Domestic PCB Assembly* and final product assembly and testing from imported / domestically manufactured parts and components, excluding the value of bare PCB.
LCD / LED Monitor	Domestic assembly and testing of LCD / LED Monitor from parts consisting of imported/domestically assembled LCD / LED Panel and Domestic PCB Assembly*, Domestic plastic moulding and Domestic stamping of metal parts, excluding the value of bare PCB.
DVD Drive	Domestic assembly and testing from imported / domestically manufactured parts and components.
Cabinet + SMPS	Domestically manufactured Cabinet and Domestic PCB Assembly* and the final assembly and testing of SMPS from imported/ domestically manufactured parts and components, subject to the condition that the domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS").
Keyboard/Mouse	Domestic PCB Assembly* and the final assembly and testing from imported / domestically manufactured parts and components.
Bare PCB	Domestically manufactured from imported / domestically manufactured inputs.
(i) Final Assembly / Testing and (ii) Design / Development	(i) Domestically assembled/tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU/ processor(s) parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.2 Thin Clients

(A) Definition:

For the purpose of this Notification, a Thin Client (TC) shall necessarily consist of a CPU, Memory, DOM, Keyboard, Mouse and a separate or integrated display unit and should be able to operate independently.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of a Thin Client would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM / stages for manufacture of Thin Client	Value addition / local content required for the input to be classified as domestic BOM
1	2
Main Board / Motherboard and CPU	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 30% of the total BOM of the Thin Client.
Memory Module/ DOM	Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB.
SMPS/ Power Adapter	Domestically PCB Assembly* and the final assembly and testing of SMPS/ Power Adapter from imported/ domestically manufactured parts and components, subject to the condition that the domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS").
LCD/ LED Monitor	Domestic assembly and testing of LCD/ LED Monitor from parts consisting of imported/ domestically assembled LCD/ LED Panel and Domestic PCB Assembly*, Domestic plastic moulding and Domestic stamping of metal parts, excluding the value of bare PCB.
Cabinet	Domestically manufactured.
Keyboard/Mouse	Domestic PCB Assembly* and the final assembly and testing from imported / domestically manufactured parts and components.
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
(i) Final Assembly/ Testing and (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.3 Laptop Personal Computers (PCs)

(A) Definition:

For the purpose of this Notification, a Laptop PC (commonly known in the market as Laptop/ Notebook/ Netbook/ Ultrabook, etc.) shall necessarily consist of a CPU, Memory, Hard disk drive, Keyboard, Touchpad and/ or Trackpoint, an integrated display unit, integrated battery and should be able to operate independently.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of a Laptop PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Laptop PC	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Main Board/ Motherboard and CPU/ GPU	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU/ GPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 35% of the total BOM of the Laptop PC.
Power Module	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components.
Memory Module	Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB.
Hard Disk Drive/ Solid State Drive (SSD)	Domestic PCB Assembly* and final product assembly and testing from imported/ domestically manufactured parts and components, excluding the value of bare PCB.
Display Panel (LCD, LED, etc.)	Domestic assembly into the Back Cover and Bezel and final testing from imported/ domestically assembled Display Panel, LED Back light, Antennae, excluding the value of the Back Cover and Bezel.
DVD Drive	Domestic assembly and testing from imported / domestically manufactured parts and components.
Power Adapter	Domestic assembly with domestic PCB Assembly* and final testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter").
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Keyboard/ Touchpad and/ or Trackpoint	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Battery	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Cabinet/ Chassis of Laptop including bottom cover, back cover, Keyboard face bezel and Display face bezel and Hinges	Domestically manufactured through injection moulding/ stamping using imported/ domestic inputs.
(i) Final Assembly/ Testing and (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU/ processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.4 Computer Monitors

(A) Definition:

For the purpose of this Notification, a Computer Monitor (commonly known in the market as Monitor) shall necessarily consist of a LCD/ LED Display assembly, Logic card, Power Supply Adaptor and Cabinet with Display Ports for connecting it to a Desktop PC or Laptop PC or Tablet PC.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of a Computer Monitor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Computer Monitor	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Logic Cards/ Micro controller	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components including value of Semiconductors** and excluding the value of bare PCB.
LCD/ LED Panel	Domestic integration and testing of imported/ domestically assembled LCD/ LED Panel*** into the Monitor Cabinet/ Chassis, excluding the value of the Cabinet/ Chassis. However, the weightage of total value of LCD/ LED Panel shall not exceed 35% of the total BOM of the Computer Monitor.
Cables	Domestically manufactured and tested from imported/ domestically manufactured inputs.
Power Adapter	Domestic assembly with domestic PCB Assembly* and final testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter").
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Cabinet/ Chassis	The Monitor Bezel, Back cover, Stand, Base and Chassis wherein the plastic mouldings and the stamping of metal parts is done domestically using imported/ domestic inputs.
(i) Final Assembly/ Testing and (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU processor(s)/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

**** This shall be reviewed when LCD/LED Panel manufacturing of Computer Monitors (of each size and type) in India is operational.*

4.5 Tablet Personal Computers (PCs)

A. **Definition**:

For the purpose of this Notification, a Tablet PC shall necessarily consist of an Integrated Motherboard with on board CPU/Processor, Memory and Power Module; Display Panel (Touch Panel + LCD/LED Module) and integrated battery and should be able to operate independently.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of Tablet PC would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Tablet PC	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Integrated Motherboard with on board CPU/ GPU/ Processor	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including value of Semiconductors** and Processor/CPU/ GPU** and excluding the value of bare PCB. However, the weightage of total value of CPU shall not exceed 35% of the total BOM of the Tablet PC.
Memory and Power Module	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, excluding the value of bare PCB.
Display Panel (Touch Panel + LCD/ LED Module)	Domestic assembly and testing from imported/ domestically manufactured Touch Panel, LCD/ LED Module or combination, subject to the condition that backlight assembly and testing of Display Panel shall be done domestically.
Power Adapter	Domestic assembly and testing from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter").
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Casing	Domestically manufactured Casing.
Battery	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Accessories (Camera, Speaker, WiFi Antenna, etc.)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
(i) Final Assembly/ Testing and (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU/ GPU/ processor/ parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational*

4.6 Dot Matrix Printers

(A) Definition:

A Dot Matrix Printer is a type of impact printer that forms dot on paper by a metal pin of diameter 0.2 mm to 0.3 mm which is driven by electromagnet based on solenoid principle and required character matrix is produced by horizontal and vertical resolution of dot matrix printhead. Dot Matrix Printer can create carbon copies and carbonless copies based on mechanical pressure of pin.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of a Dot Matrix Printer would be the sum of the cost of main inputs specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Dot Matrix Printer	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Main PCB	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "Main PCB" will be minimum 15% (of the total value of parts and components used in the manufacture of "Main PCB"), excluding the value of bare PCB.
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
SMPS	Domestic assembly and testing from imported/ domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 20% (of the total value of parts and components used in the manufacture of "SMPS").
Carriage Motors and Paper Feed Motors	Imported as sub-assembly and tested domestically along with main Printer Mechanism.
Front Control Panel	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Home Position/Paper End Sensors	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Main Printer Cabinet and other small plastic components	Domestic moulding of Printer Cabinet and other parts.
Printer Mechanism Assembly	Domestic assembly using domestically manufactured Rubber Platens, small rubber parts, sheet metal components, plastic gears and other plastic parts with turned steel shafts and above mentioned sensors and Motors.
Print Heads and Interconnecting Cables	Imported as sub-assembly and tested domestically along with main Printer Mechanism.
(i) Final Assembly/ Testing and (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts/ components on the bare PCB using the SMT process should mandatorily be done in India.*

4.7 Smart Cards

(A) Definition:

For the purpose of this Notification, Smart Card is usually a Credit Card sized plastic Card with an Integrated Circuit (IC) contained inside. The IC contains a microprocessor and memory. Smart Cards can be contact, contactless or dual interface (both contact and contactless). Some of the applications of Smart Card are Identity Card, Banking Card, Health Card, Vehicle Registration Card etc.

I(B) Mechanism for calculation of local content for Contact Smart Cards

The domestic Bill of Material (BOM) of a Contact Smart Card would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Contact Smart Card	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Plastic Card Body	Domestic manufacturing including sheet cutting & punching, printing, lamination and testing using imported/ domestically manufactured raw material, parts and components.
IC Chip Module	Domestic assembly, packaging and testing of IC Chip Module using imported/ domestically manufactured raw material, parts and components*.
Milling and Embedding of IC Chip Module on Plastic Card	Milling and Embedding of IC Chip Module on Plastic Card done domestically.
(i) Final Assembly and Testing (ii) Design/ Development	(i) Domestically assembled/tested and (ii) Intellectual Property (IP) resident in India for any of the above items, including fusion of domestically developed Operating System. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** This shall be reviewed when the Semiconductor FAB in India is operational.*

II(B) Mechanism for calculation of local content for Contactless Smart Cards

The domestic Bill of Material (BOM) of Contactless Smart Card would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/stages for manufacture of Contactless Smart Card	**Value addition/local content required for the input to be classified as domestic BOM**
1	**2**
Plastic Card Body	Domestic manufacturing including sheet cutting & punching, printing, lamination and testing using imported/ domestically manufactured raw material, parts and components.
Card inlay (Antenna)	Domestic assembly and testing from imported/ domestically manufactured raw material, parts and components.
IC Chip Module	Domestic assembly, packaging and testing of IC Chip Module using imported/ domestically manufactured raw material, parts and components*.
Milling and Embedding of IC Chip Module on Plastic Card	Milling and Embedding of IC Chip Module on Plastic Card done domestically.

(i) Final Assembly and Testing (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items, including fusion of domestically developed Operating System. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.8 LED Products

(A) Definition:

For the purpose of this Notification, LED products are those whose function is to utilize light produced by LEDs and spanning applications in the areas of: (i) Illumination, (ii) Optical Displays including True LED TVs, (iii) Backlighting, (iv) Signalling & Indication and (v) Transportation.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of LED Products would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table. However, the weightage of total value of (d) Heat Sink or Thermal Management Solutions, (e) Secondary Optics and (f) System Fixture and Fitting shall not exceed 20% of the total BOM of the LED Product:

Main inputs in BOM/ stages for manufacture of LED Products	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
LED Emitter	Packaging from imported/ domestically fabricated Bare LED Die, subject to the condition that the Bare LED Die shall be domestically fabricated using imported/ domestically manufactured inputs.
Driving Electronics	Domestic assembly from imported/ domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components (excluding the value of bare PCB) used in the assembly of "Driving Electronics" will be minimum 30% of the total value of parts and components used in the manufacture of "Driving Electronics".
Bare PCB including MCPCB	Domestically manufactured using imported/ domestically manufactured inputs.
Heat Sink or Thermal Management Solutions	Domestically manufactured using imported/ domestically manufactured inputs.
Secondary Optics	Domestically manufactured using imported/ domestically manufactured inputs.
System Fixture and Fitting	Domestically manufactured.
Final Assembly/ Testing	Domestically assembled/ tested meeting Indian Standards as notified from time to time.

4.9 Biometric Access Control/Authentication Devices

(A) Definition:

For the purpose of this Notification, Biometric Access Control/ Authentication Device shall include *inter-alia* a Finger Print Sensor/ Iris Sensor, Controller Module and Power supply. It may or may not contain a display unit. Some of the applications of Biometric Access Control/ Authentication Device are Physical access control, Time and Attendance control etc.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of Biometric Access Control/ Authentication Device would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Biometric Access Control/ Authentication Device	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Finger Print Sensor/ Iris Sensor	Domestically manufactured as notified (refer Paragraphs 4.10 and 4.11).
Main PCB (Controller Module)	Domestic assembly and testing from imported / domestically manufactured parts and components, excluding the value of bare PCB.
Bare PCB	Domestically manufactured from imported / domestically manufactured inputs.
Power Supply/ Battery(if separate)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Display Unit	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Optional features such as Camera, Keyboard, RFID, Smart Card Reader, GPRS Module, Wi-Fi, Blue Tooth etc.	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Plastic Housing	Domestically manufactured from imported/ domestically manufactured inputs.
USB Cables	Domestically manufactured from imported/ domestically manufactured inputs.
(i) Final Assembly and Testing (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

4.10 <u>Biometric Finger Print Sensors</u>

(A) Definition:

For the purpose of this Notification, Biometric Finger Print Sensor consists of a Controller Module, CMOS Sensor and Optics. The applications of the Biometric Finger Print Sensor are personal identification and verification, etc.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of Biometric Finger Print Sensor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/stages for manufacture of Biometric Finger Print Sensor	**Value addition/local required for the input to be classified as domestic BOM**
1	**2**
Main PCB (Controller Module)	Domestic assembly and testing using imported / domestically manufactured parts and components, excluding the value of bare PCB.

Optics	Domestically manufactured from imported / domestically manufactured inputs.
CMOS Sensor	Domestic assembly, packaging and testing of CMOS Sensor using imported/ domestically manufactured inputs*.
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Plastic Housing	Domestically manufactured from imported / domestically manufactured inputs.
USB Cables	Domestically manufactured from imported / domestically manufactured inputs.
(i) Final Assembly and Testing (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.11 Biometric Iris Sensors

(A) Definition:

For the purpose of this Notification, Biometric Iris Sensor consists of a Controller Module, CMOS Sensor and Optics. The applications of the Biometric Iris Sensor are personal identification and verification, etc.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of Biometric Iris Sensor would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/stages for manufacture of Biometric Iris Sensor	**Value addition/local content required for the input to be classified as domestic BOM**
1	**2**
Main PCB (Controller Module)	Domestic assembly and testing using imported / domestically manufactured parts and components except value of bare PCB.
Optics	Domestically manufactured from imported/ domestically manufactured inputs.
CMOS Sensor	Domestic assembly, packaging and testing of CMOS Sensor using imported/ domestically manufactured inputs*.
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Plastic Housing	Domestically manufactured from imported/ domestically manufactured inputs.
USB Cables	Domestically manufactured from imported/ domestically manufactured inputs.
(i) Final Assembly and Testing (ii) Design/ Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in domestic BOM.

**This shall be reviewed when the Semiconductor Fab in India is operational.*

4.12 Servers

(A) Definition:

For the purpose of this Notification, a Server shall necessarily consist of a Mother Board, CPU, Memory (RAM), Hard Disk Drive (HDD)/ Solid State Storage Drive (SSD), Power Supply Unit (SMPS), Chassis, Connecting Cables and Firmware & OS.

(B) Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of a Server would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/ stages for manufacture of Server	**Value addition /local content required for the input to be classified as domestic BOM**
1	**2**
Server Board/ Mother Board and CPU(s)/ GPU(s)	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU(s)/ GPU(s)** and excluding the value of bare PCB.
Memory Module	Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB.
Hard Disk Drive/ Solid State Storage Drive (SSD)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Cabinet + SMPS	Domestically manufactured Cabinet and domestic assembly and testing of SMPS from imported / domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 25% (of the total value of parts and components used in the manufacture of "SMPS").
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Accessories (Power Cables, Connectors, etc.)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
(i) Final Assembly and Testing (ii) Design and Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU(s)/ processor(s), parts/ components on the bare PCB using the SMT process should mandatorily be done in India*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

4.13 Cellular Mobile Phones

(A) Definition:

For the purpose of this Notification, a Cellular Mobile Phone (Feature Phone or Smart Phone) shall necessarily consist of a Main Printed Circuit Board (PCB), Battery Pack, Display Unit, Key Pad/ Touch Panel, Charger/ Adapter, Microphone & Receiver, Vibrator Motor/ Ringer and Mechanics.

(B) Mechanism for calculation of local content:

The domestic BOM of Cellular Mobile Phones would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Main inputs in BOM/stages for manufacture of Cellular Mobile Phone	**Value addition/ local content required for the input to be classified as domestic BOM**
1	**2**
Main PCB*	Domestic assembly and testing from imported/ domestically manufactured parts and components including Processor and Semiconductor** BOM (i.e the Semiconductor Chips and Modules on Main PCB), and excluding value of bare PCB.
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Battery Pack	Domestic assembly and testing of imported/ domestically manufactured inputs.
Charger/ Adapter	Domestic assembly and testing from imported/ domestically manufactured inputs.
Wired Headset	Domestic assembly and testing from imported/ domestically manufactured inputs.
Mechanics***	Domestic assembly and testing from imported/ domestically manufactured inputs.
Die Cut Parts***	Domestic assembly and testing from imported/ domestically manufactured inputs.
Microphone and Receiver	Domestic assembly and testing from imported/ domestically manufactured inputs.
Key Pad	Domestic assembly and testing from imported/ domestically manufactured inputs
USB Cable	Domestic assembly and testing from imported/ domestically manufactured inputs.
Camera Module	Domestic assembly and testing from imported/ domestically manufactured inputs.
Connectors	Domestic assembly and testing from imported/ domestically manufactured inputs.
Display Unit	Domestic assembly and testing from imported/ domestically manufactured inputs.
Touch Panel/ Cover Glass Assembly	Domestic assembly and testing from imported/ domestically manufactured inputs.
Vibrator Motor/ Ringer	Domestic assembly and testing from imported/ domestically manufactured inputs.
(i) Final Assembly and Testing (ii) Design and Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the processor/ components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational*

****Refer Annexure*

5. The Notification comes into effect immediately. This Notification shall remain valid till the revised Notification is issued.

6. No Electronic Product Notification under the Public Procurement (Preference to Make in India) Order 2017 shall have retrospective effect.

7. Purchase Preference shall be provided as per the provisions cited in the Public Procurement (Preference to Make in India) Order 2017 dated 04.06.2020 for the procurement of aforesaid electronics products.

8. The notification would also be applicable to all Central Schemes (CS)/ Central Sector Schemes (CSS) for the procurement of electronic products made by States and local bodies, if project or scheme is fully or partially funded by Government of India.

9. Procedure for calculating local content/ domestic value addition

9.1 Bill of Material sourced from domestic manufacturers (Dom-BOM) may be calculated based on one of the followings depending on data available. Each of these calculations should provide consistent result.

a. Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) and which have not been imported directly or through a domestic trader or an intermediary.

b. Ex-Factory Price of product minus profit after tax minus sum of imported Bill of Material used (directly or indirectly) as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) minus warranty costs.

c. Market price minus post-production freight, insurance and other handling costs minus profit after tax minus warranty costs minus sum of Imported Bill of Material used as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken) minus sales and marketing expenses.

9.2 Total Bill of Material (Total-BOM) may be calculated based on one of the following depending on data available. Each of these calculations should provide consistent result.

a. Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken).

b. Ex-Factory Price of product minus profit after tax, minus warranty costs.

c. Market price minus post-production freight, insurance and other handling costs minus profit after tax, minus warranty costs minus sales and marketing expenses.

9.3 The percentage of domestic value-addition may be calculated based on information furnished as per the following formula:

$$\text{Percentage of local content/ domestic value-addition} = \frac{\text{Dom-BOM}}{\text{Total-BOM}} \times 100$$

It is recommended that each agency assessing should calculate the domestic local content/ value-addition using at least two of the above formulae so as to validate the assessments in this regard and ensure that the domestic value addition that is claimed is consistent.

10. Verification of local content/ Domestic Value Addition

a. The local supplier at the time of tender, bidding or solicitation shall provide self-certification that the item offered meets the minimum local content and shall give details of the location(s) at which the local value addition is made.

b. In cases of procurement for a value in excess of Rs. 10 crore, the local supplier shall provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

c. In case a complaint is received by the procuring agency or the concerned Ministry/Department against the claim of a bidder regarding local content/ domestic value addition in an electronic product, the same shall be referred to STQC.

d. Any complaint referred to STQC shall be disposed of within 4 weeks. The bidder shall be required to furnish the necessary documentation in support of the domestic value addition claimed in an electronic product to STQC. If no information is furnished by the bidder, such laboratories may take further necessary action, to establish the bonafides of the claim.

e. A complaint fee of Rs.2 Lakh or 1% of the value of the domestically manufactured electronic products being procured (subject to a maximum of Rs. 5 Lakh), whichever is higher, to be paid by Demand Draft to be deposited with STQC. In case, the complaint is found to be incorrect, the complaint fee shall be forfeited. In case, the complaint is upheld and found to be substantially correct, deposited fee of the complainant would be refunded without any interest.

f. False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules for which a bidder or its successors can be debarred for up to two years as per Rule 151 (iii) of the General Financial Rules along with such other actions as may be permissible under law.

11. MeitY shall be the Nodal Ministry to monitor the implementation of the Electronic Products Notification.

12. In case of a question whether an item being procured is an electronic product to be covered under the Public Procurement (Preference to Make in India) Order 2017, the matter would be referred to the Ministry of Electronics and Information Technology for clarification.

SAURABH GAUR, Jt. Secy.

Annexure

Indicative List of Mechanics and Die Cut Parts

A. Mechanics

1. Battery Cover (HS 39209999)
2. Front Cover (HS 39209999)
3. Front Cover (With Zinc Casting) (HS 39209999)
4. Middle Cover (HS 39209999)
5. GSM Antenna/ Antenna of any technology (HS 39209999)
6. Side Key (HS 85389000)
7. Main Lens (HS 39209999)
8. Camera Lens (HS 39209999)
9. Screw (HS 73181500)
10. Mic Rubber Case (HS 40169990)
11. Sensor Rubber Case/ Sealing Gasket including sealing gaskets/ cases from Rubbers like SBR, EPDM, CR, CS, Silicone and all other individual rubbers or combination/ combinations of rubbers (HS 40 1 69990)
    - 11.1 PU Case/ Sealing Gasket (HS 39269091) - Other articles of Polyurethane foam like sealing gaskets/ cases.
    - 11.2 Sealing Gaskets/ Cases from PE, PP, EPS, PC and all other individual polymers or combination/ combinations of polymers (HS 39269099)
12. SIM Socket/ Other Mechanical items (Metal) (HS 73269099)
13. SIM Socket/ Other Mechanical items (Plastic) (HS 39269099)
14. Back Cover (HS 39209999)

B. Die Cut Parts

1. Conductive Cloth (HS 39269099)
2. Heat Dissipation Sticker Battery Cover (HS 39199090)
3. Sticker-Battery Slot (HS 39199090)
4. Protective Film for Main Lens (HS 39199090)
5. Mylar for LCD FPC (HS 39199090)
6. LCD Conductive Foam (HS 39269099)
7. Film-Front Flash (HS 39199090)
8. LCD Foam (HS 39269099)
9. BT Foam (HS 39269099)

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

MANOJ KUMAR VERMA

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-21102023-249586
CG-DL-E-21102023-249586

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 4417] नई दिल्ली, बृहस्पितवार, अक्तूबर 19, 2023/आश्विन 27, 1945
No. 4417] NEW DELHI, THURSDAY, OCTOBER 19, 2023/ASVINA 27, 1945

इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

(आईपीएचडब्ल्यू डिवीजन)

अधिसूचना

नई दिल्ली, 12 अक्तूबर, 2023

विषय: दिनांक 07.09.2020 के इलेक्ट्रॉनिक उत्पाद अधिसूचना फ़ा.सं.डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई के खंड संख्या 4.12 (सर्वर) में संशोधन संबंधी।

का.आ. 4591(अ).—दिनांक 15.06.2017 के उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 जिसे दिनांक 28.05.2018, 29.05.2019, 04.06.2020 और 16.09.2020 के आदेशों द्वारा यथा संशोधित किया गया, को आगे बढ़ाते हुए दिनांक 07.09.2020 की इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) की राजपत्र अधिसूचना फा.सं. डब्लयु-43/4/2049-आईपीएचडब्ल्यु-एमईआईटीवाई के द्वारा इलेक्ट्रॉनिक उत्पादों को अधिसूचित किया गया था।

2. सर्वर के मामले में, खंड 4.12 (ख): स्थानीय सामग्री की गणना के लिए तंत्र को निम्नानुसार संशोधित किया गया है और यह तत्काल प्रभाव से लागू होगा:

Page 120 of 1204 : C098-TENDER DOC-C098-000-81-41-CD-T-8105 : Rev. A

स्थानीय सामग्री की गणना के लिए संशोधित तंत्र:

सर्वर की घरेलू सामग्री बिल (बीओएम) निम्नलिखित तालिका के कॉलम 1 में विनिर्दिष्ट मुख्य इनपुट की लागत के योग के बराबर होगा, बशर्ते कि इनपुट अलग-अलग रूप से तालिका के कॉलम 2 में विनिर्दिष्ट मूल्य वर्धन आवश्यकता को पूरा करें। हालांकि, 'एड ऑन कंट्रोलर' के कुल मूल्य का वेटेज **सर्वर** के कुल बीओएम के **3%** से अधिक नहीं होगा।

बीओएम के प्रमुख इनपुट/ सर्वर के विनिर्माण के लिए चरण	**मूल्य वर्धन/इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए अपेक्षित स्थानीय सामग्री**
1	2
सर्वर बोर्ड/मदर बोर्ड और सीपीयू(एस)/जीपीयू(एस)	सेमीकंडक्टर्स** और सीपीयू (एस) / जीपीयू (एस)** को शामिल करके" और बेअर पीसीबी के मूल्य को छोड़कर आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू पीसीबी असेंबली* और परीक्षण
मेमोरी मॉड्यूल	पीसीबी असेंबली* और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित मेमोरी चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण।
हार्ड डिस्क ड्राइव/ सॉलिड स्टेट स्टोरेज ड्राइव (एसएसडी)	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण।
कैबिनेट + एसएमपीएस	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू रूप से घरेलू स्तर पर विनिर्मित कैबिनेट और एसएमपीएस का घरेलू असेंबली और परीक्षण, इस शर्त के अध्यधीन कि "एसएमपीएस" की असेंबली में उपयोग किए गए घरेलू स्तर पर विनिर्मित भागों और संघटकों का मूल्य न्यूनतम 25% होगा ("एसएमपीएस " के विनिर्माण में उपयोग किए जाने वाले भागों और संघटकों का कुल मूल्य)
बेयर पीसीबी	आयातित/घरेलू विनिर्मित इनपुट से घरेलू स्तर पर विनिर्मित
सहायक उपकरण (पावर केबल, कनेक्टर, आदि)	आयातित/घरेलू स्तर पर विनिर्मित भागों और संघटकों से घरेलू असेंबली और परीक्षण।
ऐड-ऑन कंट्रोलर I. आरएआईडी कंट्रोलर/एडाप्टर II. नेटवर्क इंटरफ़ेस कंट्रोलर	पीसीबी असेंबली* और बेअर पीसीबी के मूल्य को छोड़कर, आयातित/घरेलू स्तर पर विनिर्मित बेअर पीसीबी पर आयातित/घरेलू स्तर पर विनिर्मित चिप्स** और कलपुर्जों/संघटको से घरेलू परीक्षण।
(i) फाइनल असेंबली और टेस्टिंग (ii) डिजाइन और विकास	(i) घरेलू स्तर पर असेम्बल/परीक्षित और (ii) उपरोक्त आइटमों में से किसी आइटम के लिए बौद्धिक सम्पदा (आईपी) अधिकार रखने वाला व्यक्ति भारत का निवासी हो । उपरोक्त आइटमों में से किसी आइटम के लिए भारत में (आईपी) निवासी के मूल्य को घरेलू बीओएम में उसके मूल्य से घटाया जाएगा।

** यह आवश्यक है कि सीपीयू (एस)/जीपीयू (एस)/प्रोसेसर (एस) के प्रिंटेड सर्किट बोर्ड असेंबली (पीसीबीए), एसएमटी प्रक्रिया का उपयोग कर बेयर पीसीबी पर भागों/संघटकों को अनिवार्य **रूप से** भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर फैब चालू होने पर इसकी समीक्षा की जाएगी।*

3. दिनांक 07.09.2020 की एमईआईटीवाई की राजपत्र अधिसूचना फ़ा.सं.डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई के अन्य सभी नियम और शर्तें अपरिवर्तित रहेंगी।

[फा. सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई]

आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY

(IPHW Division)

NOTIFICATION

New Delhi, the 12th October, 2023

Subject: Amendment to Electronic Products Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020 w.r.t. Clause No. 4.12 (Servers) – reg.

S.O. 4591(E).— Electronic Products were notified vide Ministry of Electronics and Information Technology (MeitY) Gazette Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020, in furtherance of the Department for Promotion of Industry and Internal Trade (DPIIT) Public Procurement (Preference to Make in India) Order 2017 dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020.

2. In case of Servers, Clause 4.12 (B): Mechanism for calculation of local content is amended as under and will be applicable with immediate effect:

Revised Mechanism for calculation of local content:

The domestic Bill of Material (BOM) of **Server** would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table. However, the weightage of total value of 'Add on Controller' shall not exceed **3%** of the total BOM of the **Server**.

Main inputs in BOM/ stages for manufacture of Server	**Value addition /local content required for the input to be classified as domestic BOM**
1	2
Server Board/ Mother Board and CPU(s)/ GPU(s)	Domestic PCB Assembly* and testing from imported/ domestically manufactured parts and components, including the value of Semiconductors** and CPU(s)/ GPU(s)** and excluding the value of bare PCB.
Memory Module	Domestic PCB Assembly* and testing from imported/ domestically manufactured memory chips** and parts/ components on imported/ domestically manufactured bare PCB, excluding the value of bare PCB.
Hard Disk Drive/ Solid State Storage Drive (SSD)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Cabinet + SMPS	Domestically manufactured Cabinet and domestic assembly and testing of SMPS from imported / domestically manufactured parts and components, subject to the condition that value of domestically manufactured parts and components used in the assembly of "SMPS" will be minimum 25% (of the total value of parts and components used in the manufacture of "SMPS").
Bare PCB	Domestically manufactured from imported/ domestically manufactured inputs.
Accessories (Power Cables, Connectors, etc.)	Domestic assembly and testing from imported/ domestically manufactured parts and components.
Add-on Controllers i. RAID Controller/Adapter	Domestic PCB Assembly* and testing from imported/ domestically manufactured chips** and parts/ components on imported/ domestically

ii. Network Interface Controllers	manufactured bare PCB, excluding the value of bare PCB.
(i) Final Assembly and Testing (ii) Design and Development	(i) Domestically assembled/ tested and (ii) Intellectual Property (IP) resident in India for any of the above items. The value of IP resident in India for any of the above items shall be reduced from its value in the domestic BOM.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the CPU(s)/ GPU(s)/ processor(s), parts/ components on the bare PCB using the SMT process should **mandatorily** be done in India*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

3. All other terms and conditions of MeitY Gazette Notification F.No.W-43/4/2019-IPHW-MeitY dated 07.09.2020 remain unchanged.

[F. No. W-43/4/2019-IPHW-MeitY]

ASHA NANGIA, Group Coordinator & Scientist 'G'

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

SARVESH KUMAR SRIVASTAVA

No. 13(7)/2022-EG-II
Government of India
Ministry of Electronics and Information Technology
Electronics Niketan, 6, CGO Complex, New Delhi-110003.

Dated: 17.08.2022

OFFICE MEMORANDUM

Subject: Exemption from Public Procurement (Preference to Make in India) Clause for procurement of various items – regarding

This has reference to the request made by the Unique Identification Authority of India (UIDAI), vide letter no. T-11014/07/2017-Tech/87 dated 07.06.2022, for seeking exemption from Public Procurement (Preference to Make in India) Clause for procurement of various information security tools/items.

2. The items requested by UIDAI for exemption along with their justification for exemption are listed in the table at **Annexure-1** (08 Items).

3. In this regard, the Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No.P-45021/2/2017-B.E-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020 to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

4. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017], Ministry of Electronics and Information Technology (MeitY) has notified the mechanism for calculation of local content for 13 Electronic Products vide Electronic Products Notification vide F.No.43/4/2019-IPHW-MeitY dated 07.09.2020; and Public Procurement (Preference to Make in India) Order 2019 for Cyber Security Products vide Notification No.1(10)/2017-CLES dated 06.12.2019.

5. In this regard, the undersigned is directed to convey the approval of Hon'ble Minister of Electronics and Information Technology for exemption from Public Procurement (Preference to Make in India) for procurement of the items requested by UIDAI (refer **Annexure-1**) as per Clause 14 of the Public Procurement (Preference to Make in India) Order 2017 notified vide DPIIT File No. P-45021/2/2017-B.E.-II dated 16.09.2020 with following conditions:

i. UIDAI will do a thorough check on Government e-Marketplace (GeM) for availability of the aforesaid items / services as per PPP-MII Order 2017 conditions before going for the exempted category of procurement.

Dir (IS) 20 Aug 22
DDG (IS) 23/8
Dhawan 24/8/22
846/CEO/UIDAI 17/8/22
149/DDG (ES & Engg.)/UIDAI 22/08/2022
DD/S
SO/IS

ii. Exemption shall be given for a maximum period of one year which may be reviewed any time after completion of six months.

iii. UIDAI shall adhere to the PPP-MII Order 2017 issued by DPIIT and the Electronic Products & Cyber Security Products Notifications issued by MeitY, as amended from time to time.

iv. Adherence to all codal formalities as per the provisions of General Financial Rules-2017, and Department of Expenditure and central Vigilance Commission's guidelines.

(D. K. Sagar)
Joint Director

Encl: As above.

To:

1. The Chief Executive Officer, UIDAI, Bangla Sahib Road, New Delhi.

2. The Secretary, DPIIT & Chairman, Standing Committee on PPP-MII Order 2017, New Delhi.

3. Group Coordinator (UIDAI), Ministry of Electronics and Information Technology, New Delhi.

Annexure-1

List of various hardware and software items requested by UIDAI for Exemption of Make in India (MII) clause for procurement through GeM			
SL. No.	**ICT Item Categories**	**Item Details**	**Justification for MII Exemption**
1	Network Intrusion Prevention system (**NIPS**)	Network Intrusion Prevention system works by examining incoming/outgoing traffic for intrusions, vulnerabilities, exploits and provides remediation to protect network servers and applications. IPS provides holistic view of intrusions across the network through a single dashboard (existing IPS manager) where it stores vulnerability patches and signatures in single storage which can be pushed to all the IPS sensors across the network. The IPS managers can be utilized as to troubleshoot customer/ network issues related to IPS. In the present setup the Data Centre has IPS Solutions of McAfee.	1. At present there is no OEM manufacturing this class of equipment in India. 2. Network Intrusion preventions works on signature based technology for basic solution coverage and hence it needs global and deep experience to have signature coverage for all latest attack patterns to provide efficient solution which is currently not available in India.

No. IV-24011/22/2020-Prov-I/270.
Government of India
Ministry of Home Affairs
Police Modernization Division
Prov-III Desk

26, Man Singh Road,
Jaisalmer House, New Delhi
Dated the 26 April, 2024.

Office Memorandum

Subject : Forwarding of MeitY's communications regarding CCTVs.

(i) Notification dated 06 March, 2024 on the amendments to Public Procurement Order (PPO)-2017 for CCTV/Video Surveillance Systems,
(ii) Amendment notification dated 09 April, 2024 to the "Electronics and information Technology Goods (Requirement of Compulsory Registration) Order, 2021
(iii) Advisory dated 11 March, 2024 on the Threat of Information through CCTV/Video Surveillance system."

The undersigned is directed to say that Ministry of Electronics and Information Technology has notified amendment to Public Procurement (Preference to Make in India) Order 2017 for CCTV/Video Surveillance System for Security and furtherance of the order vide Gazette Notification dated 6th March, 2024 (copy enclosed). MeitY has also issued amendment notification dated 09 April, 2024 to the "Electronics and Information Technology Goods (Requirement of Compulsory Registration) Order, 2021" for the security of a CCTV system (copy enclosed).

2. All Government agencies are advised that henceforth they may procure their CCTVs and allied solutions and hardware on the basis of the Public Procurement Order-2017 and ensure the security of CCTV systems as mentioned in the above said notifications.

3. Further, MeitY has issued Advisory vide O.M. dated W-43/11/2021-IPHW dated 11 Mar, 2024 (copy enclosed) on the Threat of Information through CCTV/Video Surveillance System (VSS)/Digital Video Recorders/Network Video Recorders. All Government agencies are advised to adhere to the guidelines outlined within the ambit of the Public Procurement Orders to safeguard the overall security and integrity of CCTV Cameras and IoT Devices.

Encl:A/a

26/04/24

(Anuj Kumar)
2IC (Prov.)
Tel: 23386034
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To:

1. Chief Secretaries of all States.
2. Administrators of all UTs.
3. Commissioner of Police, Delhi.
4. Directors : CBI, IB, SVP NPA-Hyderabad, NEPA-Shillong, NCRB, NICFS.
5. DsG : AR, BSF, BPR&D, CISF, CRPF, ITBP, NDRF, NSG, SSB & NIA

Internal:

1. All Divisional Heads, MHA.
2. SO(IT) with the request to upload the OM on MHA's website.
3. Director (Procurement)/Director (PM-I & II).
4. US (Prov-I)/US(Prov-II).

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-08032024-252738
CG-DL-E-08032024-252738

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 1062] नई दिल्ली, बृहस्पतिवार, मार्च 7, 2024/फाल्गुन 17, 1945
No. 1062] NEW DELHI, THURSDAY, MARCH 7, 2024/PHALGUNA 17, 1945

इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

(आईपीएचडब्ल्यू प्रभाग)

अधिसूचना

नई दिल्ली, 6 मार्च, 2024

विषय: सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के अनुक्रम में सुरक्षा के लिए क्लोज्ड सर्किट टेलीविजन (सीसीटीवी)/वीडियो निगरानी प्रणाली को अधिसूचित करना

सन्दर्भ:

(i) उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक 28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017

(ii) इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) की दिनांक 07.09.2020 की इलेक्ट्रॉनिक उत्पाद अधिसूचना सं. डब्ल्यू-43/4/2019-आईपीएचडब्ल्यू-एमईआईटीवाई

का.आ. 1119(अ).—सरकार ने 'मेक इन इंडिया' को प्रोत्साहित करने और आय और रोजगार बढ़ाने के उद्देश्य से भारत में वस्तुओं और सेवाओं के विनिर्माण और उत्पादन को बढ़ावा देने के लिए उद्योग और आंतरिक व्यापार संवर्धन विभाग (डीपीआईआईटी) के दिनांक **28.05.2018, 29.05.2019 और 04.06.2020 के आदेशों के जरिए यथासंशोधित आदेश संख्या पी-45021/2/2017-बीई-II दिनांक 15.06.2017 के तहत सार्वजनिक क्रय (मेक इन इंडिया वरीयता) आदेश, 2017 जारी किया है।**

2. उपर्युक्त संदर्भ के जरिये अधिसूचित सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 [पीपीपी-एमआईआई आदेश 2017] के अनुक्रम में इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय (एमईआईटीवाई) एतद्वारा अधिसूचित करता है कि समय-समय पर संशोधित पूर्वोक्त आदेश के अनुसार स्थानीय रूप से विनिर्मित इलेक्ट्रॉनिक उत्पादों को सभी क्रय संस्थाओं द्वारा वरीयता प्रदान की जाएगी।

3. इस अधिसूचना के उद्देश्य से :

3.1 श्रेणी- I स्थानीय आपूर्तिकर्ता, श्रेणी-II स्थानीय आपूर्तिकर्ता और गैर-स्थानीय आपूर्तिकर्ता की परिभाषा दिनांक 16.09.2020 के डीपीआईआईटी पीपीपी-एमआईआई आदेश 2017 संख्या समय-समय पर यथा संशोधित पी-45021/2/2017-पीपी(बीई-II) के पैराग्राफ 2 के अनुसार होगी।, । इस अधिसूचना में प्रत्येक अधिसूचित इलेक्ट्रॉनिक उत्पाद के लिए स्थानीय सामग्री की गणना के लिए तंत्र निर्धारित किया गया है।

3.2 समय-समय पर यथासंशोधित दिनांक 16.09.2020 के डीपीआईआईटी पीपीपी-एमआईआई आदेश 2017 सं. पी-45021/2/2017-पीपी(बीई-II) के पैराग्राफ 3 क को खरीद के प्रतिशत के लिए संदर्भित किया जाएगा, जिसके लिए घरेलू रूप से निर्मित इलेक्ट्रॉनिक उत्पादों को वरीयता प्रदान की जानी है (मूल्य के संदर्भ में)।

4. वीडियो निगरानी प्रणाली के निम्नलिखित इलेक्ट्रॉनिक उत्पादों को सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत अधिसूचित किया गया है:

4.1 वीडियो निगरानी प्रणाली

परिभाषा:

इस अधिसूचना के प्रयोजन के लिए, वीडियो निगरानी प्रणाली आमतौर पर एक प्रणाली है जिसमें *अन्य बातों के साथ-साथ* निम्नलिखित शामिल हैं: (i) क्लोज्ड सर्किट टेलीविजन (सीसीटीवी) कैमरा (एनालॉग/आईपी/एनालॉग स्पीड डोम/आईपी स्पीड डोम), (ii) डिजिटल वीडियो रिकॉर्डर (डीवीआर)/नेटवर्क वीडियो रिकॉर्डर (एनवीआर)। सुरक्षा और वीडियो निगरानी प्रणाली के कुछ अनुप्रयोग शहरों, स्कूलों, बैंकों, सरकारी कार्यालयों, सार्वजनिक स्थानों, यातायात निगरानी और गृह सुरक्षा आदि की निगरानी हैं।

4.2 सीसीटीवी कैमरा (एनालॉग) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (एनालॉग) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्य संवर्धन आवश्यकता को पूरा करते हों:

क्रम सं.	बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (एनालॉग) के निर्माण के लिए चरण	इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए अपेक्षित मूल्य संवर्धन/स्थानीय सामग्री
	(1)	(2)
1.0	मुख्य पीसीबी*	सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण,. हालांकि, वैकल्पिक बोर्डों के साथ/इसके बिना मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 10% से अधिक नहीं होगा
(i)	आई /ओ बोर्ड (वैकल्पिक)	
(ii)	इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक)	
(iii)	नियंत्रण बोर्ड (वैकल्पिक)	
2.0	बेयर पीसीबी	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 5% से अधिक नहीं होगा
3.0	ऑप्टिक्स	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 10% से अधिक नहीं होगा
4.0	इन-हाउस आर एंड डी #	घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।

		2023-24 & 2024-25	2025-26	2026-27 के बाद
		7%	10%	12%
5.0	इन-हाउस डिजाइन/आईपीआर #	घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विशेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।		
		2023-24 & 2024-25	2025-26	2026-27 के बाद
		7%	10%	12%
6.0	हाउसिंग (प्लास्टिक/एल्यूमीनियम/एमएस) और कैमरा माउंट	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से विनिर्माण । हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 15% से अधिक नहीं होगा।		
7.0	कनेक्टिंग केबल्स और कनेक्टर्स	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एनालॉग) के कुल बीओएम के 5% से अधिक नहीं होगा।		
8.0	अंतिम असेम्बली और परीक्षण	समय-समय पर अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरे के कुल बीओएम के 10% से अधिक नहीं होगा		

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

 # आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 4.0 (इन-हाउस आर एंड डी) और क्रम संख्या 5.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.

वित्तीय वर्ष	2023-24 & 2024-25	2025-26	2026-27 के बाद
आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में	25%	35%	45%

4.3 सीसीटीवी कैमरा (आईपी) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (आईपी) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

क्रम सं.	बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (आईपी) के निर्माण के लिए चरण	इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री
	(1)	(2)
1.0	मुख्य पीसीबी* कैप्चर और/या प्रोसेसर कार्ड के साथ	सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण.

<table>
<tr><td>(i)</td><td>नेटवर्क इंटरफेस कार्ड (वैकल्पिक)</td><td rowspan="4">हालांकि, वैकल्पिक बोर्डों के साथ/इनके बिना मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
<tr><td>(ii)</td><td>इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(iii)</td><td>आई/ओ बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(iv)</td><td>पावर ओवर इथरनेट (पी ओ ई) कार्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>3.0</td><td>ऑप्टिक्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। प्रकाशिकी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
<tr><td>4.0</td><td>इन-हाउस आर एंड डी #</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
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<tr><td>5.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
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<tr><td>6.0</td><td>हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 15% से अधिक नहीं होगा।</td></tr>
<tr><td>7.0</td><td>कनेक्टिंग केबल्स और कनेक्टर्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>8.0</td><td>अंतिम असेम्बली और परीक्षण</td><td>समय-समय पर यथा अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित .फाइनल असेंबलिंग और टेस्टिंग के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपी) के कुल बीओएम के 10% से अधिक नहीं होगा.</td></tr>
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** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों की मुद्रित सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

***भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।# आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 4.0 (इन-हाउस आर एंड डी) और क्रम संख्या 5.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.*

वित्तीय वर्ष	2023-24 & 2024-25	2025-26	2026-27 के बाद
आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में	25%	35%	45%

4.4 सीसीटीवी कैमरा (एनालॉग स्पीड डोम) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (एनालॉग स्पीड डोम) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्य संवर्धन आवश्यकता को पूरा करते हों:

<table>
<tr><th>क्रम सं.</th><th>बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (एनालॉग स्पीड डोम) के निर्माण के लिए चरण</th><th>इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>मुख्य नियंत्रक बोर्ड*</td><td rowspan="3">सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. हालांकि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य नियंत्रक बोर्ड/मुख्य पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
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	कैमरा माउंट	5% से अधिक नहीं होगा।
6.0	कनेक्टिंग केबल्स और कनेक्टर्स	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।
7.0	मोटर, हीटर और ब्लोअर, ज़ूम मॉड्यूल, बेल्ट, प्लास्टिक तंत्र भागों, ग्लास आदि	घरेलू रूप से आयातित/घरेलू रूप से निर्मित इनपुट भागों और यांत्रिक घटकों से निर्मित। हालांकि, इन सभी भागों/घटकों के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा
8.0	पावर एडाप्टर	घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडॉप्टर" के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा
9.0	अंतिम असेम्बली और परीक्षण	समय-समय पर अधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरा (एएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

 # आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.

वित्तीय वर्ष	**2023-24 & 2024-25**	**2025-26**	**2026-27 के बाद**
आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.8.0) अंतिम असेंबली और परीक्षण और वैकल्पिक के रूप में अन्य	25%	35%	45%

4.5 सीसीटीवी कैमरा (आईपी स्पीड डोम) की स्थानीय सामग्री की गणना के लिए तंत्र:

सीसीटीवी कैमरा (आईपी स्पीड डोम) का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

क्रम सं.	**बीओएम में मुख्य इनपुट / सीसीटीवी कैमरा (आईपी स्पीड डोम) के निर्माण के लिए चरण**	**इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री**
	(1)	**(2)**
1.0	मुख्य नियंत्रक बोर्ड*	सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. हालांकि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य नियंत्रक बोर्ड के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा
(I)	आई /ओ बोर्ड (वैकल्पिक)	
(ii)	इन्फ्रारेड (आईआर) बोर्ड (वैकल्पिक)	

<table>
<tr><td>(iii)</td><td>प्रोसेसर कार्ड (वैकल्पिक)</td><td rowspan="3"></td></tr>
<tr><td>(iv)</td><td>नेटवर्क इंटरफेस कार्ड (वैकल्पिक)</td></tr>
<tr><td>(v)</td><td>पावर ओवर इथरनेट (पी ओ ई) कार्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>3.0</td><td>इन-हाउस आर एंड डी #</td><td>घरेलू/इन हाउस आर एंड डी में स्वयं अपने संसाधन/विशेषज्ञता का उपयोग कर नये उत्पादों, प्रक्रियाओं, प्रौद्योगिकीयों या समाधानों के विकास के लिए वैज्ञानिक अनुसंधान, प्रयोग, प्रोटोटाइपिंग और परीक्षण अथवा भारत में वैज्ञानिक और औद्योगिक अनुसंधान विभाग (डीएसआईआर) के साथ पंजीकृत आर एंड डी इकाई के साथ कानूनी अनुबंध शामिल है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
<table>
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<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table>
</td></tr>
<tr><td>4.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
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</table>
</td></tr>
<tr><td>5.0</td><td>हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और कैमरा माउंट</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। हाउसिंग और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>6.0</td><td>कनेक्टिंग केबल्स और कनेक्टर्स</td><td>घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल्स और कनेक्टर्स के लिए इनपुट के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>7.0</td><td>मोटर, हीटर और ब्लोअर, ज़ूम मॉड्यूल, बेल्ट, प्लास्टिक तंत्र भागों, ग्लास आदि</td><td>घरेलू रूप से आयातित/घरेलू रूप से निर्मित इनपुट भागों और यांत्रिक घटकों से निर्मित। तथापि, इन सभी भागों/संघटकों के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा।</td></tr>
<tr><td>8.0</td><td>पावर एडाप्टर</td><td>घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडॉप्टर" के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 5% से अधिक नहीं होगा</td></tr>
<tr><td>9.0</td><td>अंतिम असेम्बली और परीक्षण</td><td>समय-समय पर यथाअधिसूचित भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल /परीक्षित . अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज सीसीटीवी कैमरा (आईपीएसडी) के कुल बीओएम के 10% से अधिक नहीं होगा</td></tr>
</table>

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड की असेंबली (पीसीबीए) अनिवार्य रूप से भारत में की जानी चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

 # आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.

वित्तीय वर्ष	2023-24 & 2024-25	2025-26	2026-27 के बाद
आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.9.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में	25%	35%	45%

4.6 डीवीआर/एनवीआर की स्थानीय सामग्री की गणना के लिए तंत्र:

डीवीआर/एनवीआर का घरेलू बीओएम निम्नलिखित तालिका के कॉलम 1 में यथा निर्दिष्ट मुख्य इनपुट की लागत का योग होगा, बशर्ते इनपुट व्यक्तिगत रूप से तालिका के कॉलम 2 में निर्दिष्ट मूल्यवर्धन आवश्यकता को पूरा करते हों:

<table>
<tr><th>क्रम सं.</th><th>बीओएम में मुख्य इनपुट / डीवीआर/एनवीआर के निर्माण के लिए चरण</th><th>इनपुट को घरेलू बीओएम के रूप में वर्गीकृत करने के लिए आवश्यक मूल्य संवर्धन/स्थानीय सामग्री</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>मुख्य पीसीबी*</td><td rowspan="3">सेमीकंडक्टर के मूल्य सहित ** और बेयर पीसीबी के मूल्य को छोड़कर घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण. तथापि, वैकल्पिक बोर्डों के साथ/के बिना मुख्य पीसीबी के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 10 % से अधिक नहीं होगा.</td></tr>
<tr><td>(i)</td><td>फ्रंट पैनल और एलईडी बोर्ड (वैकल्पिक)</td></tr>
<tr><td>(ii)</td><td>आई/ओ बोर्ड (वैकल्पिक)</td></tr>
<tr><td>2.0</td><td>बेयर पीसीबी</td><td>घरेलू रूप से विनिर्मित इनपुट से घरेलू रूप से निर्मित। बेयर पीसीबी के कुल मूल्य का वेटेज सीसीटीवी कैमरा (डीवीआर / एनवीआर) के कुल बीओएम के 5% से अधिक नहीं होगा.</td></tr>
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<tr><td>4.0</td><td>इन-हाउस डिजाइन/आईपीआर #</td><td>घरेलू/इन हाउस डिज़ाइनिंग में संगठन के अपने संसाधन/विषेशज्ञता का प्रयोग कर अपनी फैसिलिटी में ही डिज़ाइन पद्धतियों सेवाओं या समाधानों की प्रक्रिया अथवा भारत में तृतीय पक्षकार के साथ कानूनी अनुबंध शामिल हैं। भारत में बौद्धिक संपदा अधिकार (आईपीआर) के तहत कोई भी पेटेंट, ट्रेडमार्क, कॉपीराइट और व्यापार रहस्य उनकी रचनाओं या आविष्कारों के डिजाइन के पक्ष में कानूनी स्वामित्व स्थापित करता है। इसके वेटेज की गणना संबंधित वित्तीय वर्ष में घरेलू बीओएम के प्रतिशत के आधार पर की जाएगी जैसा कि नीचे दी गई तालिका में उल्लिखित है।
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</td></tr>
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		7%	10%	12%
5.0	हाउसिंग (प्लास्टिक / एल्यूमीनियम / एमएस) और कैमरा माउंट	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। आवास और कैमरा माउंट के लिए इनपुट के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा।		
6.0	कनेक्टिंग केबल, कनेक्टर्स और यूएसबी माउस	घरेलू रूप से निर्मित इनपुट से घरेलू रूप से निर्मित। कनेक्टिंग केबल, कनेक्टर्स और यूएसबी माउस के लिए इनपुट के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा।		
7.0	रिमोट कंट्रोल	घरेलू असेंबली * और आयातित/घरेलू रूप से निर्मित कलपुर्जो और संघटकों से परीक्षण इस शर्त के अधीन है कि "रिमोट कंट्रोल" की असेंबली में उपयोग किए जाने वाले घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य वर्ष 2 में न्यूनतम 20% होगा ("रिमोट कंट्रोल" के निर्माण में उपयोग किए जाने वाले कलपुर्जो और संघटकों के कुल मूल्य का), जो वित्तीय वर्ष 2025-26, 2026-27 और 2027-28 से आगे क्रमशः न्यूनतम 30%, 40% और 50% तक बढ़ जाएगा ।		
8.0	पावर एडाप्टर	घरेलू पीसीबी असेम्बली * और आयातित / घरेलू रूप से निर्मित कलपुर्जो और संघटकों से अंतिम असेम्बली और परीक्षण, बशर्ते कि "पावर एडाप्टर" की असेम्बली में इस्तेमाल घरेलू रूप से निर्मित कलपुर्जो और संघटकों का मूल्य न्यूनतम 40%होगा ("पावर एडाप्टर" के निर्माण में इस्तेमाल कलपुर्जो और संघटकों के कुल मूल्य का). हालांकि, "पावर एडाप्टर" के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 5% से अधिक नहीं होगा।		
9.0	अंतिम असेम्बली और परीक्षण	समय-समय पर अधिसूचित वेटेज भारतीय मानकों को पूरा करने वाले घरेलू रूप से असेम्बल / परीक्षित. अंतिम संयोजन और परीक्षण के कुल मूल्य का वेटेज डीवीआर/एनवीआर के कुल बीओएम के 10% से अधिक नहीं होगा।		

** यह आवश्यक है कि एसएमटी प्रक्रिया का उपयोग करके बेयर पीसीबी पर कलपुर्जो और संघटकों के मुद्रित सर्किट बोर्ड असेंबली (पीसीबीए) अनिवार्य रूप से भारत में किया जाना चाहिए।*

*** भारत में सेमीकंडक्टर एफएबी के चालू होने पर इसकी समीक्षा की जाएगी।*

 # आवेदक संबंधित वित्तीय वर्ष के लिए नीचे दी गई तालिका में उल्लिखित न्यूनतम मूल्यवर्धन/स्थानीय सामग्री को पूरा करके मूल्य संवर्धन/स्थानीय सामग्री की गणना के लिए संबंधित वित्तीय वर्ष में क्रम संख्या 3.0 (इन-हाउस आर एंड डी) और क्रम संख्या 4.0 (इन-हाउस डिजाइन/आईपीआर) का लाभ उठाने के लिए पात्र होगा.

वित्तीय वर्ष	2023-24 & 2024-25	2025-26	2026-27 के बाद
आवश्यक के रूप में न्यूनतम मूल्य संवर्धन/स्थानीय सामग्री (क्रम सं. 1.0) मुख्य पीसीबी और (क्रम सं.9.0) अंतिम असेंबली और परीक्षण और अन्य वैकल्पिक के रूप में	25%	35%	45%

5. निगरानी उपकरणों यानी सीसीटीवी कैमरों (एनालॉग/आईपी/एनालॉग स्पीड डोम/आईपी स्पीड डोम/आईपी स्पीड डोम) को समय-समय पर यथा संशोधित परिशिष्ट 'क' के अनुसार वीएसएस/सीसीटीवी सिस्टम की सुरक्षा सुनिश्चित करने के लिए एमईआईटीवाई द्वारा निर्धारित सुरक्षा के लिए आवश्यक आवश्यकताओं (ईआर) का अनु पालन करना चाहिए। सीसीटीवी/वीएसएस के लिए सुरक्षा परीक्षण प्रतिवेदन मानकीकरण परीक्षण और गुणवत्ता प्रमाणन (एसटीक्यूसी) प्रयोगशाला या एमईआईटीवाई द्वारा समय-समय पर अधिसूचित किसी अन्य एजेंसी द्वारा जारी किया जाएगा। एसटीक्यूसी लैब द्वारा जारी परीक्षण रिपोर्ट की वैधता रिपोर्ट के जारी होने की तारीख से तीन वर्ष होगी. सीसीटीवी कैमरों/वीएसएस प्रणाली की सुरक्षा के लिए इन अनिवार्य आवश्यकताओं (ईआर) को इस अधिसूचना के जारी होने की तारीख से 3 महीने के बाद लागू किया जाएगा। डीवीआर और एनवीआर के लिए सुरक्षा मानदंडों को बाद में अधिसूचित किया जाएगा।

6. अधिसूचना इस अधिसूचना के जारी होने की तारीख से 3 महीने के बाद प्रभावी होगी। यह अधिसूचना संशोधित अधिसूचना जारी होने तक वैध रहेगी। इस अधिसूचना के प्रयोजन के लिए 1 वर्ष 31.03.2025 तक होगा।

7. सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत किसी भी इलेक्ट्रॉनिक उत्पाद अधिसूचना का पूर्वव्यापी प्रभाव नहीं होगा।

8. पूर्वोक्त इलेक्ट्रॉनिक्स उत्पादों की खरीद के लिए समय-समय पर यथा संशोधित दिनांक 16.09.2020 के सार्वजनिक खरीद (मेक इन इंडिया को वरीयता) आदेश 2017 में उद्धृत प्रावधानों के अनुसार खरीद वरीयता प्रदान की जाएगी ।

9. यदि भारत सरकार द्वारा परियोजना या योजना पूरी तरह से या आंशिक रूप से वित्त पोषित होती है, तो राज्यों और स्थानीय निकायों द्वारा बनाए गए इलेक्ट्रॉनिक उत्पादों की क्रय के लिए अधिसूचना सभी केंद्रीय योजनाओं (सीएस)/केंद्रीय क्षेत्र की योजनाओं (सीएसएस) पर भी लागू होगी।

10. स्थानीय सामग्री/घरेलू मूल्यवर्धन की गणना करने हेतु प्रक्रिया

10.1 घरेलू विनिर्माताओं (डीओएम-बीओएम) से प्राप्त सामग्री के बिल की गणना उपलब्ध आंकड़ों के आधार पर निम्नलिखित में से किसी एक के आधार पर की जा सकती है।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और जिनका आयात प्रत्यक्ष रूप से या घरेलू व्यापारी या माध्यस्थ के माध्यम से नहीं किया गया है।

ख. उत्पाद के फैक्ट्री बाह्य मूल्य से उत्पाद के उत्पादन में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल (प्रत्यक्ष या अप्रत्यक्ष रूप से) को घटाकर (इनपुटों की क्रय पर लागए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है) और उसमें से वारंटी लागत को घटाकर।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर, उसमें से कर पश्चात लाभ, वारंटी लागत को घटाया जाता है, उसमें से उत्पादों के उत्पादन (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ लिया जा सकता है) में इनपुटों के रूप में उपयोग की गई सामग्री के आयातित बिल के योग को घटाया जाता है और बिक्री और विपणन खर्च को घटाया जाता है।

10.2 सामग्री के कुल बिल (कुल-बीओएम) की गणना उपलब्ध आंकडों पर आधारित निम्नलिखित में से किसी एक के आधार पर की जा सकती है।

क. सभी इनपुटों की लागतों का योग जो उस उत्पाद को बनाने के लिए आवश्यक है (इनपुटों की क्रय पर लगाए गए शुल्क और करों सहित, सिवाय उनको छोड़कर जिनके लिए क्रेडिट/सेट-ऑफ का लाभ लिया जा सकता है)।

ख. उत्पाद के फैक्टरी बाह्य मूल्य से कर पश्चात लाभ और वारंटी लागतों को घटाया जाता है।

ग. बाजार मूल्य से उत्पादन पश्चात मालभाडा, बीमा और अन्य हथालन लागतों को घटाकर उसमें से कर पश्चात लाभ, वारंटी लागत, बिक्री और विपणन खर्च घटाया जाता है।

10 .3 निम्नलिखित फॉर्मूला के अनुसार प्रस्तुत जानकारी के आधार पर घरेलू मूल्य-वृद्धि के प्रतिशत की गणना की जा सकती है:

$$\text{स्थानीय सामग्री/घरेलू मूल्य-वृद्धि का प्रतिशत} = \frac{\text{डीओएम-बीओएम}}{\text{कुल-बीओएम}} \times 100$$

11. स्थानीय सामग्री/घरेलू मूल्यवृद्धि का सत्यापन

11.1. निविदा, बोली प्रक्रिया या सिफ़ारिश के समय स्थानीय आपूर्तिकर्ता स्व-प्रमाणन प्रदान करेगा कि प्रसतावित की गई वस्तुएं न्यूनतम स्थानीय सामग्री की आवश्यकताओं को पूरा करती हैं और उस स्थान (स्थानों) का विवरण देगा, जिस पर स्थानीय मूल्य वृद्धि की गई है।

11.2. 10 करोड़ रुपए से अधिक मूल्य की क्रय के मामलों में, स्थानीय आपूर्तिकर्ता स्थानीय सामग्री का प्रतिशत देते हुए कंपनी के सांविधिक लेखा परीक्षक)कंपनियों के मामले में) या लागत लेखापरीक्षक या किसी पेशेवर लागत लेखाकार ये पेशेवर चार्टेड लेखाकार (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाणपत्र उपलब्ध कराएगा।

11.3. यदि किसी इलेक्ट्रॉनिक उत्पाद के संबंध में स्थानीय सामग्री/घरेलू मूल्य वृद्धि के संबंध में बोलीकर्ता के दावे के खिलाफ क्रय एजेंसी या संबंधित मंत्रालय/विभाग द्वारा शिकायत प्राप्त की जाती है, तो उसे एसटीक्यूसी के पास भेजा जाएगा।

11.4. एसटीक्यूसी को संदर्भित कोई भी शिकायत 4 सप्ताह के भीतर निपटा दी जाएगी। बोलीकर्ता को एसटीक्यूसी हेतु किसी इलेक्ट्रॉनिक उत्पाद में दावा की गई घरेलू मूल्य वृद्धि के समर्थन में आवश्यक दस्तावेज प्रस्तुत करने की आवश्यकता होगी। यदि बोलीकर्ता के द्वारा कोई जानकारी प्रस्तुत नहीं की जाती है, तो ऐसी प्रयोगशालाएं दावे के वास्तविकता को सिद्ध करने के लिए अगली आवश्यक कार्रवाई कर सकती हैं। **स्थानीय सामग्री की गणना में विसंगतियों के मामले में, स्थानीय सामग्री के प्रतिशत की गणना के लिए कंपनी के सांविधिक लेखा परीक्षक या लागत लेखा परीक्षक (कंपनियों के मामले में) या प्रैक्टिसिंग कॉस्ट एकाउंटेंट या प्रैक्टिसिंग चार्टर्ड एकाउंटेंट (कंपनियों के अलावा अन्य आपूर्तिकर्ताओं के संबंध में) से एक प्रमाण पत्र स्व-घोषणा प्रमाण पत्र पर अधिक्रमित होगा।**

11.5. 2 लाख रुपए या खरीदे जा रहे घरेलू रूप से विनिर्मात इलेक्ट्रॉनिक उत्पादों की कीमत का 1% शिकायत शुल्क (5 लाख रुपए की अधिकतदम सीमा के अध्यधीन), जो भी अधिक हो, का डिमांड ड्राफ्ट द्वारा भुगतान किया जाएगा, जो एसयीक्यूसी में जमा जमा होगा। यदि शिकायत गलत पाई जाती है, तो शिकायत शुल्क जब्त कर लिया जाएगा। यदि, शिकायत को बरकरार रखा जाता है और काफी हद तक सही पाया जाता है तो शिकायतकर्ता को जमा शुल्क बिना किसी ब्याज के वापस कर दिया जाएगा।

11.6. सामान्य वित्तीय नियम (जीएफआर) के नियम 175(1)(i)(एच) के तहत झूठी घोषणाएं सत्यनिष्ठा संहिता का उल्लंघन होंगी, जिसके लिए बोली लगाने वाले या उसके उत्तराधिकारियों को नियम 151 (iii) के अनुसार प्रतिबंधित किया जा सकता है। सामान्य वित्तीय नियमों के साथ-साथ बोली लगाने के ऐसे अन्य प्रावधान, एकल मंत्रालय/विभाग द्वारा रोक लगाना और व्यय विभाग के कार्यालय ज्ञापन संख्या एफ.1/20/2018-पीपीडी दिनांक 2 नवंबर, 2021 के अनुसार आदेशों को रद्द करना समय-समय पर संशोधित कानून के तहत अनुमन्य हो सकता है।

12. इलेक्ट्रॉनिक्स उत्पाद अधिसूचनाओं के कार्यान्वयन की निगरानी के लिए एमईआईटीवाई नोडल मंत्रालय होगा। एसटीक्यूसी द्वारा दिए गए निर्णय के विरुद्ध किसी विवाद/स्पष्टीकरण के मामले में, शिकायतों के सत्यापन/पुनरीक्षण, यादृच्छिक आधार पर स्व-घोषणाओं और लेखा परीक्षक/लेखाकार के प्रमाणपत्रों के स्वतंत्र सत्यापन, इलेक्ट्रॉनिकी उत्पादों के घरेलू विनिर्माताओं के विरुद्ध प्रतिबंधात्मक और भेदभावपूर्ण निबंधन और शर्तों के लिए निम्नलिखित घटकों वाली एक समिति गठित की जाती है: -

i)	समूह समन्वयक/वैज्ञानिक- 'जी' (आईपीएचडब्ल्यू)	- अध्यक्ष
ii)	एसटीक्यूसी से वैज्ञानिक-'जी'/वैज्ञानिक-'एफ'	- सदस्य
iii)	वैज्ञानिक- 'ई'/सर्ट-इन/साइबर डिवीजन अथवा वरिष्ठ.	- सदस्य
vi)	अध्यक्ष द्वारा सहयोजित कोई अन्य सदस्य (सदस्यों)	-सदस्य
v)	आईपीएचडब्ल्यू प्रभाग से वैज्ञानिक-'ई'/प्रतिनिधि	-सदस्य सचिव

13. यदि प्रश्न उठता है कि क्या खरीदी जा रही कोई वस्तु एक इलेक्ट्रॉनिक उत्पाद है, जिसे सार्वजनिक क्रय (मेक इन इंडिया को वरीयता) आदेश 2017 के तहत शामिल किया जाना है, तो इस मामले को स्पष्टीकरण के लिए इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय को संदर्भित किया जाएगा।

[फ़ा. सं. डब्ल्यू-43/11/2021-आईपीएचडब्ल्यू]

आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

परिशिष्ट 'क'

सीसीटीवी की सुरक्षा के लिए अनिवार्य आवश्यकता

संवेदनशील जानकारी की सुरक्षा और सिस्टम को प्रभावी ढंग से संचालित करने के लिए सीसीटीवी (क्लोज-सर्किट टेलीविजन) प्रणाली को सुरक्षित करना महत्वपूर्ण है। परीक्षण के प्रमुख क्षेत्रों में एक्स्पोस्ड नेटवर्क सेवाएं, डिवाइस संचार प्रोटोकॉल, डिवाइस के यूएआरटी,जेटीएजी,एसडब्ल्युडी आदि तक भौतिक पहुंच, मेमोरी और फर्मवेयर निकालने की क्षमता, फर्मवेयर अपडेट प्रक्रिया सुरक्षा और डेटा का भंडारण और एन्क्रिप्शन शामिल हैं। सीसीटीवी सिस्टम की सुरक्षा के लिए यहां संक्षिप्त आवश्यकताएं दी गई हैं:

		और विकास प्रक्रियाओं के हिस्से के रूप में एक या अधिक अद्यतन मैलवेयर पहचान उपकरण नियोजित किए जाएंगे। अंतिम पैकेजिंग और प्रदायगी से पहले मैलवेयर पहचान तकनीकों का उपयोग किया जाएगा (उदाहरण के लिए, एक या अधिक अद्यतन मैलवेयर पहचान उपकरणों का उपयोग करके मैलवेयर के लिए तैयार उत्पादों और घटकों को स्कैन करना)।	पहचान टैर्निंग/जालसाजी, सीएम टूल के ट्रैकिंग लक्ष्यों की आवश्यकता के रूप में की गई है। गुणवत्ता आश्वासन प्रक्रिया को प्रस्तुत करने और उसे प्रदर्शित करने की आवश्यकता है।	
		4.4 आपूर्ति श्रृंखला जोखिम की पहचान, मूल्यांकन, प्राथमिकता और शमन आयोजित किया जाएगा।		आपूर्ति श्रृंखला जोखिम / व्यापार निरंतरता योजना नीति दस्तावेज, प्लेबुक जो दर्शाती है कि आपूर्ति श्रृंखला व्यवधान को कैसे संभालना है, घटना के बाद सारांश दस्तावेजों को प्रस्तुत करने और उसी को प्रदर्शित करने की आवश्यकता है।

MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY

(IPHW DIVISION)

NOTIFICATION

New Delhi, the: 6th March, 2024

Subject: Public Procurement (Preference to Make in India) Order 2017-Notifying CCTV/ Video Surveillance System for Security in furtherance of the Order

Reference:

(i) Department for Promotion of Industry and Internal Trade (DPIIT) Order No. P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020

(ii) Ministry of Electronics and Information Technology (MeitY) Electronic Products Notification No. W-43/4/2019-IPHW-MeitY dated 07.09.2020

S.O. 1119(E).—The Government has issued Public Procurement (Preference to Make in India) Order 2017 vide the Department for Promotion of Industry and Internal Trade (DPIIT) Order No.P-45021/2/2017-B.E.-II dated 15.06.2017, as amended by Orders dated 28.05.2018, 29.05.2019, 04.06.2020 and 16.09.2020, to encourage 'Make in India' and promote manufacturing and production of goods and services in India with a view to enhancing income and employment.

2. In furtherance of the Public Procurement (Preference to Make in India) Order 2017 [PPP-MII Order 2017] notified vide reference cited above, the Ministry of Electronics and Information Technology (MeitY) hereby notifies

that preference shall be provided by all procuring entities to locally manufactured Video Surveillance System for Security as per the aforesaid Order, as amended from time to time.

3. For the purpose of this notification:

3.1 The definition of Class-I local supplier, Class-II local supplier and Non-local supplier shall be as per paragraph 2 of the DPIIT PPP-MII Order 2017 No. P-45021/2/2017-PP(BE-II) dated 16.09.2020, as amended from time to time. The mechanism for calculation of local content is prescribed for each notified Electronic Product in this notification.

3.2 Paragraph 3A of the DPIIT PPP-MII Order 2017 No. P-45021/2/2017-PP(BE-II) dated 16.09.2020, as amended from time to time, shall be referred for percentage of procurement for which preference to domestically manufactured Electronic Products is to be provided (in value terms).

4. Following electronic products of Video Surveillance System are notified under the Public Procurement (Preference to Make in India) Order 2017:

4.1 Video Surveillance System

Definition:

For the purpose of this Notification, Video Surveillance System is usually a system that *inter-alia* includes: (i) Closed Circuit Television (CCTV) Camera (Analog/ IP/ Analog Speed Dome/ IP Speed Dome), (ii) Digital Video Recorder (DVR) / Network Video Recorder (NVR). Some of the applications of Security and Video Surveillance System are surveillance of Cities, Schools, Banks, Government Offices, public places, traffic monitoring and home security, etc.

4.2 Mechanism for calculation of local content of CCTV Camera (Analog):

The domestic BOM of CCTV Camera (Analog) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr. No.</th><th>Main inputs in BOM / stages for manufacture of CCTV Camera (Analog)</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>(1)</td><td>(2)</td></tr>
<tr><td>1.0</td><td>Main PCB*</td><td rowspan="4">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>(i)</td><td>I/O Board (optional)</td></tr>
<tr><td>(ii)</td><td>Infrared (IR) Board (optional)</td></tr>
<tr><td>(iii)</td><td>Control Board (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>3.0</td><td>Optics</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Optics shall not exceed 10 % of the total BOM of the CCTV Camera (Analog)</td></tr>
<tr><td>4.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property</td></tr>
</table>

		Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:

2023-24 & 2024-25	2025-26	2026-27 onwards
7%	10%	12%

6.0	Housing (Plastic /Aluminium/MS) and Camera Mount	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed to 15 % of the total BOM of the CCTV Camera (Analog).
7.0	Connecting Cables & Connectors	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BOM of the CCTV Camera (Analog).
8.0	Final Assembly and Testing	Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10% of the total BOM of the CCTV Camera.

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

 # The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.

Financial Year	2023-24 & 2024-25	2025-26	2026-27 onwards
Minimum Value Addition/Local Content of (Sr. No. 1) Main PCB and (Sr. No.8) Final Assembly and Testing as -Essential and others as optional	25%	35%	45%

4.3 Mechanism for calculation of local content of CCTV Camera (IP):

The domestic BOM of CCTV Camera (IP) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

Sr. No.	Main inputs in BOM / stages for manufacture of CCTV Camera (IP)	Value addition / local content required for the input to be classified as domestic BOM
	1	2
1.0	Main PCB* with Capture and/or Processor Card	Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BOM of the CCTV Camera (IP)
(i)	Network Interface Card (optional)	
(ii)	Infrared (IR) Board (optional)	
(iii)	I/O Board (optional)	
(iv)	Power over Ethernet (PoE) Card (optional)	
2.0	Bare PCB	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BOM of the CCTV Camera (IP)
3.0	Optics	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Optics shall not exceed 10 % of the total BOM of the CCTV Camera (IP)
4.0	In-house R&D #	Domestically/In-house R&D includes scientific research, experimentation,

<table>
<tr><td></td><td></td><td>prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>6.0</td><td>Housing (Plastic / Aluminium / MS) and</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 15 % of the total BOM of the CCTV Camera (IP).</td></tr>
<tr><td>7.0</td><td>Connecting Cables and Connectors</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BOM of the CCTV Camera (IP).</td></tr>
<tr><td>8.0</td><td>Final Assembly and Testing</td><td>Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of Final Assembling and Testing shall not exceed 10% of the total BOM of the CCTV Camera (IP)</td></tr>
</table>

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

 # The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.

Financial Year	2023-24 & 2024-25	2025-26	2026-27 onwards
Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 8.0) Final Assembly and Testing as -Essential and others as optional	25%	35%	45%

4.4 Mechanism for calculation of local content of CCTV Camera (Analog Speed Dome):

The domestic BOM of CCTV Camera (Analog Speed Dome) would be the sum of the costs of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr. No.</th><th>Main inputs in BOM / stages for manufacture of CCTV Camera (Analog Speed Dome)</th><th>Value addition required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>1</td><td>2</td></tr>
<tr><td>1</td><td>Main Controller Board*</td><td rowspan="3">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main Controller Board/Main PCB with/without optional boards shall not exceed 10 % of the total BoM of the CCTV Camera (ASD)</td></tr>
<tr><td>(i)</td><td>I/O Board (optional)</td></tr>
<tr><td>(ii)</td><td>Infrared (IR) Board (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total</td></tr>
</table>

		BoM of the CCTV Camera (ASD)
3.0	Inhouse R&D#	Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with *Department of Scientific and Industrial Research* (*DSIR)* in India. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:

2023-24 & 2024-25	2025-26	2026-27 onwards
7%	10%	12%

4.0	In-house Design/IPR#	Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:

2023-24 & 2024-25	2025-26	2026-27 onwards
7%	10%	12%

5.0	Housing (Plastic/ Aluminium/ MS) and Camera Mount	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the CCTV Camera (ASD).
6.0	Connecting Cables and Connectors	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BoM of the CCTV Camera (ASD).
7.0	Motor, Heater & Blower, Zoom Module, Belt, Plastic Mechanism Parts, Glass etc.	Domestically manufactured from imported / domestically manufactured input parts and mechanical components. However, the weightage of the total value of all these parts/components shall not exceed 5% of the total BoM of the CCTV Camera (ASD)
8.0	Power Adapter	Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). However, the weightage of the total value of "Power Adapter" shall not exceed 5% of the total BoM of the CCTV Camera (ASD)
9.0	Final Assembly and Testing	Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BoM of the CCTV Camera (ASD)

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

 # The applicant will be eligible to avail the benefit of Sr. No. 3.0 (In-house R&D) & Sr. No. 4.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.

Financial Year	**2023-24 & 2024-25**	**2025-26**	**2026-27 onwards**
Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional	25%	35%	45%

4.5 Mechanism for calculation of local content of CCTV Camera (IP Speed Dome):

The domestic BOM of CCTV Camera (IP Speed Dome) would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr. No.</th><th>Main inputs in BOM / stages for manufacture of CCTV Camera (IP Speed Dome)</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>1</td><td>2</td></tr>
<tr><td>1.0</td><td>Main Controller Board*</td><td rowspan="6">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main Controller Borad with/without optional boards Shall not exceed 10 % of the total BoM of the CCTV Camera (IPSD)</td></tr>
<tr><td>(i)</td><td>I/O Board (optional)</td></tr>
<tr><td>(ii)</td><td>Infrared (IR) Board (optional)</td></tr>
<tr><td>(iii)</td><td>Processor Card (optional)</td></tr>
<tr><td>(iv)</td><td>Network Interface Card (Optional)</td></tr>
<tr><td>(v)</td><td>Power over Ethernet (PoE) Card (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BoM of the CCTV Camera (IPSD)</td></tr>
<tr><td>3.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources /expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BoM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>5.0</td><td>Housing (Plastic / Aluminium / MS) and Camera Mount</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>6.0</td><td>Connecting Cables and Connectors</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables and Connectors shall not exceed 5% of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>7.0</td><td>Motor, Heater & Blower, Zoom Module, Belt, Plastic Mechanism Parts, Glass etc.</td><td>Domestically manufactured from imported / domestically manufactured input parts and mechanical components. However, the weightage of the total value of all these parts/components shall not exceed 5% of the total BoM of the CCTV Camera (IPSD).</td></tr>
<tr><td>8.0</td><td>Power Adapter</td><td>Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the</td></tr>
</table>

		assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). However, the weightage of the total value of "Power Adapter" shall not exceed 5% of the total BoM of the CCTV Camera (IPSD)
9.0	Final Assembly and Testing	Domestically assembled / tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BoM of the CCTV Camera (IPSD)

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

 # The applicant will be eligible to avail the benefit of Sr. No. 3.0 (In-house R&D) & Sr. No. 4.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.

Financial Year	2023-24 & 2024-25	2025-26	2026-27 onwards
Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional	25%	35%	45%

4.6 Mechanism for calculation of local content of DVR/ NVR:

The domestic BOM of DVR/ NVR would be the sum of the cost of main inputs as specified in Column 1 of the following table, provided the inputs individually satisfy the value addition requirement specified in Column 2 of the table:

<table>
<tr><th>Sr No.</th><th>Main inputs in BOM / stages for manufacture of DVR / NVR</th><th>Value addition / local content required for the input to be classified as domestic BOM</th></tr>
<tr><td></td><td>1</td><td>2</td></tr>
<tr><td>1.0</td><td>Main PCB*</td><td rowspan="3">Domestic PCB Assembly* and testing from imported / domestically manufactured parts and components, including the value of Semiconductors** and excluding the value of bare PCB. However, the weightage of the total value of Main PCB with/without optional boards shall not exceed 10 % of the total BoM of the DVR/NVR.</td></tr>
<tr><td>(i)</td><td>Front Panel & LED Board (optional)</td></tr>
<tr><td>(ii)</td><td>I/O Board (optional)</td></tr>
<tr><td>2.0</td><td>Bare PCB</td><td>Domestically manufactured from domestically manufactured inputs. The weightage of the total value of Bare PCB shall not exceed 5 % of the total BoM of the CCTV Camera (DVR/NVR)</td></tr>
<tr><td>3.0</td><td>In-house R&D #</td><td>Domestically/In-house R&D includes scientific research, experimentation, prototyping and testing for development of new products, process, technologies, or solutions using its own resources/expertise or legal contract with R&D unit registered with Department of Scientific and Industrial Research (DSIR) in India. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:
<table>
<tr><td>2023-24 & 2024-25</td><td>2025-26</td><td>2026-27 onwards</td></tr>
<tr><td>7%</td><td>10%</td><td>12%</td></tr>
</table></td></tr>
<tr><td>4.0</td><td>In-house Design/IPR #</td><td>Domestically/In-house Designing involves the process of design practices, services, or solutions within the organization's own facilities, using its own resources/expertise or legal contract with third party in India. Any patents, trademarks, copyrights, and trade secrets registered under Intellectual Property Rights (IPR) in India in favor of the design for their creations or inventions establishes legal ownership. The weightage of this will be calculated based on the percentage of the domestic BOM in respective Financial Year as mentioned in below table.:</td></tr>
</table>

		2023-24 & 2024-25	2025-26	2026-27 onwards
		7%	10%	12%
5.0	Housing (Plastic / Aluminium / MS) and Camera Mount	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Housing and Camera Mount shall not exceed 5 % of the total BoM of the DVR/NVR.		
6.0	Connecting Cables, Connectors and USB Mouse	Domestically manufactured from domestically manufactured inputs. The weightage of the total value of inputs for Connecting Cables, Connectors and USB Mouse shall not exceed 5% of the total BoM of the DVR/NVR.		
7.0	Remote Control	Domestic assembly* and testing from imported / domestically manufactured parts and components subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Remote Control" will be minimum 20% (of the total value of the parts and components used in the manufacture of "Remote Control") in Year 2, which will increase to minimum 30%, 40% and 50% in Financial Years 2025-26, 2026-27 and 2027-28 onwards respectively.		
8.0	Power Adapter	Domestic PCB assembly* and the final assembly and testing from imported / domestically manufactured parts and components, subject to the condition that the value of domestically manufactured parts and components used in the assembly of "Power Adapter" will be minimum 40% (of the total value of parts and components used in the manufacture of "Power Adapter"). However, the weightage of the total value of "Power Adapter" shall not exceed 5% of the total BoM of the DVR/NVR.		
9.0	Final Assembly and Testing	Domestically assembled/tested meeting Indian Standards as notified from time to time. The weightage of the total value of final assembling and testing shall not exceed 10 % of the total BOM of the DVR/NVR.		

** It is essential that the Printed Circuit Board Assembly (PCBA) of the parts and components on the bare PCB using the SMT process should mandatorily be done in India.*

*** This shall be reviewed when the Semiconductor FAB in India is operational.*

 # The applicant will be eligible to avail the benefit of Sr. No. 4.0 (In-house R&D) & Sr. No. 5.0 (In-house Design/IPR) in respective financial year for calculation of Value Addition/Local Content by meeting the minimum Value Addition/Local Content mentioned in below table for respective financial year.

Financial Year	**2023-24 & 2024-25**	**2025-26**	**2026-27 onwards**
Minimum Value Addition/Local Content of (Sr. No. 1.0) Main PCB and (Sr. No. 9.0) Final Assembly and Testing as -Essential and others as optional	25%	35%	45%

5. The surveillance devices i.e., CCTV Cameras (Analog/ IP/ Analog Speed Dome/ IP Speed Dome) should comply with the Essential Requirements (ERs) for security prescribed by MeitY to ensure the security of the VSS / CCTV systems, as per the Appendix 'A', as amended from time to time. The security testing report for CCTV/VSS to be issued by Standardisation Testing and Quality Certification (STQC) Laboratory or any other agency notified by MeitY from time to time. The validity of the test report issued by STQC Lab will be three years from the date of issue of the report. These Essential Requirements (ERs) for security of CCTV Cameras/VSS system will be enforced after 3 months from the date of issuance of this Notification. The security norms for the DVR and NVR will be notified subsequently.

6. The notification will come into effect after 3 months from the date of issuance of this Notification. This Notification shall remain valid till the revised Notification is issued. The Year 1 for the purpose of this notification would be upto 31.03.2025.

7. No Electronic Product Notification under the Public Procurement (Preference to Make in India) Order 2017 shall have retrospective effect.

8. Purchase Preference shall be provided as per the provisions cited in the Public Procurement (Preference to Make in India) Order 2017 dated 16.09.2020 and, as amended from time to time, for the procurement of aforesaid electronics products.

9. The notification would also be applicable to all Central Schemes (CS)/ Central Sector Schemes (CSS) for the procurement of electronic products made by States and local bodies, if project or scheme is fully or partially funded by Government of India.

10. Procedure for calculating local content/ domestic value addition

10.1 Bill of Material sourced from domestic manufacturers (Dom-BOM) may be calculated based on one of the followings depending on data available:

a) Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) and which have not been imported directly or through a domestic trader or an intermediary.

b) Ex-Factory Price of product minus profit after tax minus sum of imported Bill of Material used (directly or indirectly) as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit/ set-off can be taken) minus warranty costs.

c) Market price minus post-production freight, insurance and other handling costs minus profit after tax minus warranty costs minus sum of Imported Bill of Material used as inputs in producing the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken) minus sales and marketing expenses.

10.2 Total Bill of Material (Total BOM) may be calculated based on one of the following depending on data available:

a) Sum of the costs of all inputs which go into the product (including duties and taxes levied on procurement of inputs except those for which credit / set-off can be taken).

b) Ex-Factory Price of product minus profit after tax, minus warranty costs.

c) Market price minus post-production freight, insurance and other handling costs minus profit after tax, minus warranty costs minus sales and marketing expenses.

10.3 The percentage of domestic value-addition may be calculated based on information furnished as per the following formula:

Percentage of local content/ domestic value-addition = [(Dom-BOM) / (Total BOM)]*100

11. Verification of local content/ Domestic Value Addition

11.1. The local supplier at the time of tender, bidding or solicitation shall provide self-certification that the item offered meets the minimum local content and shall give details of the location(s) at which the local value addition is made.

11.2. In cases of procurement for a value in excess of Rs.10 crore, the local supplier shall provide a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) giving the percentage of local content.

11.3. In case a complaint is received by the procuring agency or the concerned Ministry/Department against the claim of a bidder regarding local content/ domestic value addition in an Electronic Product(s), the same shall be referred to STQC.

11.4. Any complaint referred to STQC shall be disposed of within 4 weeks. The bidder shall be required to furnish the necessary documentation in support of the domestic value addition claimed in an Electronic Product(s) to STQC. If no information is furnished by the bidder, such laboratories may take further necessary action, to establish the bonafides of the claim. In case of the discrepancies in computation of local content, a certificate from the statutory auditor or cost auditor of the company (in the case of companies) or from a practicing cost accountant or practicing chartered accountant (in respect of suppliers other than companies) for calculating the percentage of local content will supersede over the self-declaration certificate.

11.5. A complaint fee of Rs.2 Lakh or 1% of the value of the domestically manufactured Electronic Products being procured (subject to a maximum of Rs. 5 Lakh), whichever is higher, to be paid by Demand Draft to be deposited with STQC. In case, the complaint is found to be incorrect, the complaint fee shall be forfeited. In case, the complaint is upheld and found to be substantially correct, deposited fee of the complainant would be refunded without any interest.

11.6. False declarations will be in breach of the Code of Integrity under Rule 175(1)(i)(h) of the General Financial Rules (GFR) for which a bidder or its successors can be debarred as per Rule 151 (iii) of the General Financial Rules along with such other provisions of bidding, debarment by a single Ministry/Department and revocation of orders as per the Department of Expenditure O.M-No. F.1/20/2018-PPD dated 2nd Nov, 2021 may be permissible under law amended from time to time.

12. MeitY shall be the Nodal Ministry to monitor the implementation of the Electronic Products notifications. In case of any dispute/clarifications against the decision given by STQC, a committee is constituted with the following

compositions for verification/vetting the complaints, independent verification of self-declarations and auditor's/accountant's certificates on random basis, restrictive and discriminating terms and conditions against the domestic manufactures of Electronics Products(s): -

i)	Group Coordinator/Scientist- 'G' (IPHW)	- Chairperson
ii)	Scientist-'G'/Scientist-'F' from STQC	- Member
iii)	Scientist- 'E' or above from Cert-In/Cyber Division	- Member
vi)	Any other member(s) as co-opted by the Chairperson -	Member
v)	Representative from IPHW Division	- Member Secretary

13. In case of a question whether an item being procured is an Electronic Product(s) to be covered under the Public Procurement (Preference to Make in India) Order 2017, the matter would be referred to the Ministry of Electronics and Information Technology for clarification.

[F. No. W-43/11/2021-IPHW]

ASHA NANGIA, Group Coordinator & Scientist 'G'

Appendix 'A'

Essential Requirement(s) for Security of CCTV

Securing a CCTV (Closed-Circuit Television) system is crucial to protect sensitive information and ensure the system operates effectively. Key areas of testing include exposed network services, device communication protocols, physical access to the device's UART, JTAG, SWD, etc., the ability to extract memory and firmware, firmware update process security and storage and encryption of data. Here are brief requirements for the security of a CCTV system:

1) Physical Security - Use tamper-resistant camera enclosures and locking mechanisms to deter physical tampering.
2) Access Control by Authentication, Role-Based Access Control (RBAC) and regularly review and update access permissions to reflect personnel changes.
3) Network Security by employing encryption of data transmission
4) Software Security by Regular Updates, Disable Unused Features and Strong Password Policies
5) Penetration Testing: Employ penetration testing to assess the system's resistance to cyberattacks and address vulnerabilities.

Essential Security Requirements

Sr. No.	Category	Testing Parameter	What to be tested	Documents Required
1)	Hardware Level Security Parameter (supported by software)	1.1 Verify that application layer debugging interfaces such USB, UART, and other serial variants are disabled or protected by a complex password.	1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants through the Datasheet of the SoC being used in the device under test 2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation 3. Testing, in presence of	1. Datasheet of the SoC being used in the device. 2. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same. 3. Process flow of the Manufacturing/Provisioning of the device

			OEM team, to verify the enabling/disabling of all the ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware based debuggers and access control mechanisms in case the interface is enabled. 4. Process audit of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning. [For instance, through Block connection diagram depicting pin connections between the host microcontroller and its interactions with various sub components/peripherals.]	
		1.2 Verify that cryptographic keys and certificates are unique to each individual device.	Identifying all the keys and certificates being used in the device eco-system and verification through: • Testing, in presence of OEM team • Code review • Process audit of the key-life cycle process	1. List of all keys and certificates being used in the device ecosystem 2. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation)
		1.3 Verify that on-chip debugging interfaces such as JTAG or SWD are disabled or that available protection mechanism is enabled and configured appropriately.	1. Identification of the availability of debugging interfaces such as USB, UART, and other serial variants through the Datasheet of the SoC being used in the device under test 2. Verification and validation of the ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same as declared in the vendor documentation 3. Testing, in presence of OEM team, to verify the enabling/disabling of all the	1. Datasheet of the SoC being used in the device. 2. Documentation related to ports/interfaces enabled in the production devices and the related access control mechanism for protection of the same. 3. Process flow of the Manufacturing/Provisioning of the device

			ports and debugging interfaces such as USB, UART, and other serial variants using their relevant hardware based debuggers and access control mechanisms in case the interface is enabled. 4. Process audit of the manufacturing facility to validate the vendor's claim regarding the debugging interfaces which are closed/disabled during provisioning. [For instance, through Block connection diagram depicting pin connections between the host microcontroller and its interactions with various sub components/peripherals.]	
		1.4 Verify that trusted execution is implemented and enabled, if available on the device SoC or CPU.	Identifying whether TEE/SE/TPM is available or not in the device through the SoC datasheet and technical documentation submitted by the vendor. Further assessment is done on the basis of scenarios as applicable to device as defined below: **CASE 1: TEE/SE/TPM is not available:** No further assessment **CASE 2: TEE/SE/TPM is available and enabled:** Verification through code-review that crypto functions are called through TEE/SE/TPM APIs. **CASE 3: TEE/SE/TPM is available but not enabled by the vendor:** Termed as non-conformance to the requirement. OEM is required to enable and implement the TEE/SE/TPM.	1. Datasheet of the SoC being used in the device. 2. User manual/ Technical specifications of the device 3. Code snippets of the TEE API call, wherever applicable
		1.5 Verify that sensitive data, private keys and certificates are stored securely in a Secure Element, TPM,	Identifying all the keys and certificates being used in the device eco-system, sensitive data and their storage mechanism(s); and verification through:	1. List of all keys and certificates being used in the device ecosystem 2. List of all the sensitive data with their intended usage and secure storage

		TEE (Trusted Execution Environment), or protected using strong cryptography.	• Testing, in presence of OEM team • Code review • Process audit of the key-life cycle process	mechanism(s) as implemented along with secure configurations to be enabled in the device. 3. Key management life cycle (purpose, generation, storage, destruction/zeroization, validity, key changeover/rotation) private keys and certificates.
		1.6Verify the presence of tamper resistance and/or tamper detection features.	Testing, in presence of OEM team, to verify the measures implemented in the device to prevent software and hardware tampering.	1. Measures available in the device to prevent software tampering. 2. Measures available in the device to prevent hardware tampering.
		1.7 Verify that any available Intellectual Property protection technologies provided by the chip manufacturer are enabled.	Testing, in presence of OEM team, to verify the enabling of the Intellectual Property protection technologies provided by the chip manufacturer, if available.	1. Datasheet of the SoC 2. Documentation regarding the Intellectual Property protection technologies provided by the chip manufacturer which have been enabled. 3. In case, no Intellectual Property protection technologies are being provided by the chip manufacturer, then a declaration stating the same.
		1.8 Verify the device validates the boot image signature before loading.	Testing, in presence of OEM team, to verify the following: 1. Device boots up successfully with the documented secure boot process when a valid boot image is provided. 2. Device does not boot up when a tampered boot image (like with missing signature, invalid signature) is provided.	1. Datasheet of the SoC 2.Technical specifications of the device regarding secure boot (should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented.)
		1.9 Verify usage of cryptographically secure pseudo-random number generator on embedded device (e.g., using chip-provided random number	Verification of the documentation provided by the vendor regarding the random number generators being used in the device. Verification through code-review that random number generators or related	Documentation regarding the random generators (either hardware based or software based or both) being used in the device with their intended usage. In case, hardware based random number generators are being used, vendors

		generators).	libraries as applicable are being used in the device.	shall submit the following: 1. Datasheet of the SoC 2. Technical specifications of the device regarding random generators In case, software based random number generators are being used, vendors shall provide the libraries being used for the same.
2)	Software/Firmware	2.1 Verify that memory protection controls such as ASLR and DEP are enabled by the embedded/IoT operating system, if applicable.	Testing, in presence of OEM team, to verify the declared memory protection controls available and enabled in the device using command line-based tools/commands or any other open-source tool like DEP, EMET tool.	Declaration of the memory protection controls available and enabled in the device.
		2.2 Verify that the firmware apps protect data-in-transit using transport layer security.	1. Verifying that strong encryption algorithms and secure TLS version is supported by the device to establish secure communication. 2. Verifying that device properly validates the server's TLS certificate to ensure that it is trusted and has not been tampered with. 3. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites. 4. Using tools such as Nmap to identify open ports through which device can be accessed leading to unintended data retrieval. 5. Verifying that theTLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite.	Specifications and documentation related to the configurations available in the applications and firmware related to transport layer security.
		2.3 Verify that the firmware apps validate the digital signature of server connections.	1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following: • Security features, related to secure server connections and digital	Document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the

			signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough. • Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device. 2. Testing for vulnerabilities which can affect the security of TLS connection such as padding oracle attacks, or weak cipher suites. 3. Using tools such as Nmap to identify open ports through which device can be accessed leading to unintended data retrieval. 4. Verifying that TLS session(s) are resistant to attemptsof interception and decryption of network traffic using man-in-the-middle attacks using tools like Burpsuite.	server connections.
		2.4 Verify that any use of banned C functions are replaced with the appropriate safe equivalent functions.	Secure code review [both automated and manual], in presence of OEM team, using a licensed static analysis tool through any of the following approaches: 1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems. [Recommended] 2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency.	1. Firmware binaries for code review. 2. Internal code review reports

			3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them. 4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors.	
		2.5 Verify that each firmware maintains a software bill of materials cataloging third party components, versioning, and published vulnerabilities.	Verification of the submitted list of third-party components by running automated tools like FACT on the firmware. Identifying vulnerabilities in the third-party component(s) through publically available vulnerability databases Verification and validation of the process defined by the vendor for providing regular security updates and patches for the firmware to address any known vulnerabilities in third-party components.	1. Documentation for information on software bill of materials, including third-party components and versions. 2. Organization process and policies for the following: • Addressing and patching any identified vulnerabilities in third-party components. • Informing the customers about the security issues or vulnerabilities and providing security updates and patches for the same. 3. Configuration management system and related policies for maintaining firmware and third-party binaries, libraries and frameworks along with the patches/fixes issued to the devices.
		2.6 Verify all code including third-party binaries, libraries, frameworks are reviewed for hardcoded credentials (backdoors).	Independent secure code review [both automated and manual] using a licensed static analysis tool through any of the following approaches: 1. Visit to the evaluation agency by the vendor with the firmware code and installing the licensed static analysis tool available with the evaluation agency in their systems.	1. Firmware binaries for code review. 2. Internal code review reports

			[Recommended] 2. Visit to the evaluation agency by the vendor with the firmware code and any licensed static analysis tool available with them and demonstrating the code review activity in the presence of representatives of evaluation agency. 3. Giving a remote access of the systems at vendor site to the evaluation agency for installing their licensed static analysis tool available with them. 4. Giving a remote access of the systems at vendor site to the evaluation agency containing the firmware code along with the licensed static analysis tool available with the vendors.	
		2.7 Verify that the firmware apps pin the digital signature to a trusted server(s).	1. Identifying the scenarios when the device establishes the server connections with the external world and verifying the following: • Security features, related to secure server connections and digital signature validation as implemented like strong cipher suites, secure TLS version, SSL pinning etc. supported by code walkthrough. • Proper certificate validation, certificate chain validation and certificate revocation checks are implemented in the device.	Document mentioning the use-cases when the device establishes server connections with the external world, with detailed information about the security measures in place while validating the digital signatures of the server connections.
		2.8 Verify security controls are in place to hinder firmware reverse engineering (e.g.removal of verbose debugging symbols).	Testing, in presence of OEM team, to verify the security controls as provided by the vendor to hinder firmware reverse engineering.	Documentation regarding the security controls in place to hinder firmware reverse engineering.
		2.9 Verify that	Testing, in presence of	Measures implemented in

		the firmware update process is not vulnerable to time-of-check vs time-of-use attacks.	OEM team, to verify the measures implemented in the device to make it resistant to time-of-check vs.time-of-use attacks.	the device to make it resistant to time-of-check vs. time-of-use attacks.
		2.10 Verify the device uses code signing and validates firmware upgrade files before installing.	Testing, in presence of OEM team, to verify the following: i) Device gets successfully updated with the documented secure upgrade process when a valid update package is provided. ii) Device does not boot up when a tampered update package (like with missing signature, invalid signature) is provided.	Process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented.
		2.11 Verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware.	Testing, in presence of OEM team, to verify that the device cannot be downgraded to old versions (anti-rollback) of valid firmware.	Process of achieving secure firmware upgrade which should consist of keys involved and their management life cycle*, signature validation process and any other secure mechanisms if implemented.
		2.12 Verify that firmware can perform automatic firmware updates upon a predefined schedule.	Verification shall be done as per the applicable scenario: **Case 1: Automatic OTA updates are available:** A standard operating procedure for issuing automatic updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the evaluation agency as per C20, C21 and C22 security requirement. **Case 2: Automatic OTA updates are not available and vendor provides manual updates:** A standard operating procedure for issuing manual updates/upgrades to the in-field devices is required to be submitted by the vendor which can then be evaluated by the	1. Modes of updates available i.e. automatic, manual or both. 2. Organizational process and policies regarding the issuing of updates to the devices.

			evaluation agency as per C20, C21 and C22 security requirement.	
3)	Secure Process Conformance	3.1 Verify that wireless communications are mutually authenticated.	Testing, in presence of OEM team, to verify the process of mutual authentication as laid down in the documentation by the vendor.	The documentation regarding the process of mutual authentication as implemented in the device when wireless communications are initiated. In case, the device does not support wireless communications, the vendor shall provide a declaration for the same.
		3.2 Verify that wireless communications are sent over an encrypted channel.	Identifying all the security mechanisms being used in the communication process verification through: • Testing, in presence of OEM team • Code review • Process audit of the key-life cycle process	Documentation regarding the security measures implemented in the device to prevent tampering of the data being sent through wireless mode of communication. In case, the device does not support wireless communications, the vendor shall provide a declaration for the same.
		3.3 Verify that whether trusted sources are being used for sourcing the components of the device i.e. trusted supply chain through a managed Bill of materials for critical hardware components (related to security functions like SoC) is in use.		Bill of materials for critical hardware components (related to security functions like SoC).
		3.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted. Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption,		Supply chain risk identification, assessment, prioritization, and mitigation documents. Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents.

		post-incident summary documents need to be submitted and demonstrate the same.		
		3.5 Verify the no proprietary network protocols are being used in the device. If yes, then complete implementation details and the source code for the same shall be provided.		Document for Network protocols used in the device.
4)	Security Conformance at product development stage	4.1 Design and architecture details till the PCBA and SoC level to be provided to aid in counterfeit mitigation and malware detection.		Design and architecture documents till the PCBA and SoC level.
		4.2 Threat mitigation strategies for tainted and counterfeit products shall be implemented as part of product development.	Process and method artifacts need to be submitted and demonstrate the same.	
		4.3 One or more up-to-date malware detection tools shall be deployed as part of the code acceptance and development processes. Malware detection techniques shall be used before final packaging and delivery (e.g., scanning finished products and components for malware using one or more up-to-date	List of components that have been identified as requiring tracking targets of tainting/counterfeiting, CM tool. Quality assurance process need to be submitted and demonstrate the same.	

		malware detection tools).		
		4.4 Supply chain risk identification, assessment, prioritization, and mitigation shall be conducted.		Supply chain risk/business continuity planning policy documents, playbooks reflecting how to handle supply chain disruption, post-incident summary documents need to be submitted and demonstrate the same.

Uploaded by Dte. of Printing at Government of India Press, Ring Road, Mayapuri, New Delhi-110064
and Published by the Controller of Publications, Delhi-110054.

रजिस्ट्री सं. डी.एल.- 33004/99 REGD. No. D. L.-33004/99

भारत का राजपत्र
The Gazette of India

सी.जी.-डी.एल.-अ.-09042024-253632
CG-DL-E-09042024-253632

असाधारण
EXTRAORDINARY

भाग II—खण्ड 3—उप-खण्ड (ii)
PART II—Section 3—Sub-section (ii)

प्राधिकार से प्रकाशित
PUBLISHED BY AUTHORITY

सं. 1569] नई दिल्ली, मंगलवार, अप्रैल 9, 2024/चैत्र 20, 1946
No. 1569] NEW DELHI, TUESDAY, APRIL 9, 2024/CHAITRA 20, 1946

इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी मंत्रालय

(आईपीएचडब्ल्यू प्रभाग)

आदेश

नई दिल्ली, 9 अप्रैल, 2024

विषय: "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल में संशोधन" (अनिवार्य पंजीकरण की आवश्यकता) आदेश, 2021"

का.आ. 1652(अ).—भारतीय मानक ब्यूरो अधिनियम, 2016, (2016 का 11) की धारा 25 की उपधारा (3) के साथ पठित धारा 16 की उप-धारा (1) और (2) द्वारा प्रदत्त शक्तियों का प्रयोग करते हुए, केंद्र सरकार का यह मत है कि सार्वजनिक हित में ऐसा करना आवश्यक या समीचीन है, इसके द्वारा "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021" में निम्नलिखित संशोधन किए जाते हैं:

2. सी.सी.टी.वी. कैमरे हेतु, कॉलम (5) की निम्नलिखित प्रविष्टि को "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021 की अनुसूची में क्रम संख्या 41 पर जोड़ा जाएगा।

क्रमांक (1)	माल या सामान (2)	भारतीय मानक (3)	भारतीय मानक का शीर्षक (4)	अपेक्षित आवश्यकता (आवश्यकताएँ) (5)
41	सीसीटीवी कैमरा	आईएस 13252 : भाग 1 : 2010	सूचना तकनीकी उपकरण - सुरक्षा सामान्य आवश्यकताएं--	अनुलग्नक के अनुसार सीसीटीवी हेतु अनिवार्य आवश्यकता (आवश्यकताएँ)

3. "इलेक्ट्रॉनिकी और सूचना प्रौद्योगिकी माल (अनिवार्य पंजीकरण के लिए आवश्यकताएं) आदेश, 2021" के प्रावधान इस अधिसूचना के आधार पर उक्त आदेश की अनुसूची में जोड़े गए कॉलम (2) में निर्दिष्ट माल या सामान पर आधिकारिक राजपत्र में इस अधिसूचना के प्रकाशन की तारीख से छह महीने की समाप्ति पर, कॉलम (5) में निर्दिष्ट किए गए संबंधित अपेक्षित आवश्यकताओं के अनुरूप लागू होंगे। बीआईएस अनुरूपता मूल्यांकन विनियम, 2018 की योजना II के अनुसार बीआईएस मान्यता प्राप्त प्रयोगशालाओं से परीक्षण रिपोर्ट जमा करना मानक चिन्ह का उपयोग करने के लिए लाइसेंस प्राप्त करने हेतु एक पूर्व-आवश्यकता होगी।

[फा.सं. डब्ल्यू-43/11/2021-आईपीएचडब्ल्यू]
आशा नांगिया, समूह समन्वयक और वैज्ञानिक 'जी'

अनुलग्नक

सीसीटीवी की सुरक्षा के लिए अनिवार्य आवश्यकता

संवेदनशील जानकारी की सुरक्षा और सिस्टम को प्रभावी ढंग से संचालित करने के लिए सीसीटीवी (क्लोज-सर्किट टेलीविजन) प्रणाली को सुरक्षित करना महत्वपूर्ण है। परीक्षण के प्रमुख क्षेत्रों में एक्स्पोस्ड नेटवर्क सेवाएं, डिवाइस संचार प्रोटोकॉल, डिवाइस के यूएआरटी,जेटीएजी,एसडब्ल्युडी आदि तक भौतिक पहुंच, मेमोरी और फर्मवेयर निकालने की क्षमता, फर्मवेयर अपडेट प्रक्रिया सुरक्षा और डेटा का भंडारण और एन्क्रिप्शन शामिल हैं। सीसीटीवी सिस्टम की सुरक्षा के लिए यहां संक्षिप्त आवश्यकताएं दी गई हैं:

1. भौतिक सुरक्षा - भौतिक छेड़छाड़ को रोकने के लिए छेड़छाड़-प्रतिरोधी कैमरा एन्क्लोज़र और लॉकिंग तंत्र का उपयोग करें।
2. प्रमाणीकरण द्वारा अभिगम नियंत्रण, भूमिका-आधारित अभिगम नियंत्रण (आरबीएसी) और कर्मियों के परिवर्तनों को प्रतिबिंबित करने के लिए अभिगम अनुमतियों की नियमित रूप से समीक्षा और अद्यतनीकरण ।
3. डेटा ट्रांसमिशन के एन्क्रिप्शन को नियोजित करके नेटवर्क सुरक्षा
4. नियमित अपडेट द्वारा सॉफ़्टवेयर सुरक्षा, अप्रयुक्त सुविधाओं को अक्षम करना और सुदृढ़ पासवर्ड नीतियाँ
5. पेनीट्रेशन परीक्षण: साइबर हमलों के लिए सिस्टम के प्रतिरोध का आकलन करने और कमजोरियों को दूर करने के लिए पेनीट्रेशन परीक्षण को नियोजित करें।

अनिवार्य सुरक्षा आवश्यकताएँ

क्रमांक	वर्ग	परीक्षण पैरामीटर	क्या परीक्षण किया जाए	अपेक्षित दस्तावेज़
	हार्डवेयर स्तर सुरक्षा पैरामीटर (सॉफ़्टवेयर द्वारा समर्थित)	1.1 एक जटिल पासवर्ड द्वारा यह सत्यापित करें कि एप्लिकेशन लेयर डिबगिंग इंटरफ़ेस जैसे यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट अक्षम या संरक्षित हैं।	1. परीक्षण के तहत डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट के माध्यम से यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस की उपलब्धता की पहचान करना 2. विक्रेता दस्तावेज़ीकरण में घोषित की गई सुरक्षा के लिए उत्पादन उपकरणों और संबंधित पहुंच नियंत्रण तंत्र में सक्षम पोर्ट/इंटरफ़ेस का सत्यापन और वेधता हार्डवेयर आधारित डिबगर्स और एक्सेस कंट्रोल तंत्र का उपयोग करके सभी पोर्ट और यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस को सक्षम/अक्षम करने को सत्यापित करने के लिए ओईएम	विक्रेता द्वारा निम्नलिखित को उपलब्ध करना होगा: 1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट। 2. उत्पादन उपकरणों में सक्षम पोर्ट/इंटरफ़ेस से संबंधित दस्तावेज़ीकरण और उसकी सुरक्षा के लिए संबंधित एक्सेस नियंत्रण तंत्र। 3. डिवाइस के विनिर्माण/प्रावधान की प्रक्रिया प्रवाह

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			टीम की उपस्थिति में परीक्षण। 4. डिबगिंग इंटरफेस के बारे में विक्रेता के दावे को मान्य करने के लिए विनिर्माण सुविधा की प्रक्रिया लेखा परीक्षा जो प्रावधान के दौरान बंद/अक्षम हैं। [उदाहरण के लिए, ब्लॉक कनेक्शन आरेख के माध्यम से होस्ट माइक्रोकंट्रोलर के बीच पिन कनेक्शन और विभिन्न उप घटकों/परिधीय के साथ इसकी बातचीत को दर्शाया गया है।]	
		1.2 सत्यापित करें कि क्रिप्टोग्राफ़िक कुंजी और प्रमाणपत्र प्रत्येक व्यक्तिगत डिवाइस के लिए अद्वितीय हैं।	डिवाइस इको-सिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की पहचान करना और इनके माध्यम से सत्यापन करना: ओईएम टीम की उपस्थिति में परीक्षण कोड समीक्षा कुंजी-जीवन चक्र प्रक्रिया संबंधी प्रक्रिया लेखा परीक्षा	विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा: 1. डिवाइस इकोसिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की सूची 2. मुख्य प्रबंधन जीवन चक्र (उद्देश्य, उत्पादन, भंडारण, विनाश/शून्यीकरण, वैधता, कुंजी परिवर्तन/रोटेशन)
		1.3 सत्यापित करें कि जेटीएजी या एसडबल्यूडी जैसे ऑन-चिप डिबगिंग इंटरफ़ेस अक्षम हैं या उपलब्ध सुरक्षा तंत्र सक्षम और उचित रूप से कॉन्फ़िगर किया गया है।	1. परीक्षण के तहत डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट के माध्यम से यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस की उपलब्धता की पहचान करना 2. विक्रेता दस्तावेज़ में घोषित की गई सुरक्षा के लिए उत्पादन उपकरणों और संबंधित पहुंच नियंत्रण तंत्र में सक्षम पोर्ट/इंटरफ़ेस का सत्यापन और वेधता 3. इंटरफ़ेस सक्षम होने की स्थिति में उनके प्रासंगिक हार्डवेयर आधारित डिबगर्स और एक्सेस कंट्रोल तंत्र का उपयोग करके सभी पोर्ट और यूएसबी, यूएआरटी और अन्य सीरियल वेरिएंट जैसे डिबगिंग इंटरफेस को सक्षम/अक्षम करने को सत्यापित करने के लिए ओईएम टीम की उपस्थिति में परीक्षण। 4. डिबगिंग इंटरफेस के बारे में विक्रेता के दावे को मान्य करने के लिए विनिर्माण सुविधा की प्रक्रिया लेखा परीक्षा जो प्रावधान	विक्रेता द्वारा निम्नलिखित को उपलब्ध करना होगा: 1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट। 2. उत्पादन उपकरणों में सक्षम पोर्ट/इंटरफ़ेस से संबंधित दस्तावेज़ीकरण और उसकी सुरक्षा के लिए संबंधित एक्सेस नियंत्रण तंत्र। 3. डिवाइस के विनिर्माण/प्रावधान की प्रक्रिया प्रवाह

			के दौरान बंद/अक्षम हैं। [उदाहरण के लिए, ब्लॉक कनेक्शन आरेख के माध्यम से होस्ट माइक्रोकंट्रोलर के बीच पिन कनेक्शन और विभिन्न उप घटकों/परिधीय के साथ इसकी बातचीत को दर्शाया गया है।]	
		1.4 सत्यापित करें कि विश्वसनीय निष्पादन लागू और सक्षम है, यदि डिवाइस एसओसी या सीपीयू पर उपलब्ध है।	विक्रेता द्वारा प्रस्तुत एसओसी डेटाशीट और तकनीकी दस्तावेज के माध्यम से डिवाइस में टीईई/एसई/टीपीएम उपलब्ध है या नहीं, इसकी पहचान करना। आगे का मूल्यांकन डिवाइस पर लागू परिदृश्यों के आधार पर किया जाता है जैसा कि नीचे परिभाषित किया गया है: **स्थिति 1: टीईई/एसई/टीपीएम उपलब्ध नहीं है:** कोई और अग्रिम मूल्यांकन नहीं **स्थिति 2: टीईई/एसई/टीपीएम उपलब्ध और सक्षम है:** कोड-समीक्षा के माध्यम से सत्यापन कि क्रिप्टो फ़ंक्शन को टीईई/एसई/टीपीएम एपीआई के माध्यम से बुलाया जाता है। **स्थिति 3: टीईई/एसई/टीपीएम उपलब्ध है लेकिन विक्रेता द्वारा सक्षम नहीं किया गया है:** आवश्यकता के अनुरूप न होने के रूप में करार दिया गया। टीईई/एसई/टीपीएम को सक्षम और कार्यान्वित करने के लिए ओईएम की आवश्यकता होती है।	विक्रेता द्वारा निम्नलिखित को उपलब्ध कराना होगा: 1. डिवाइस में उपयोग किए जा रहे एसओसी की डेटाशीट। 2. डिवाइस का उपयोगकर्ता मैनुअल/तकनीकी विनिर्देश 3. टीईई एपीआई कॉल के कोड स्निपेट, जहां भी लागू हो
		1.5 सत्यापित करें कि संवेदनशील डेटा, निजी कुंजियाँ और प्रमाणपत्र एक सुरक्षित तत्व, टीपीएम, टीईई (विश्वसनीय निष्पादन पर्यावरण) में सुरक्षित रूप से संग्रहीत हैं, या सुदृढ़ क्रिप्टोग्राफी का उपयोग करके संरक्षित हैं।	डिवाइस इको-सिस्टम, संवेदनशील डेटा और उनके भंडारण तंत्र में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की पहचान करना; और इसके माध्यम से सत्यापन करना : • ओईएम टीम की उपस्थिति में परीक्षण • कोड समीक्षा • कुंजी-जीवन चक्र प्रक्रिया संबंधी प्रक्रिया लेखा परीक्षा	विक्रेता द्वारा निम्नलिखित को प्रस्तुत करना होगा: 1. डिवाइस इकोसिस्टम में उपयोग की जा रही सभी कुंजियों और प्रमाणपत्रों की सूची 2. डिवाइस में सक्षम किए जाने वाले सुरक्षित कॉन्फ़िगरेशन के साथ कार्यान्वित सभी संवेदनशील डेटा की उनके इच्छित उपयोग और सुरक्षित भंडारण तंत्र (ओं) के साथ सूची। 3. मुख्य प्रबंधन जीवन चक्र [illegible] भंडारण, विनाश(थ्रू [illegible]) निजी कुंजी

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